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22	PCH(3)_SYS PWR CONTR	52	Empty			
23	PCH(4)_CCI, HWID	53	mDP	MTE	Kel max	bottom side, 22mil
24	PCH(5)_PCIE,USB	54	Camera/Sensor Conn.	EE/SW debug		top side, 22mil
25	PCH(6)_CPU,GPIO,MISC	55	eDP connector	_TP Intel request	ed	don't care, 22mil
26	PCH(7)_POWER	56	3P3VA & Reset	100		ossible for Future Removal don't care, 22mil
27	SAM_1, K22	57	VCCEDRAM & VCCEOPIO	MTF hig pads		top side (as close to resistor as possible), 22mil
28	SAM_2, K22	58	PMIC 1	P_BF WITE big paus	1011 1 11, 03	bottom side, 31mil
29	SAM_3, K22	59	PMIC 2	TP_BF MTE big pads	for RF	top side, 31mil
30	INSTANT_ON	60	PMIC 3			(if RF connector at the bottom side of the board)

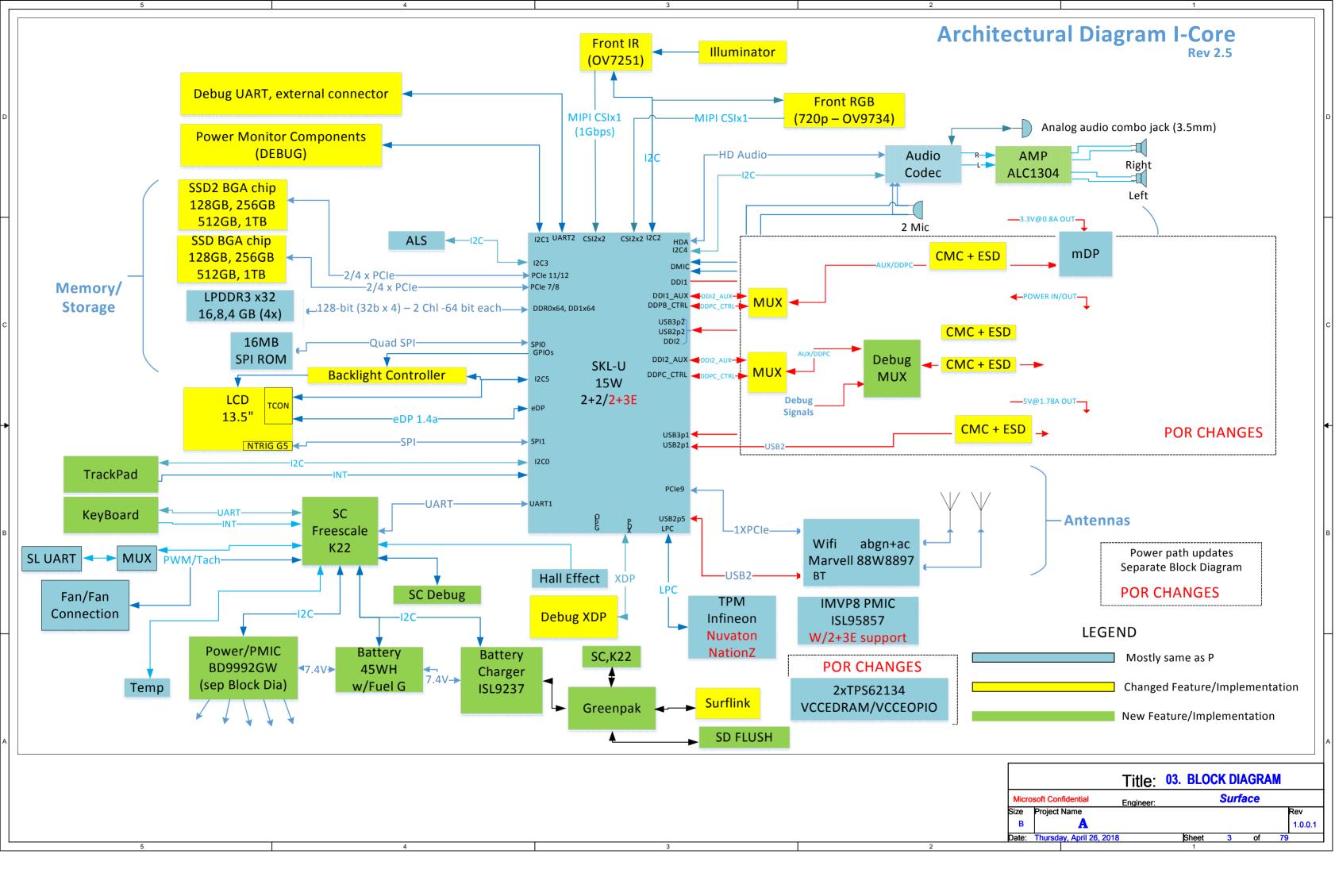
CAD Note:
Default component footprint is SMD 0201, X5R, 1% resistors.

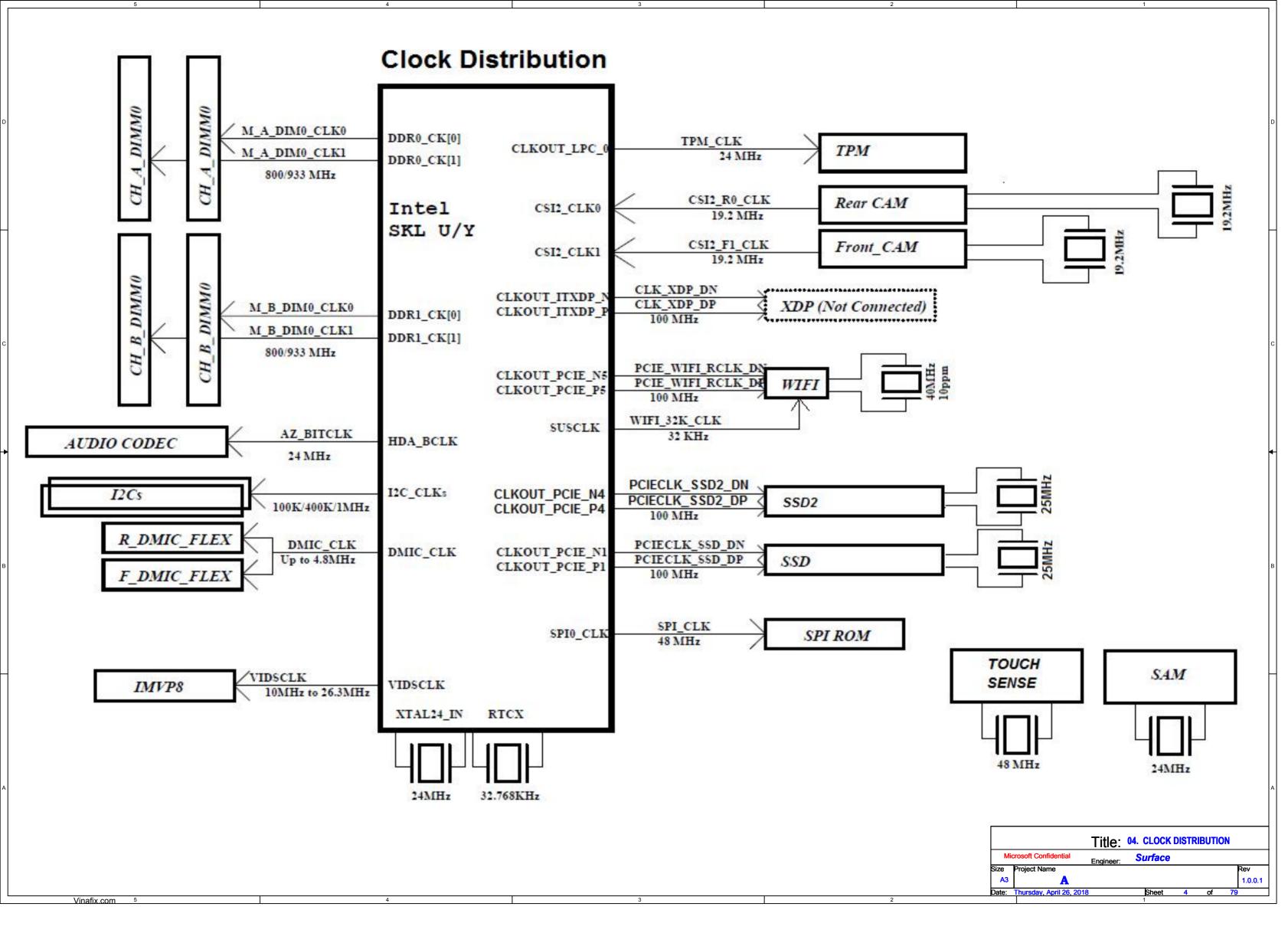
Property: BUILD-OPT DNP = Do Not Place

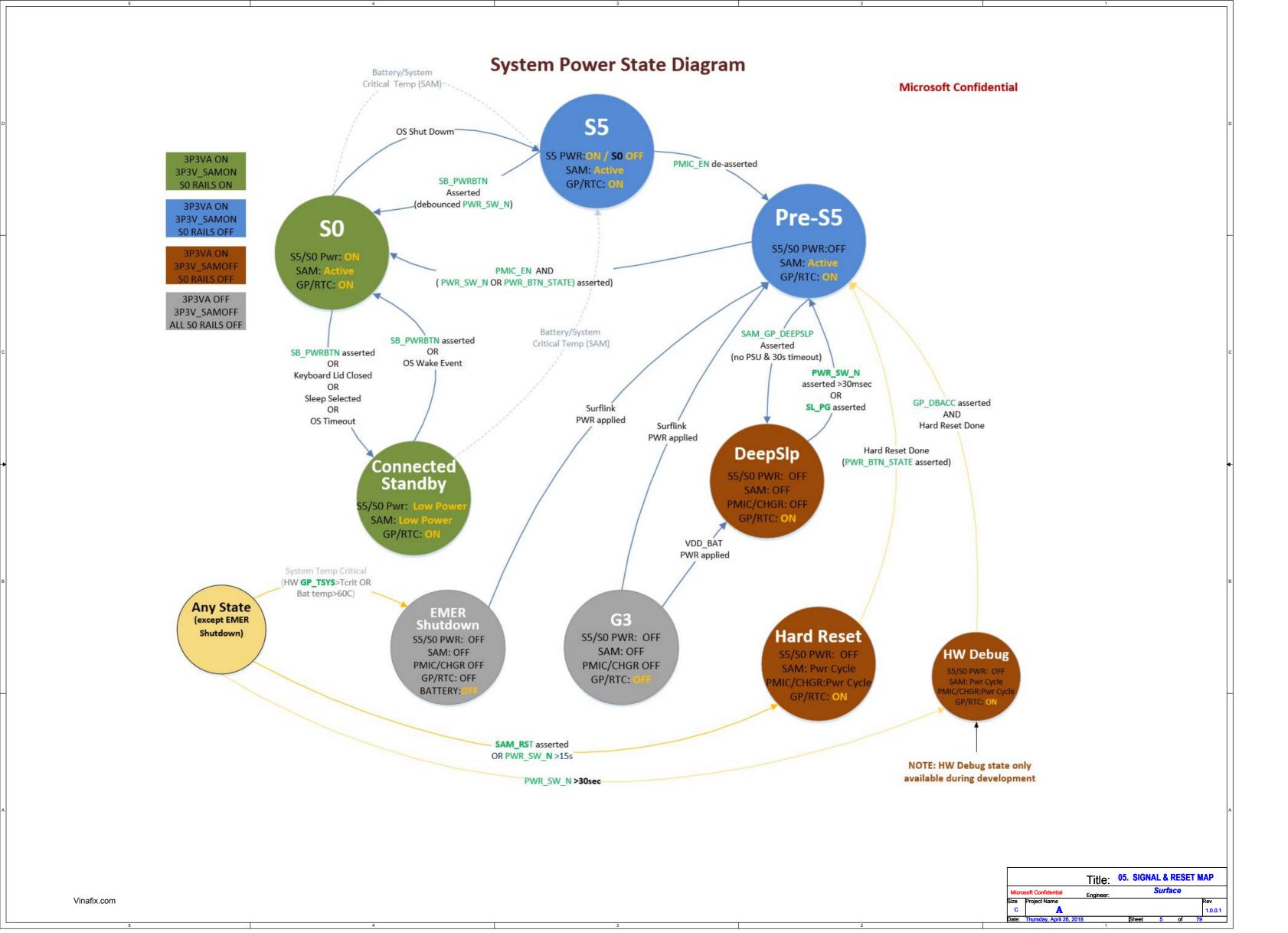
S or DB = Replace after Debug

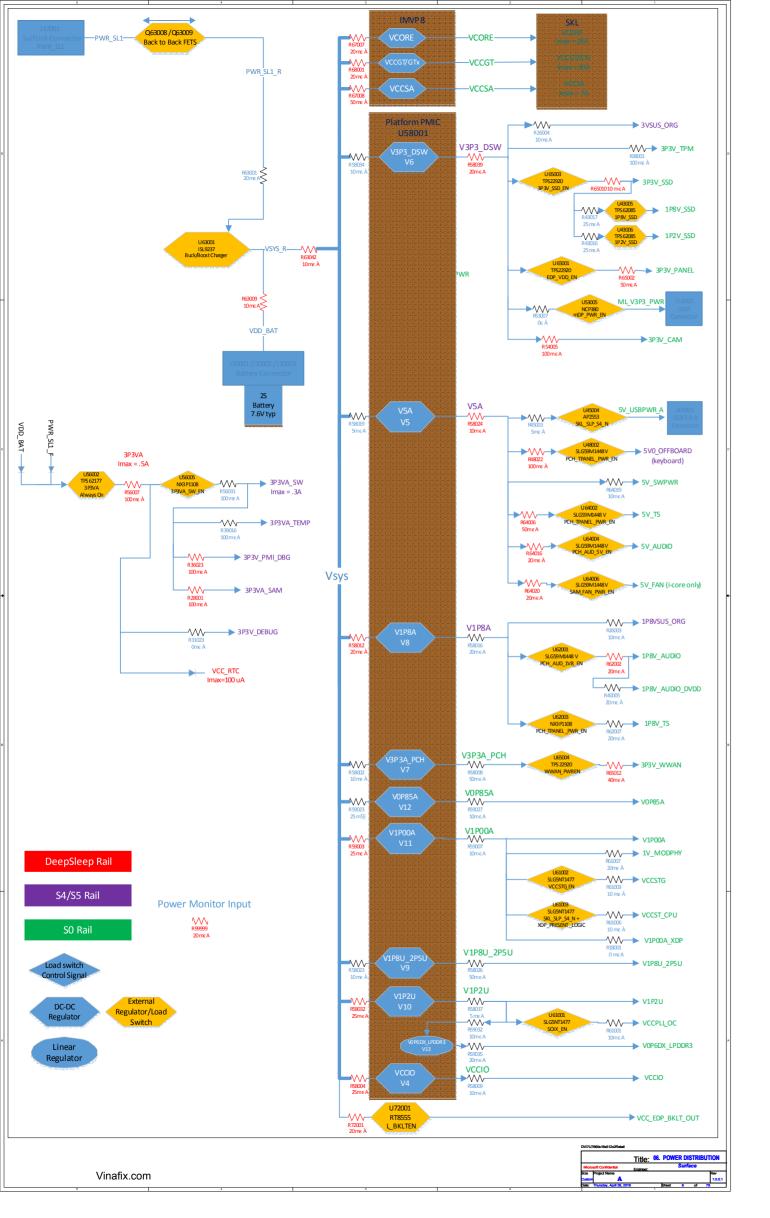
		l itle:	01. Table	ts			
Microsoft Confidential		Engineer:	Surface				
Size	Project Name	•				Rev	
A3	A					1.0.0.1	

Schematics Change History Schematics Change is maintained in spreadsheet, and would not fit on this page. S = Short after design fixed Default component footprint is SMD 0201, X5R, 1% resistors Title: 02. CHANGE HISTORY Property: BUILD-OPT DNP = Not Installed Part.

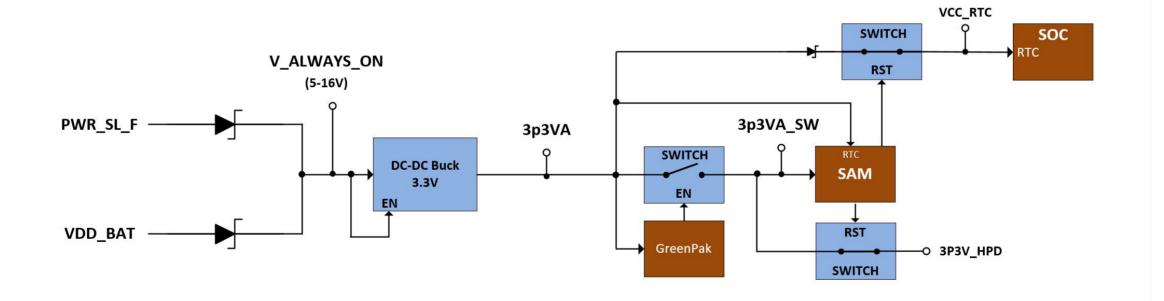


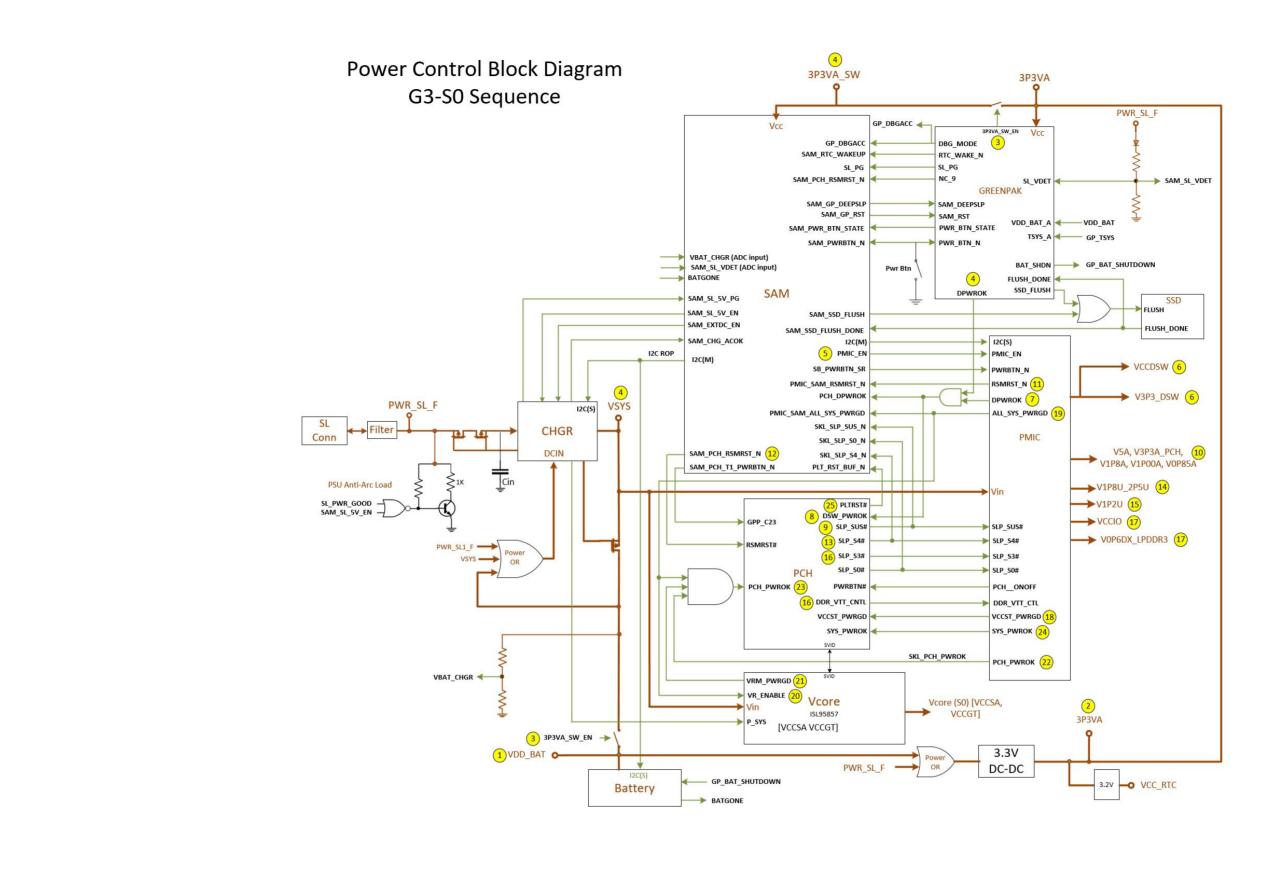




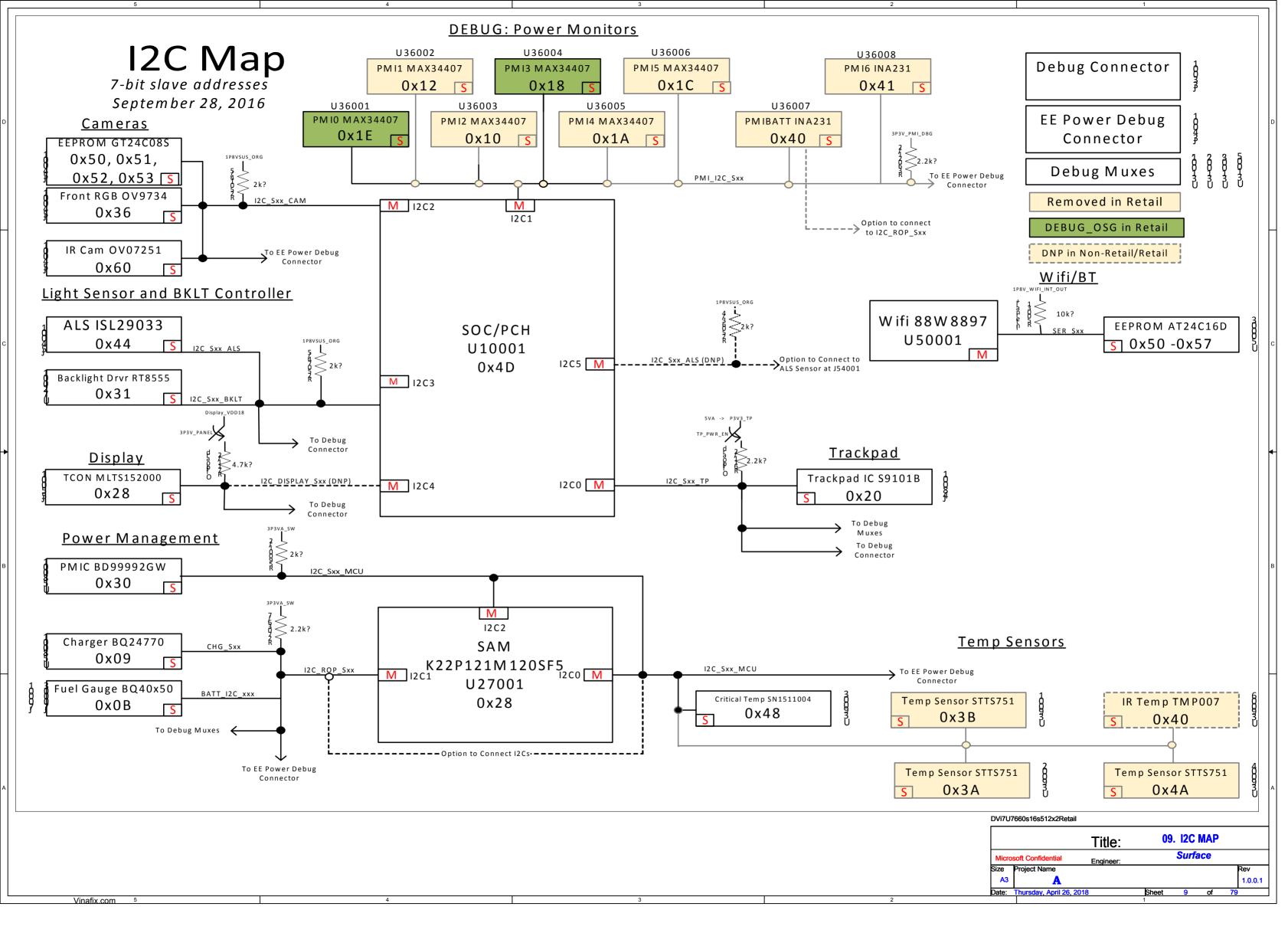


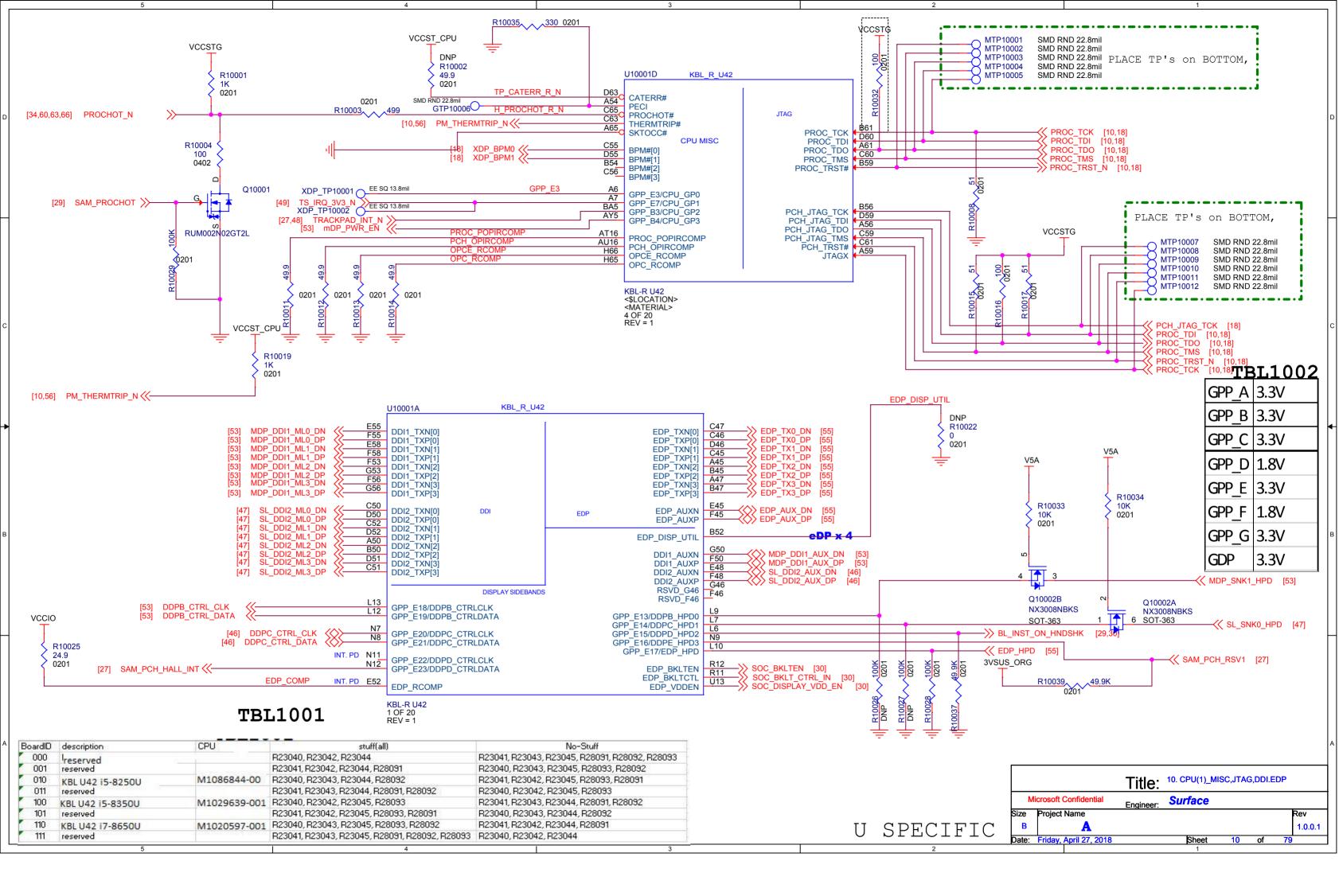
Lynx SL INPUT POWER DIAGRAM PWR_SL Vin=11-16V V_SYS PWR_SL1_F 4A max (6-8.7V) S5 Rais ACFET PMIC SL Filter FETs **ROP SO Rails** (Rest of Platform) BATFET BuckBoost **NVDC** Charger DEEPSLP FET VDD_BAT (6-8.7V) 2S2P Battery

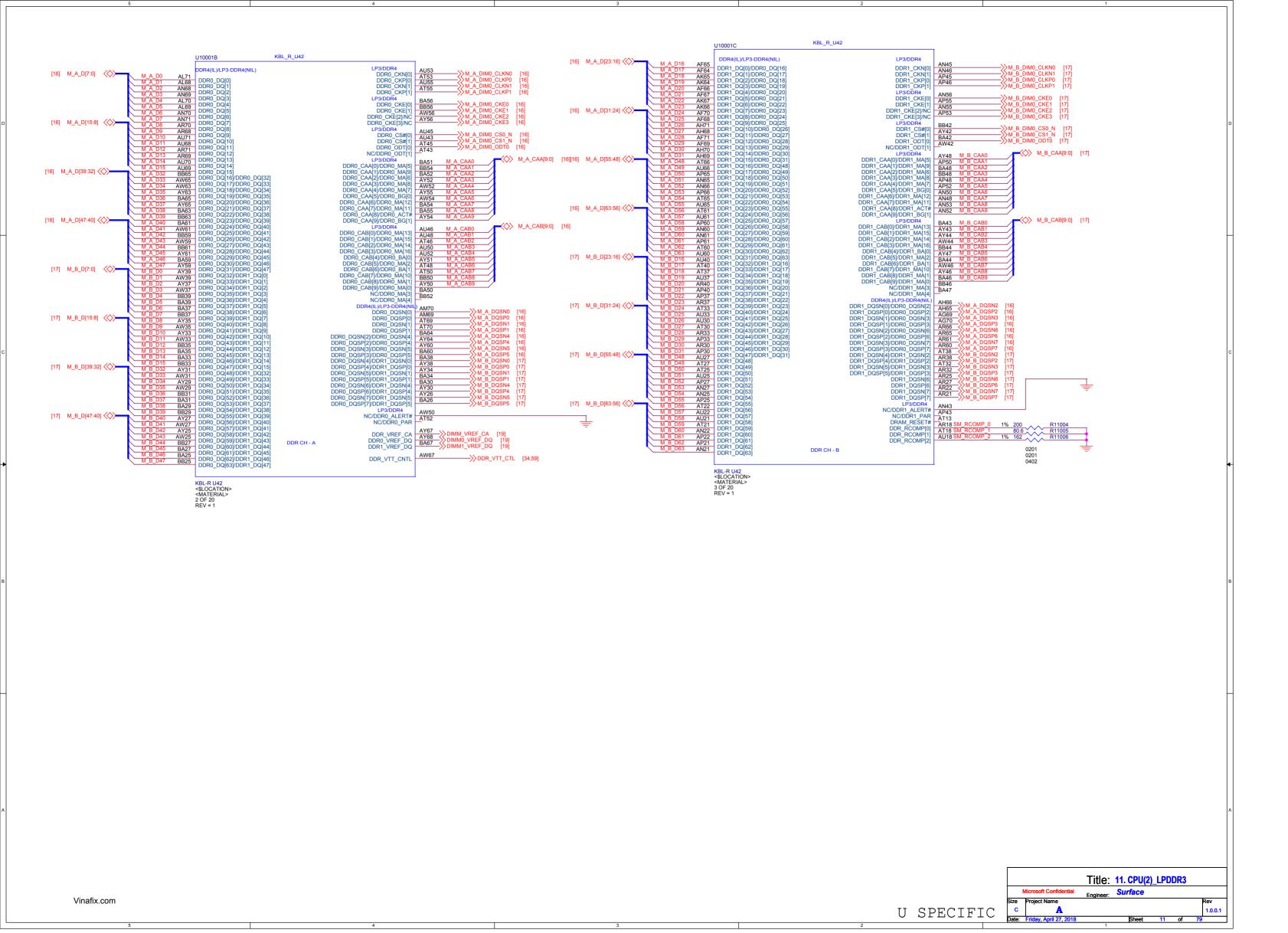


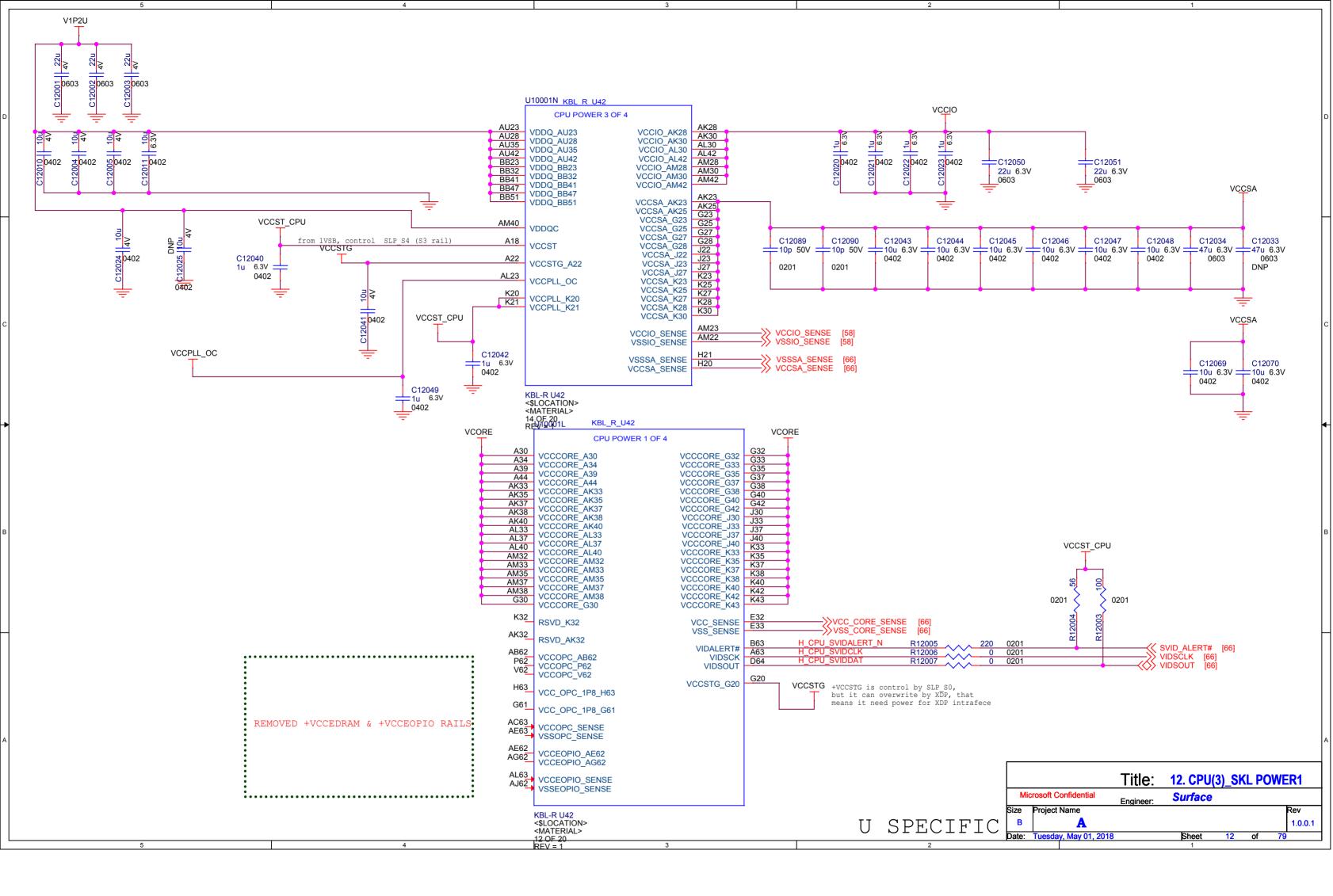


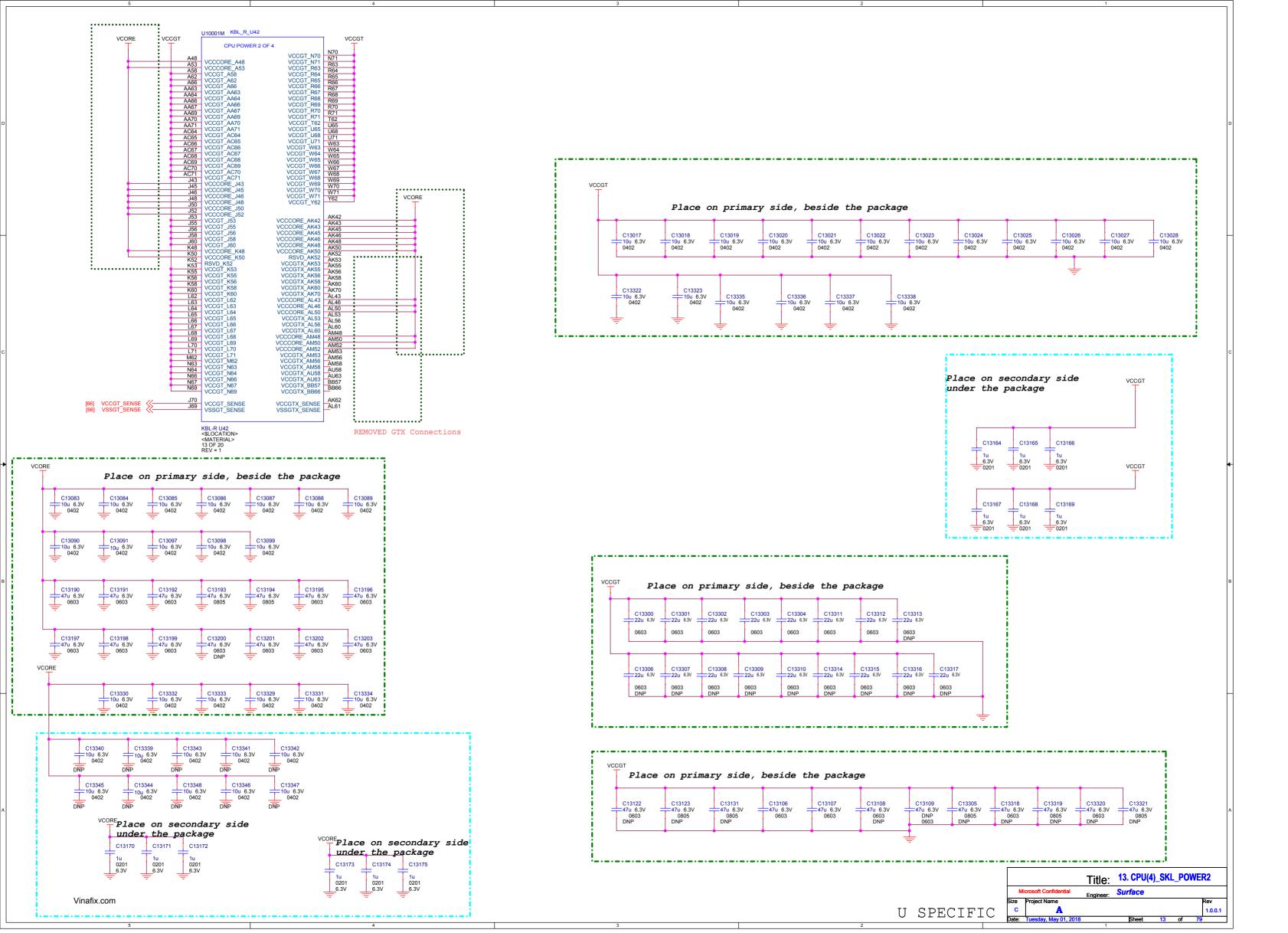


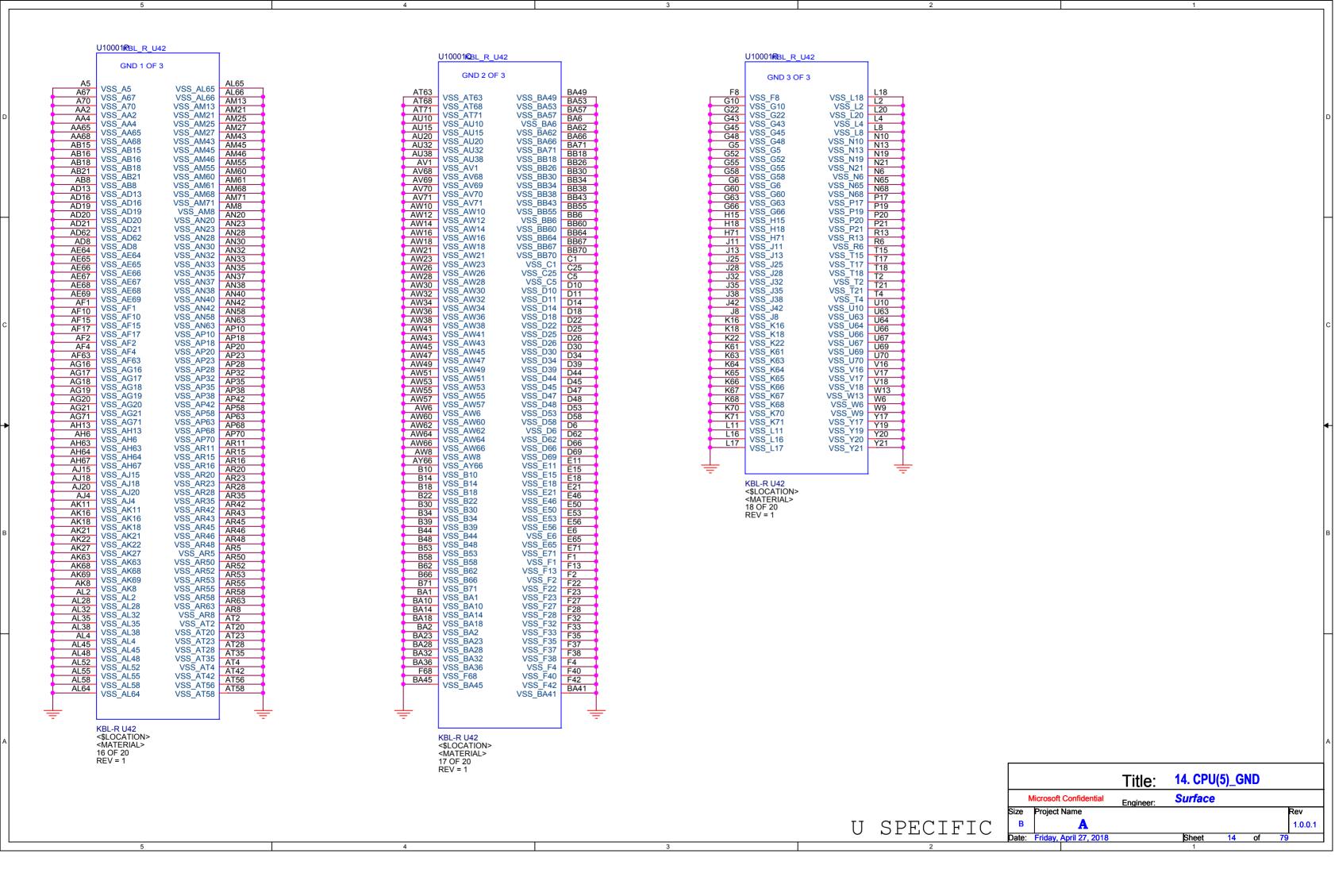


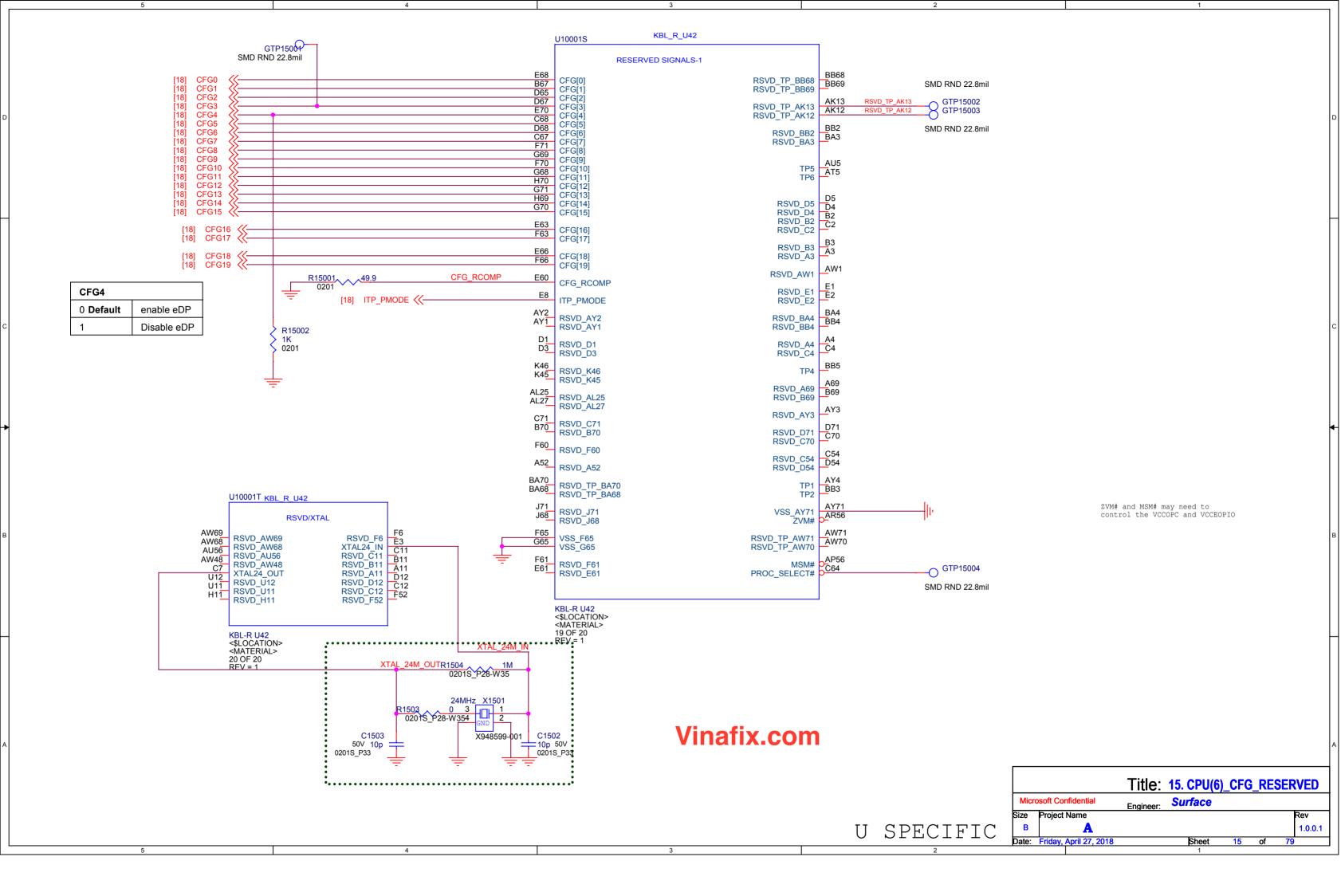


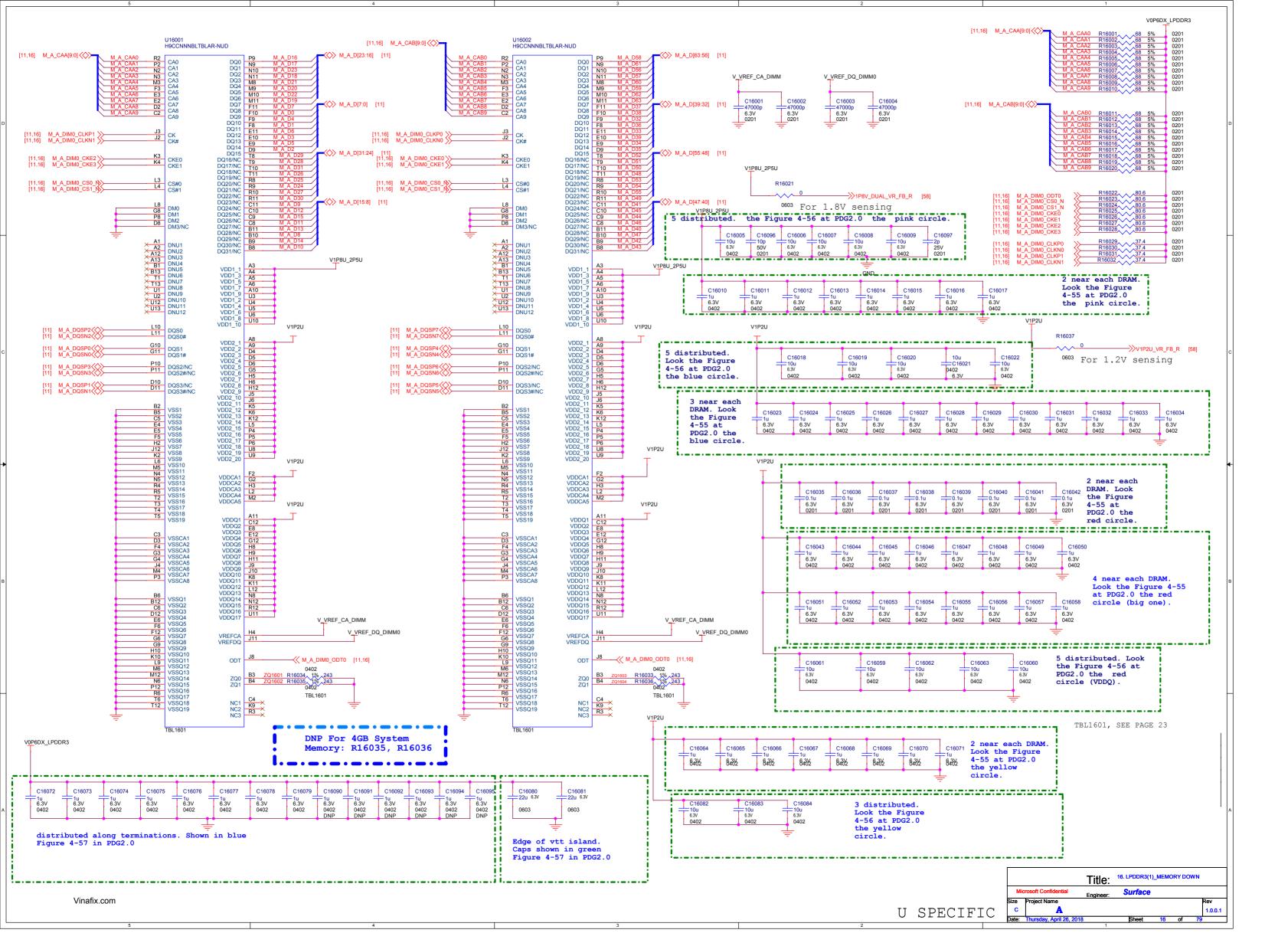


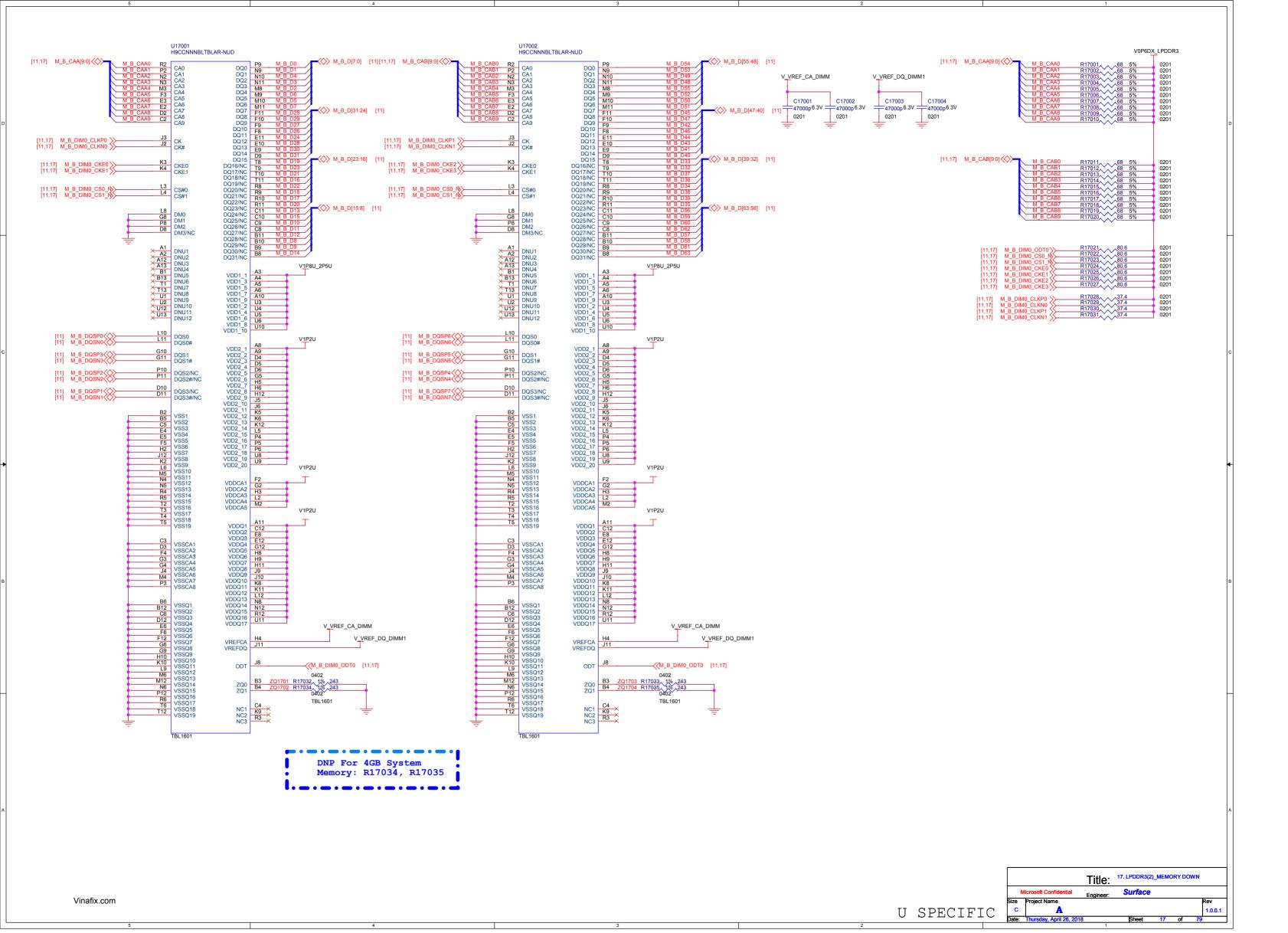


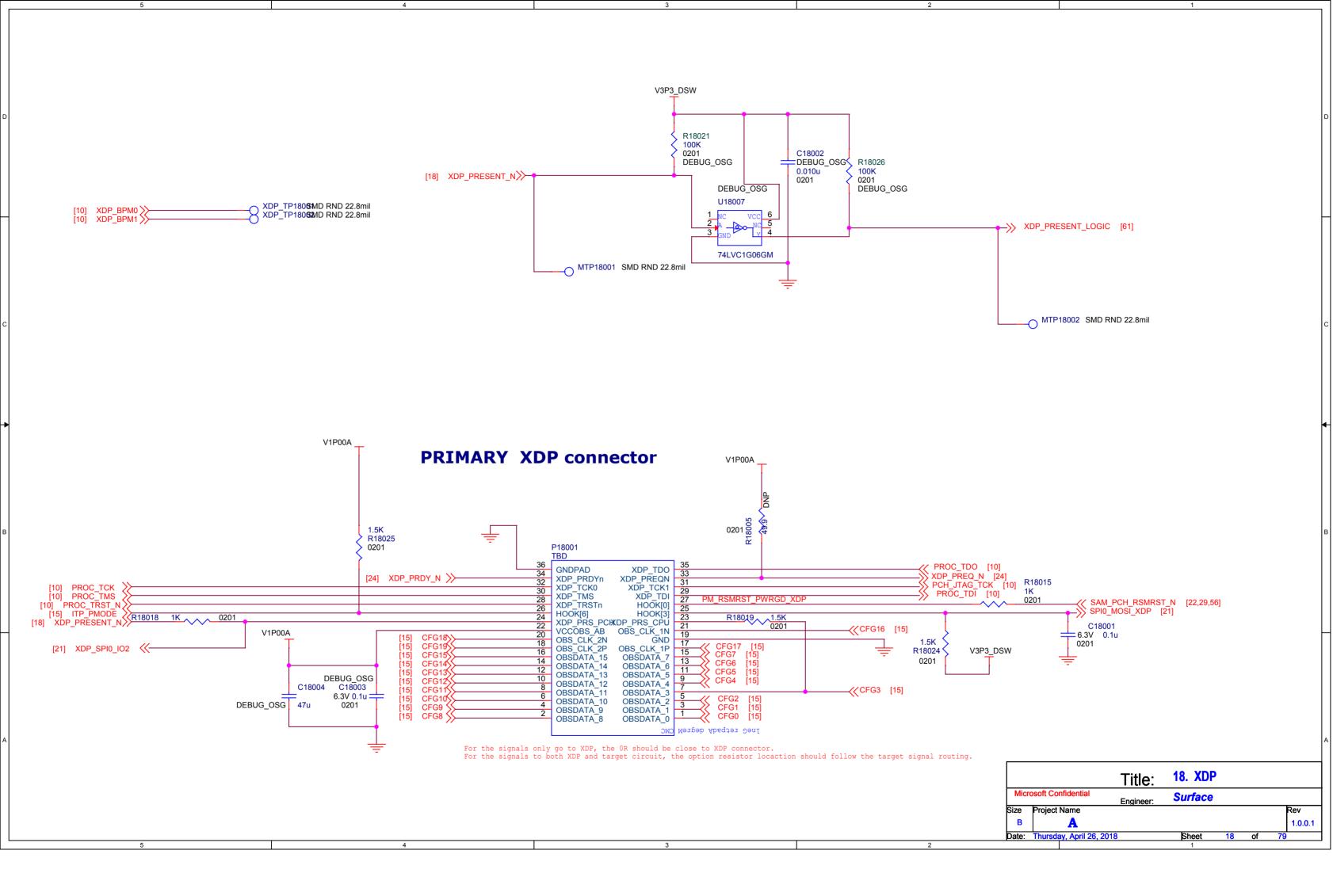


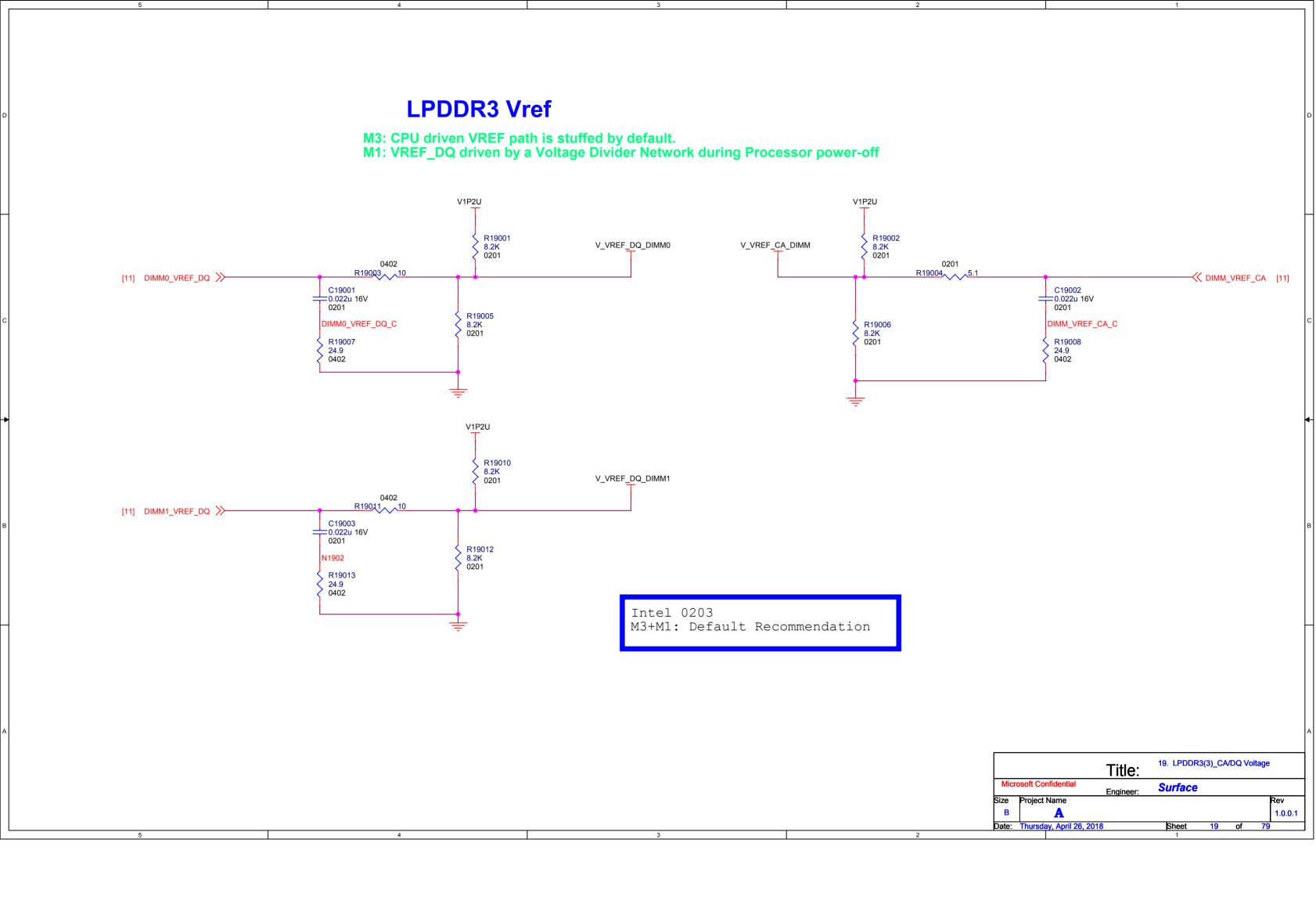


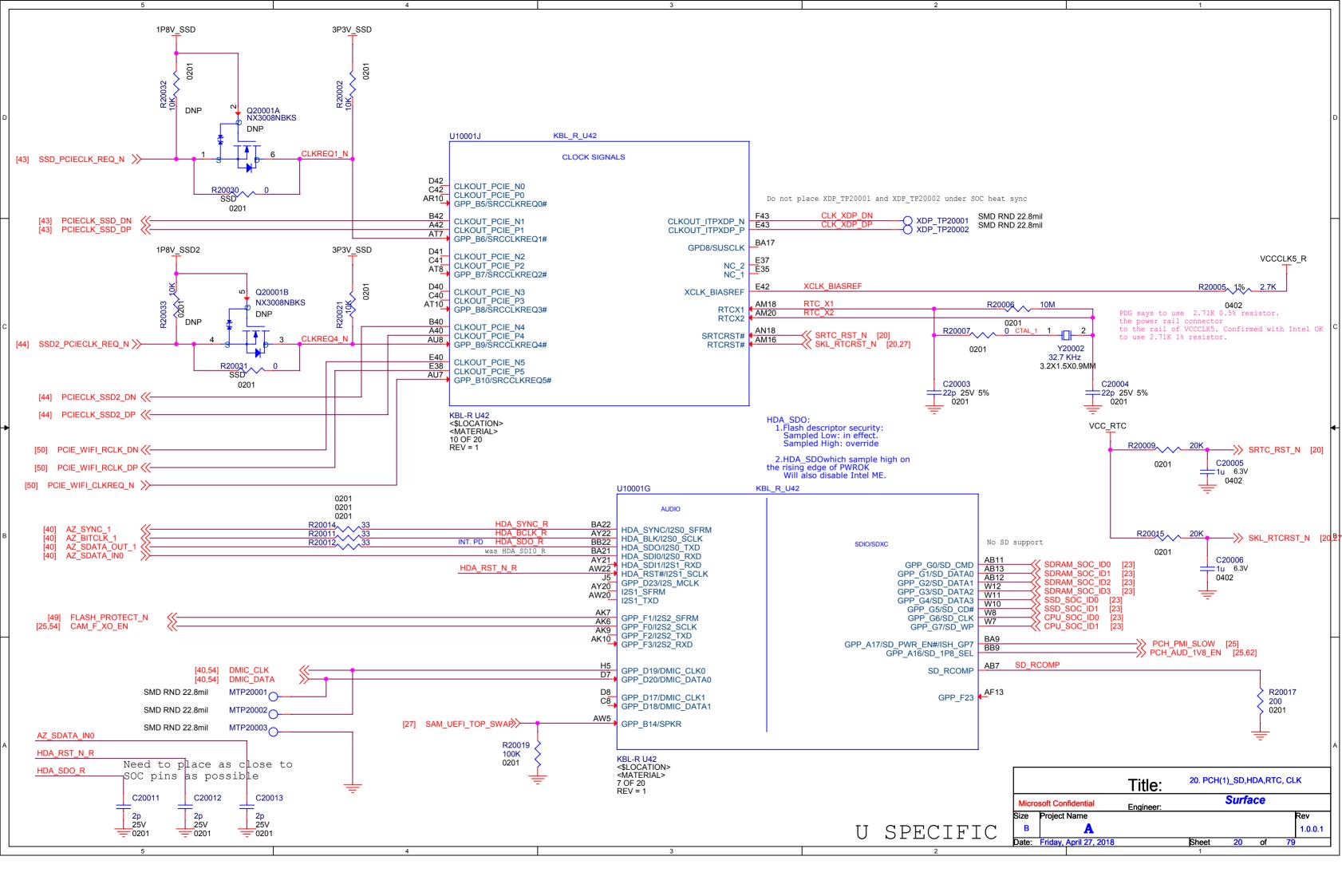


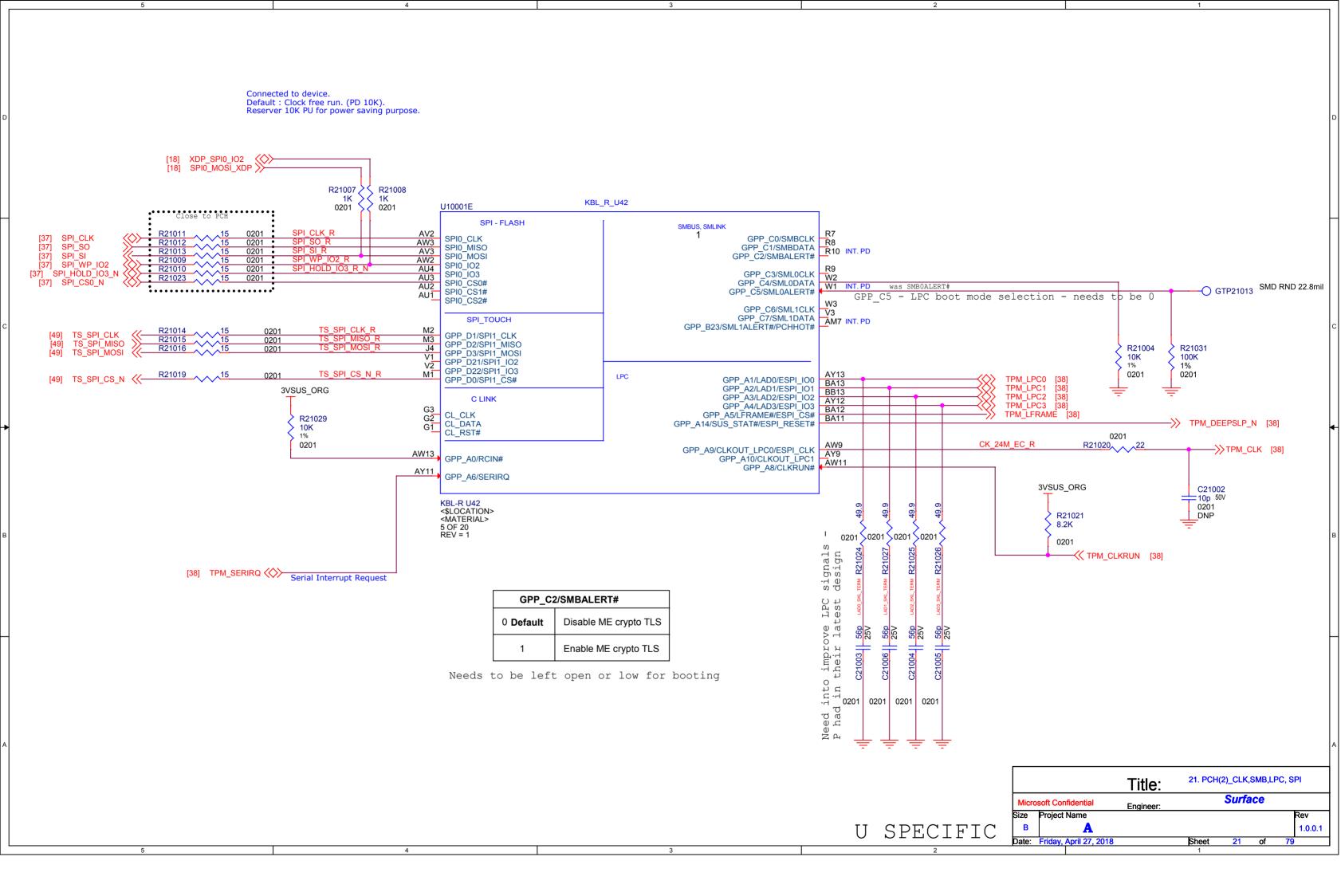


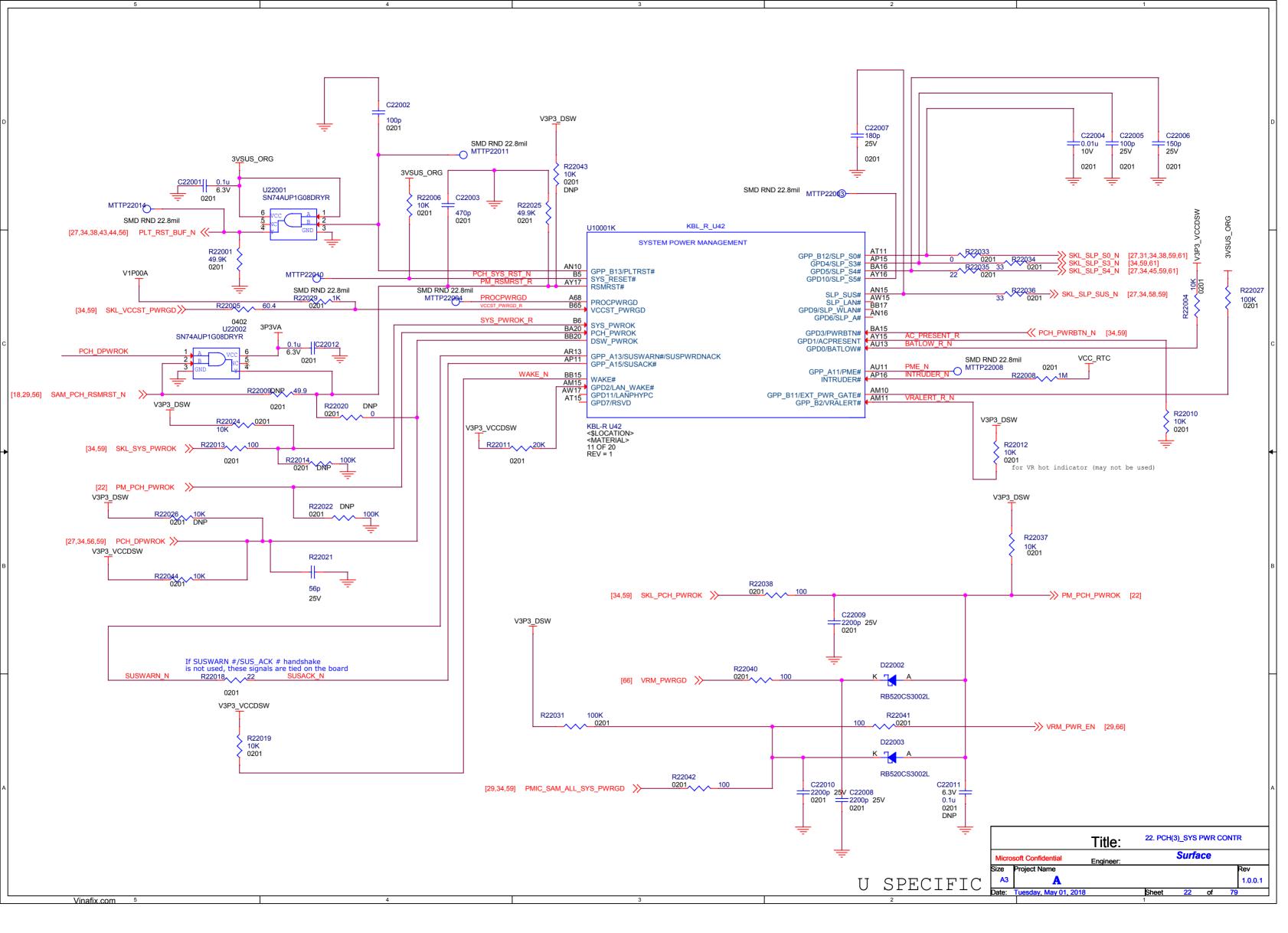


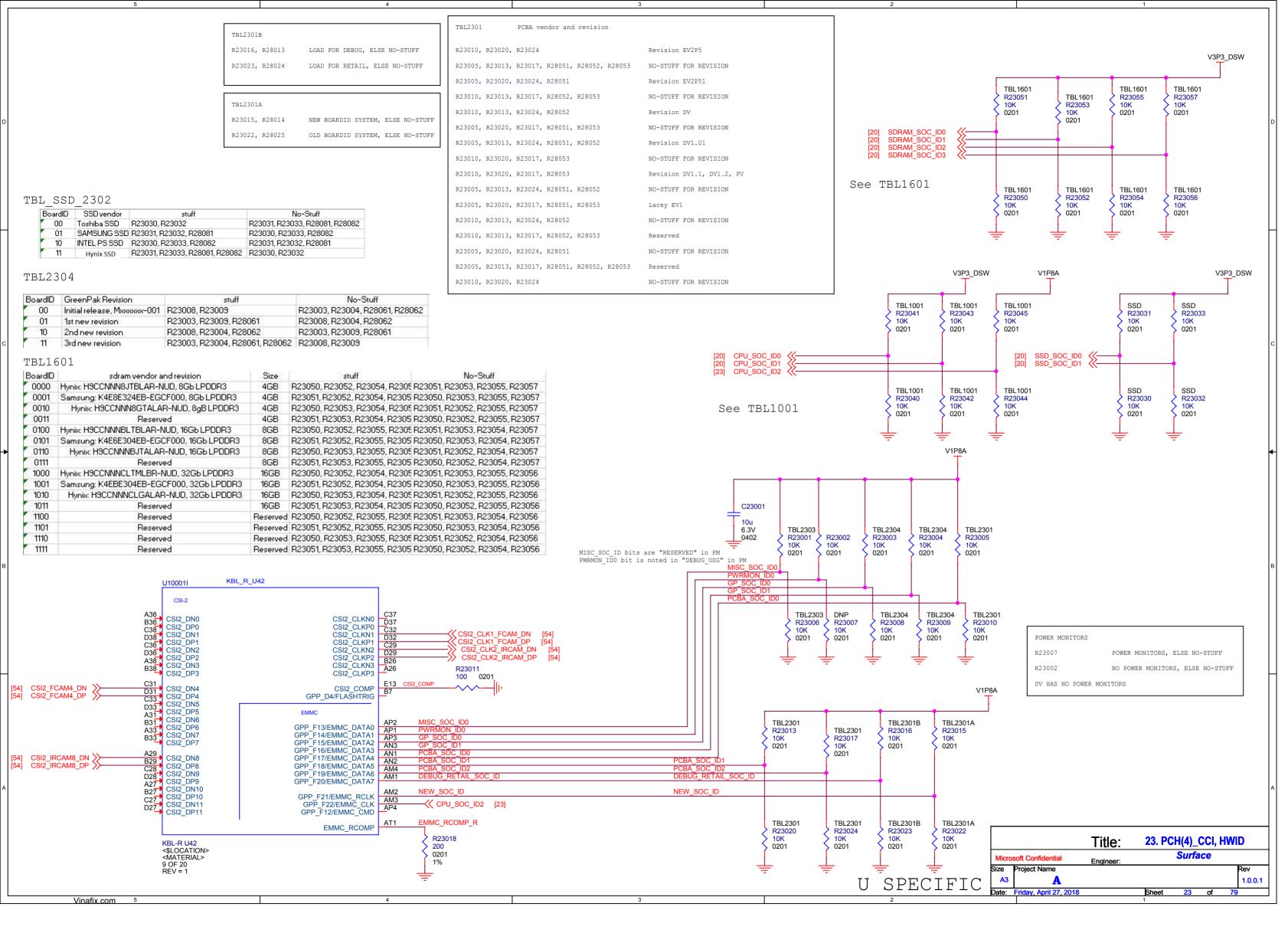


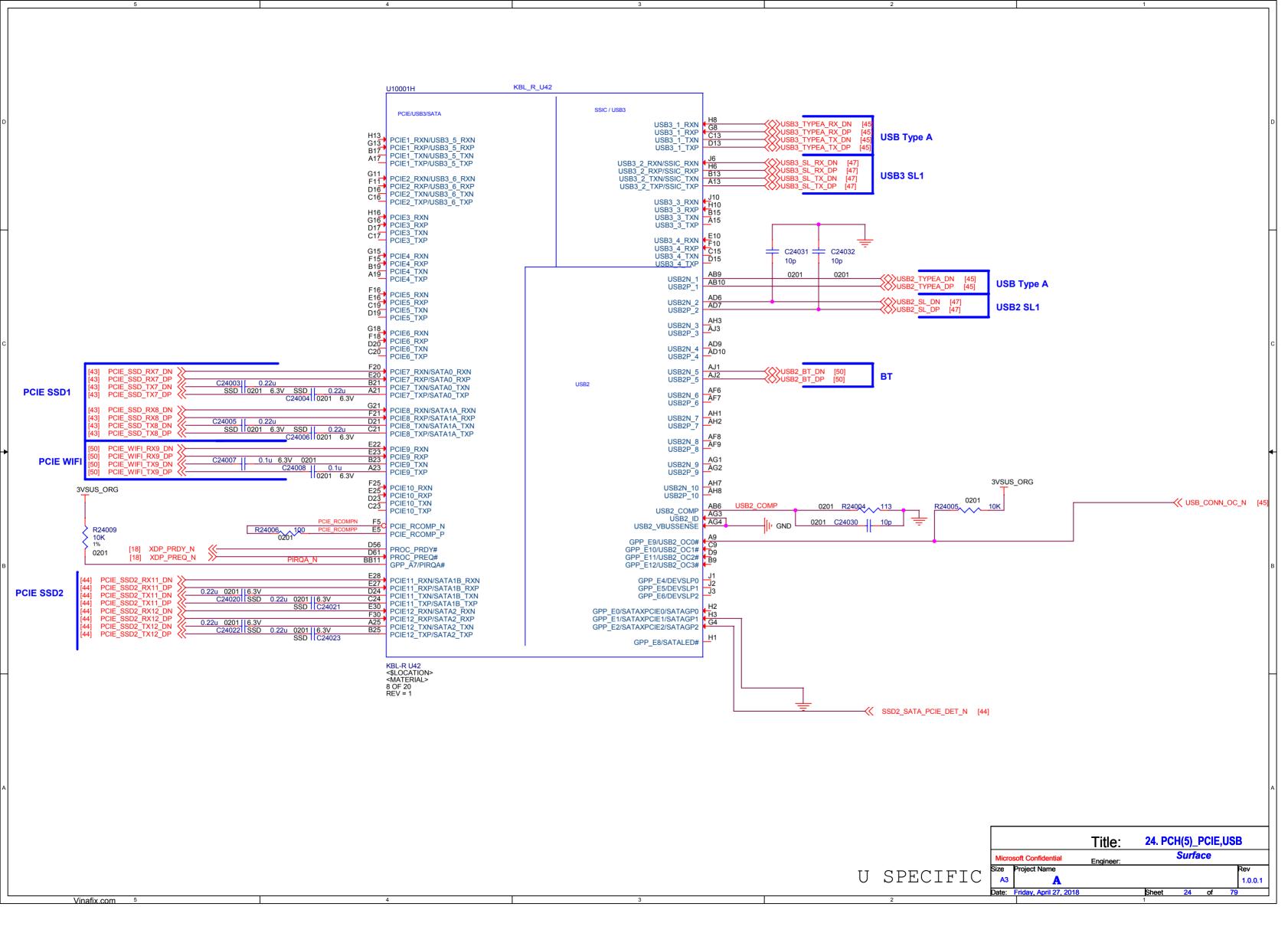


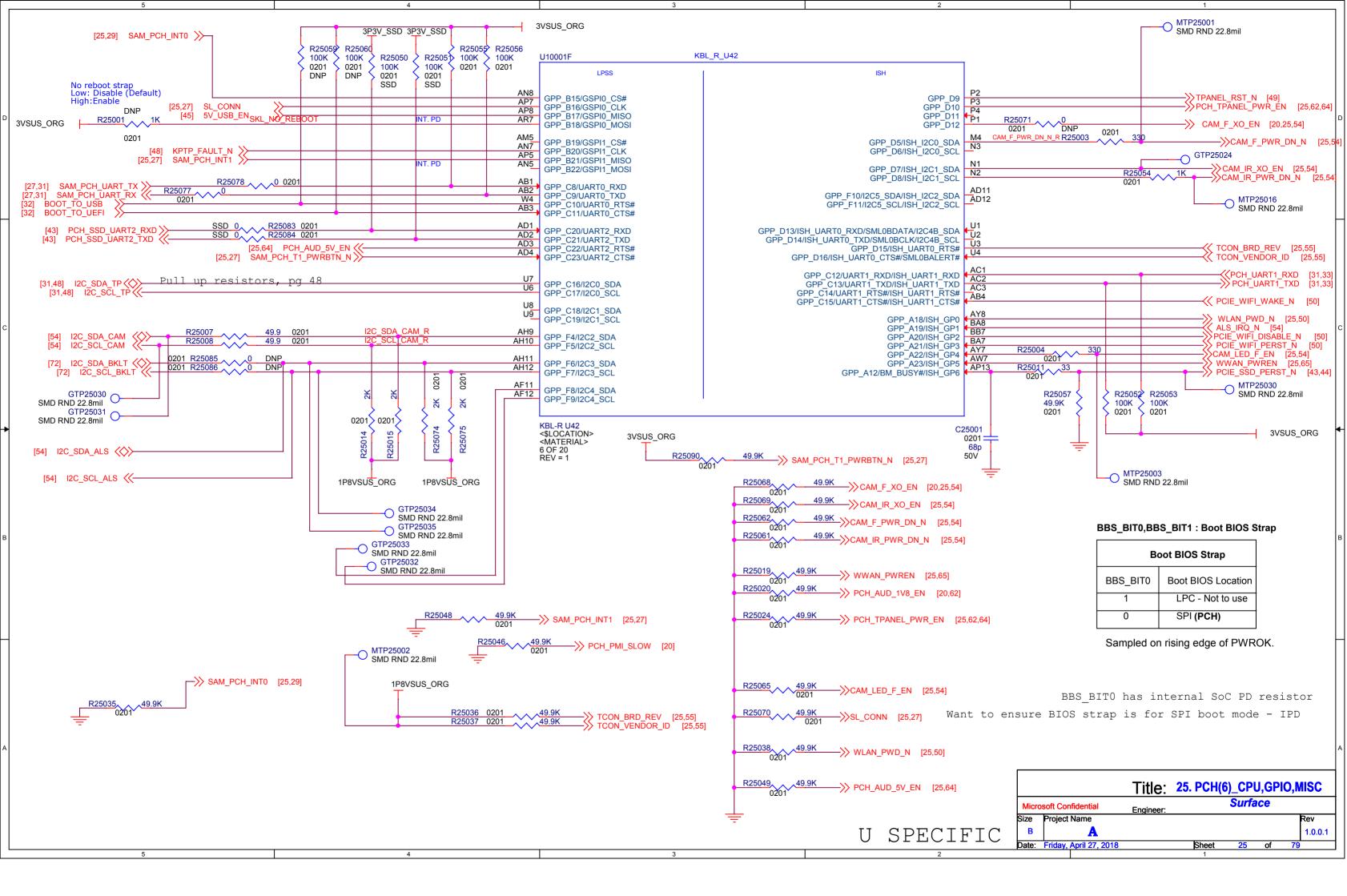


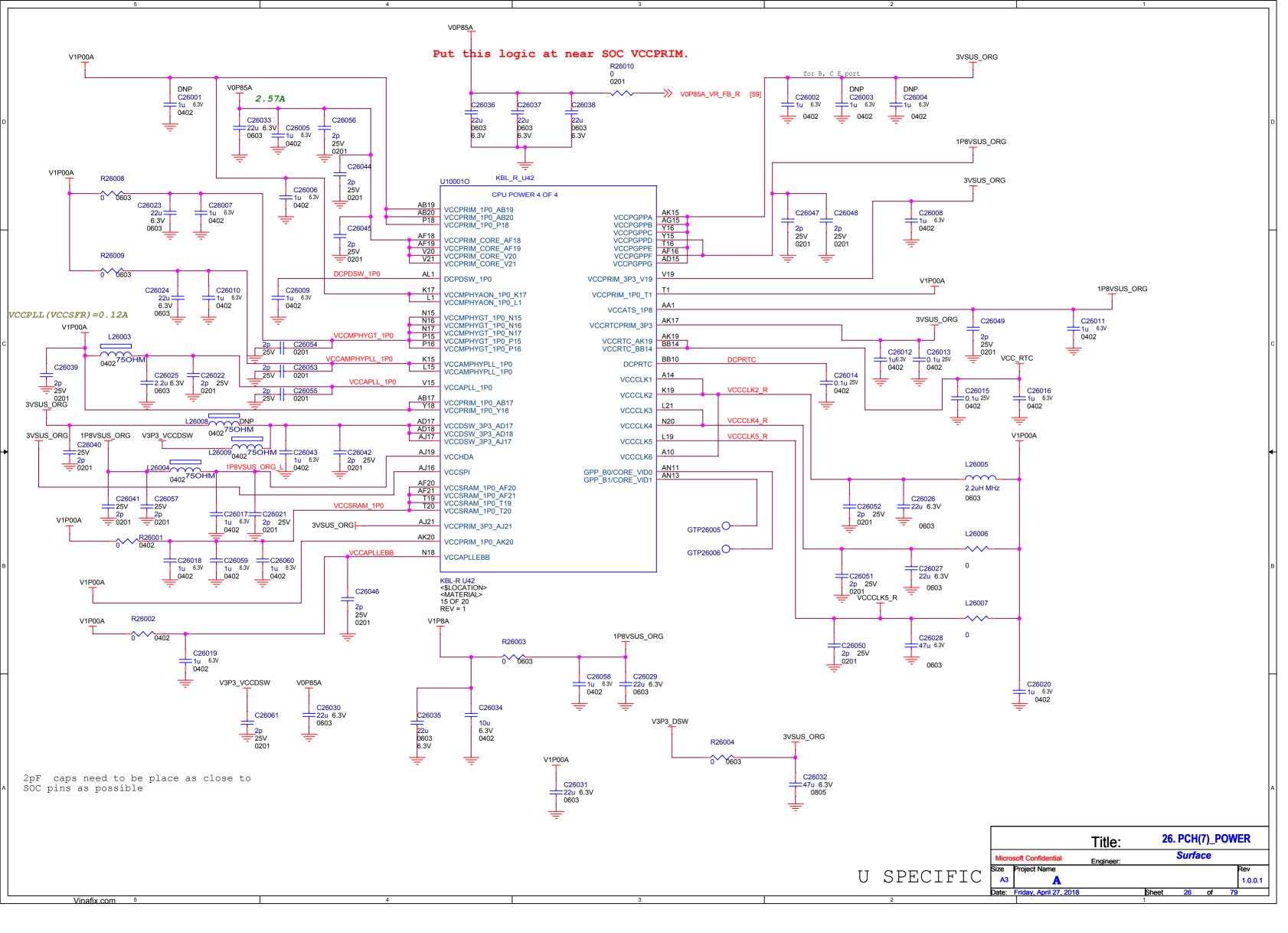


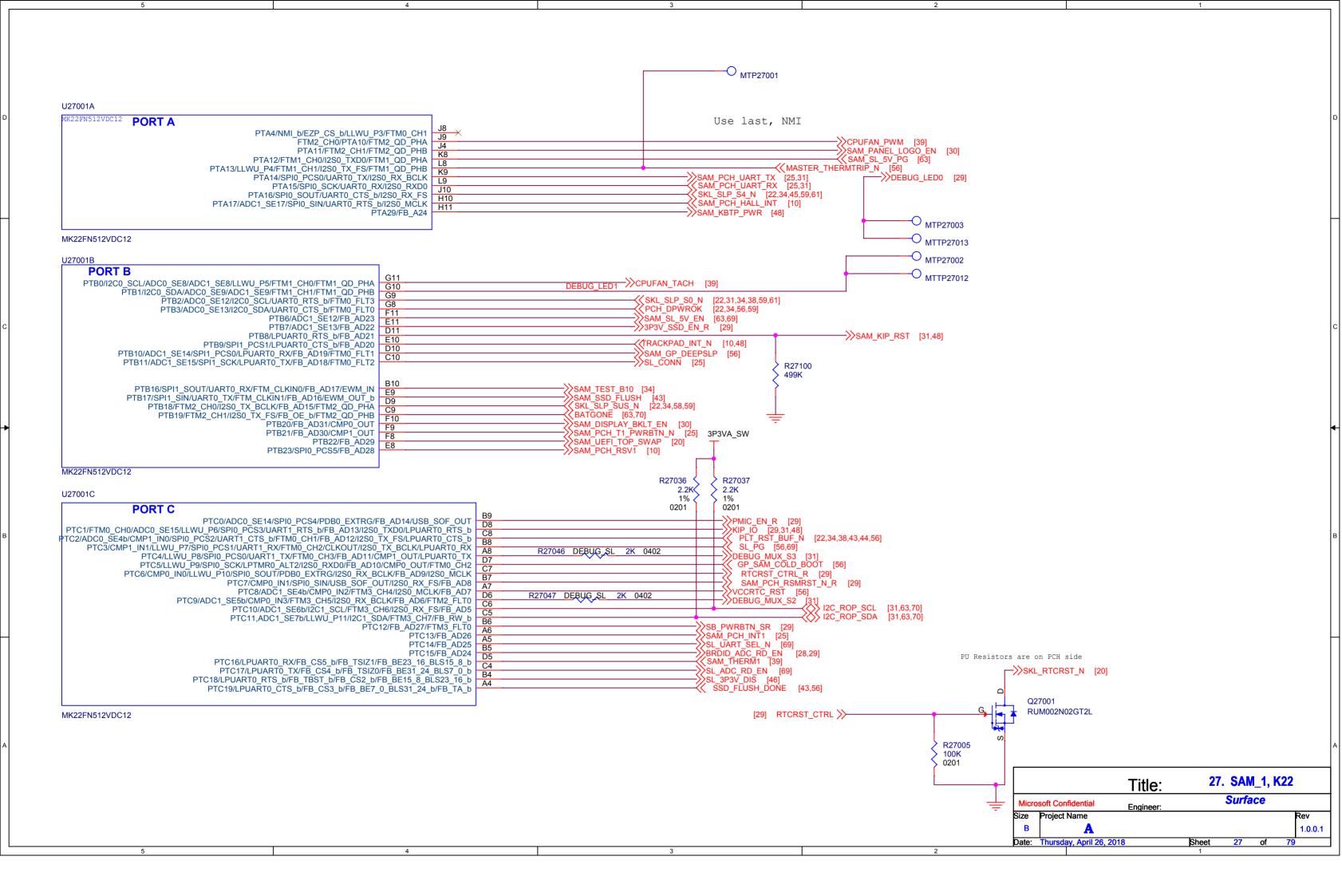


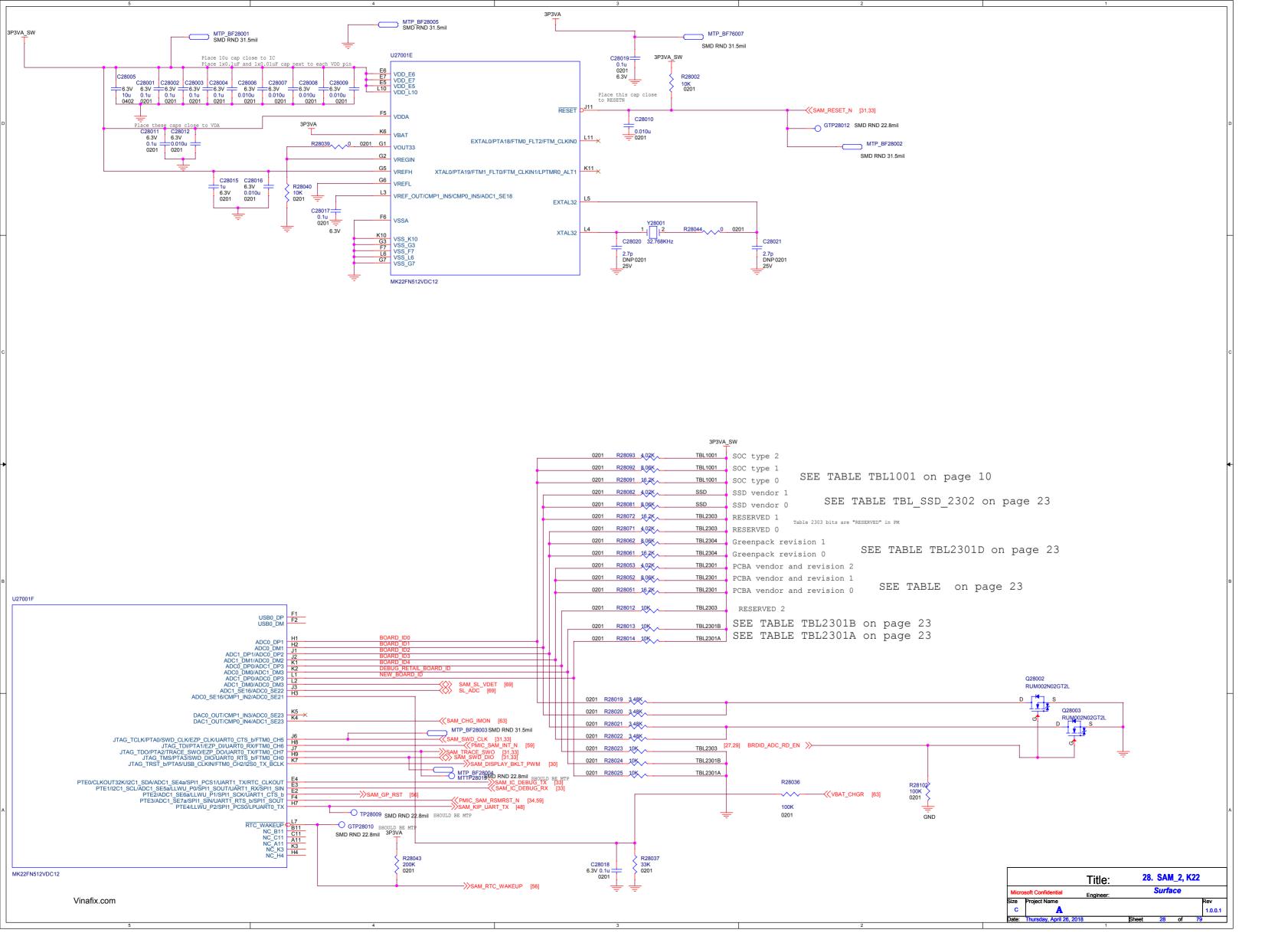


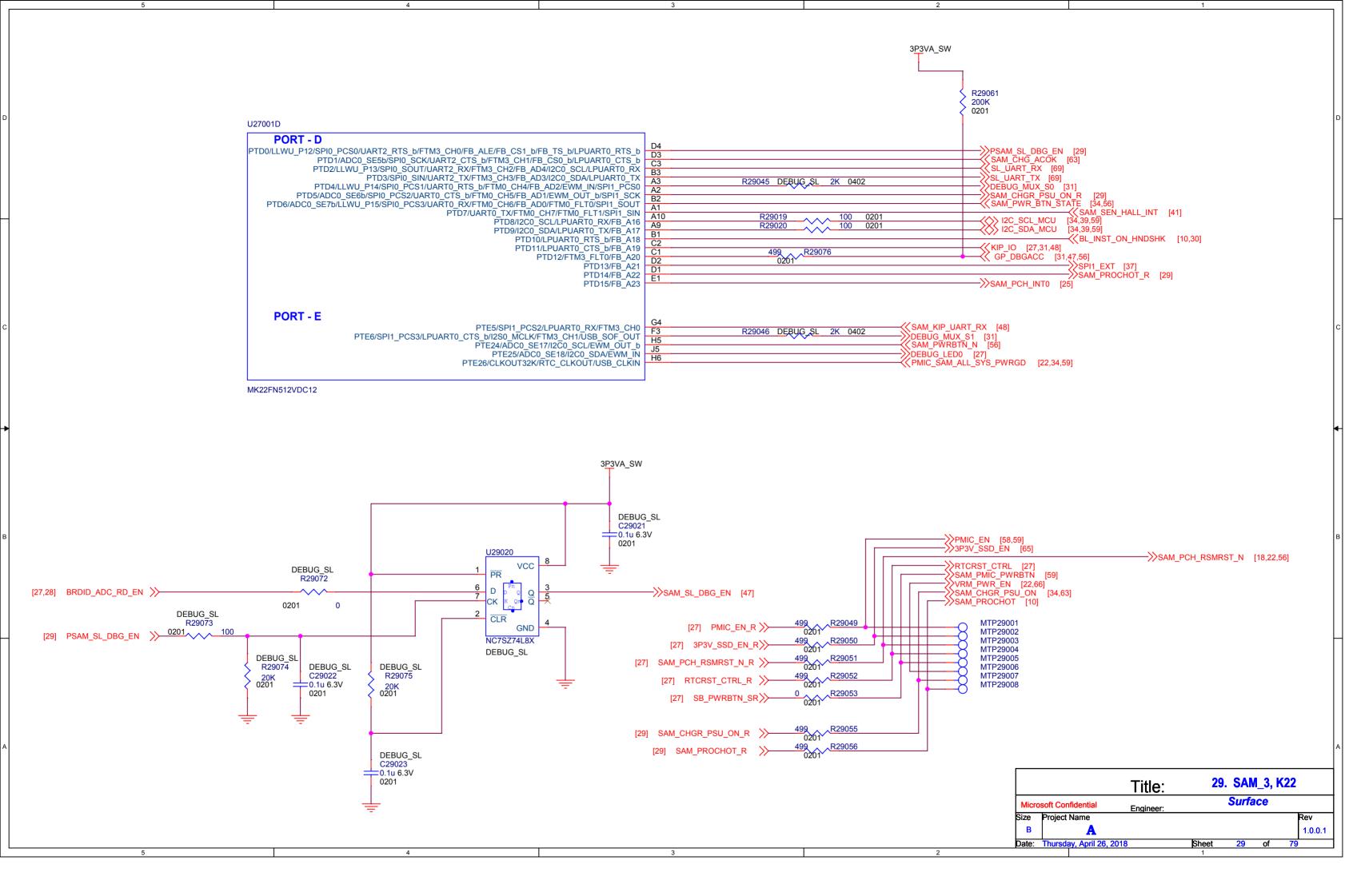


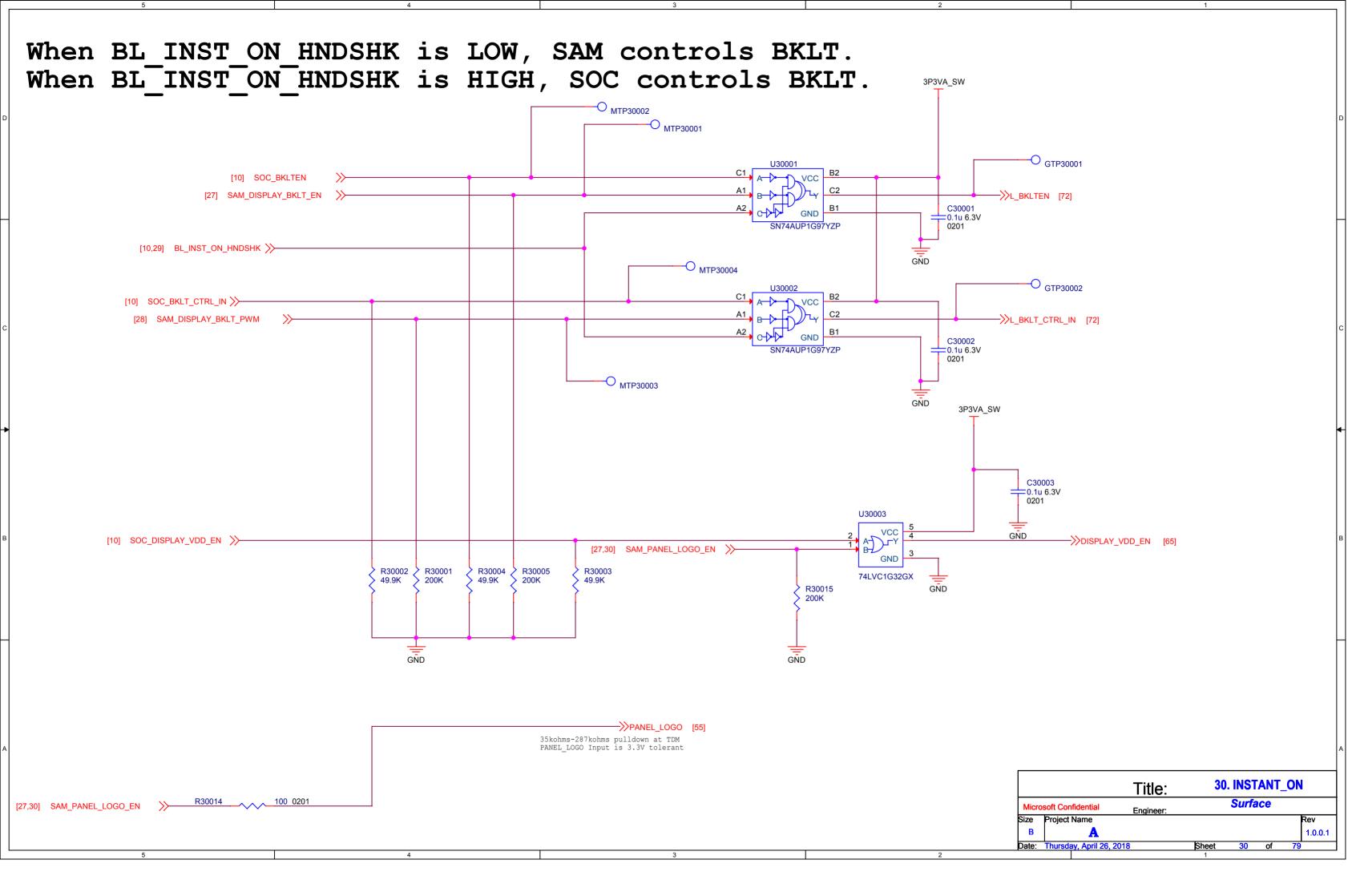


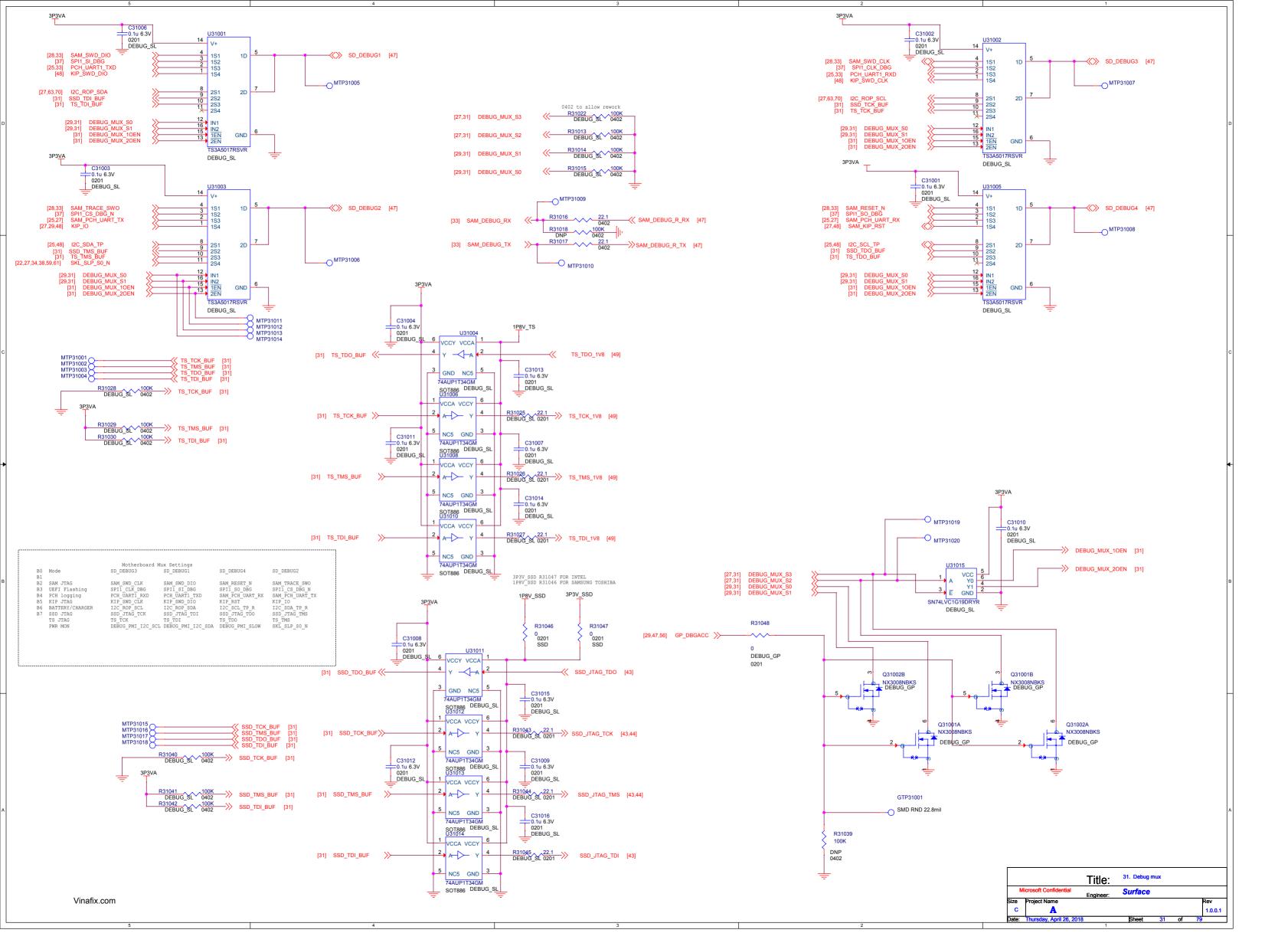


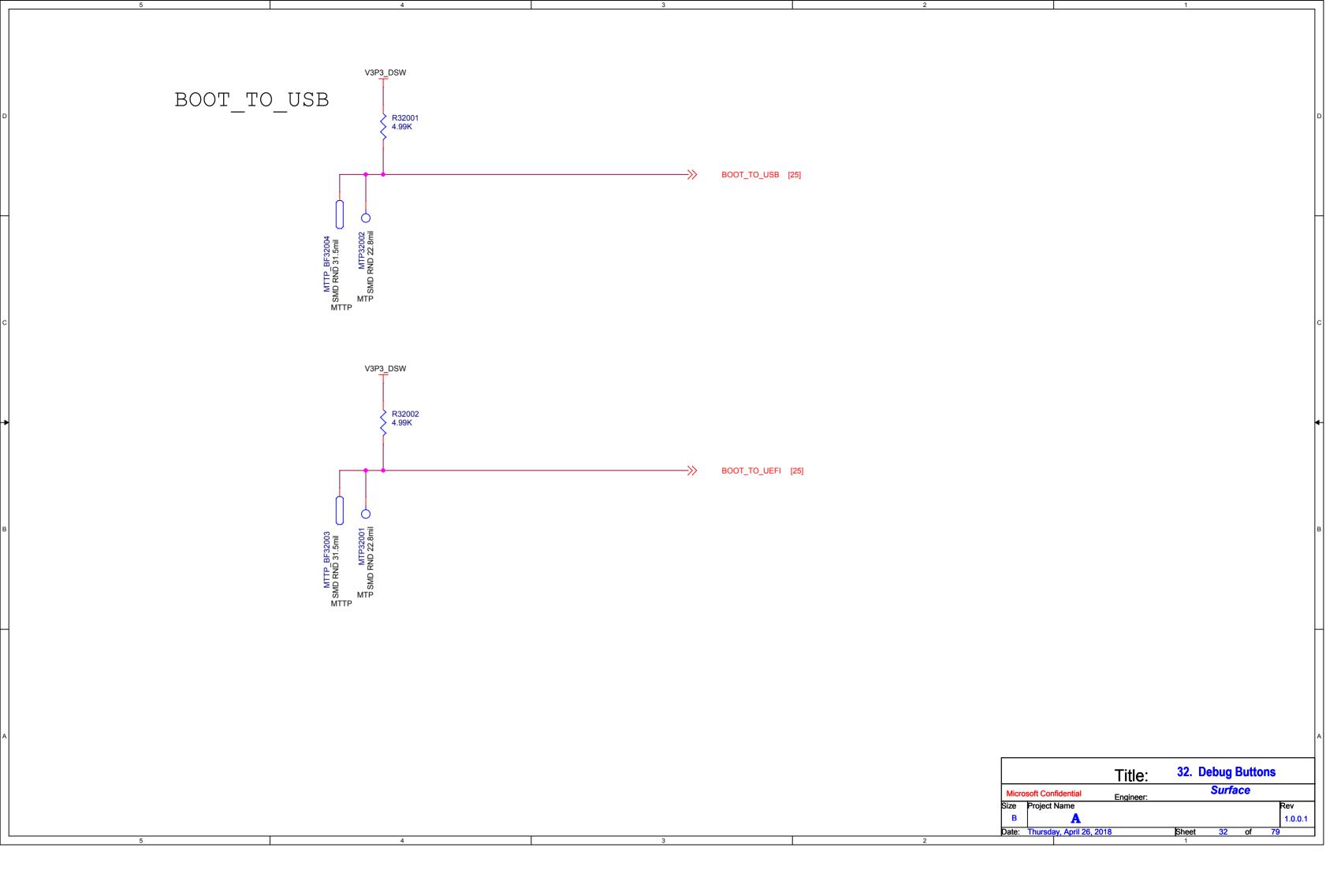


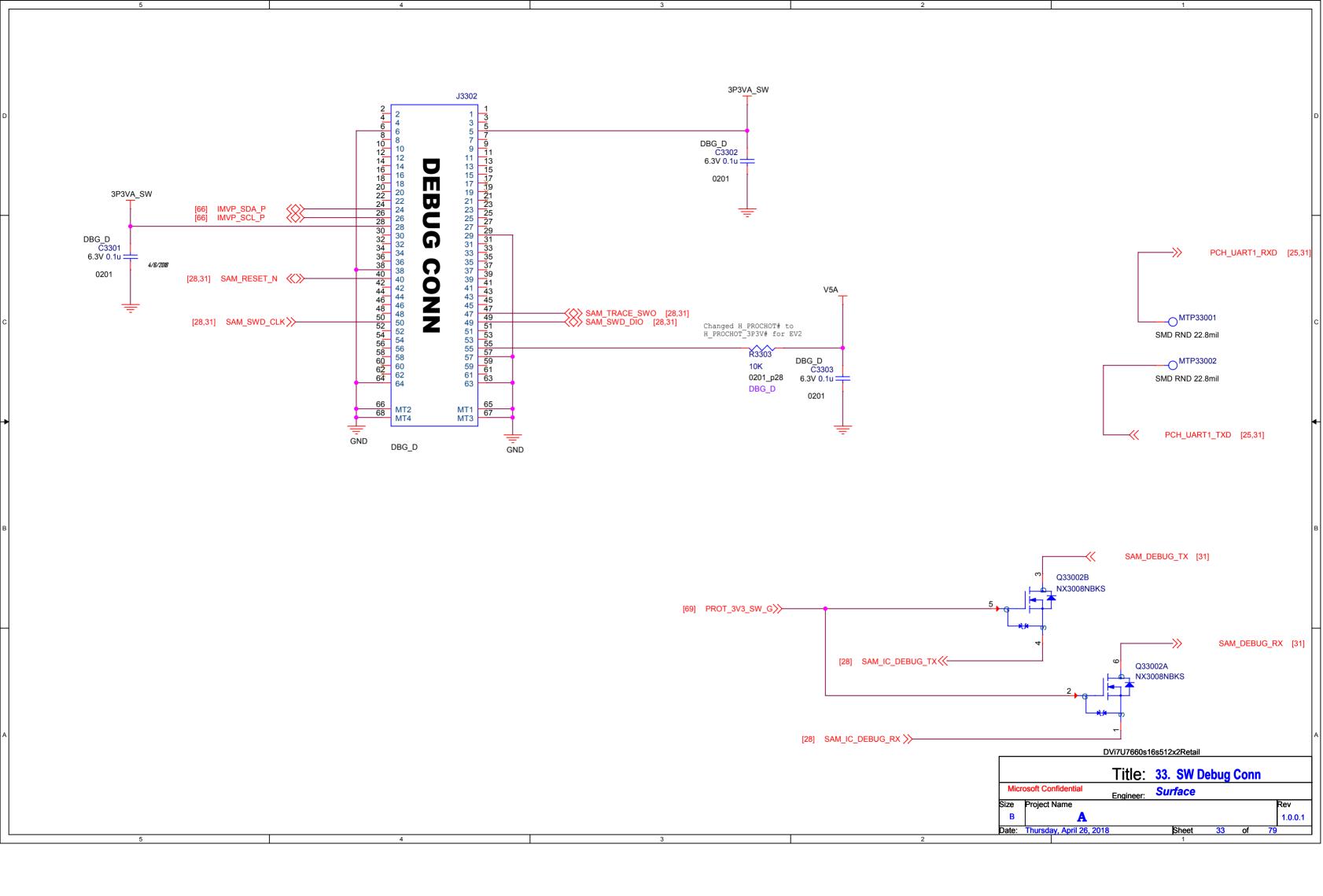


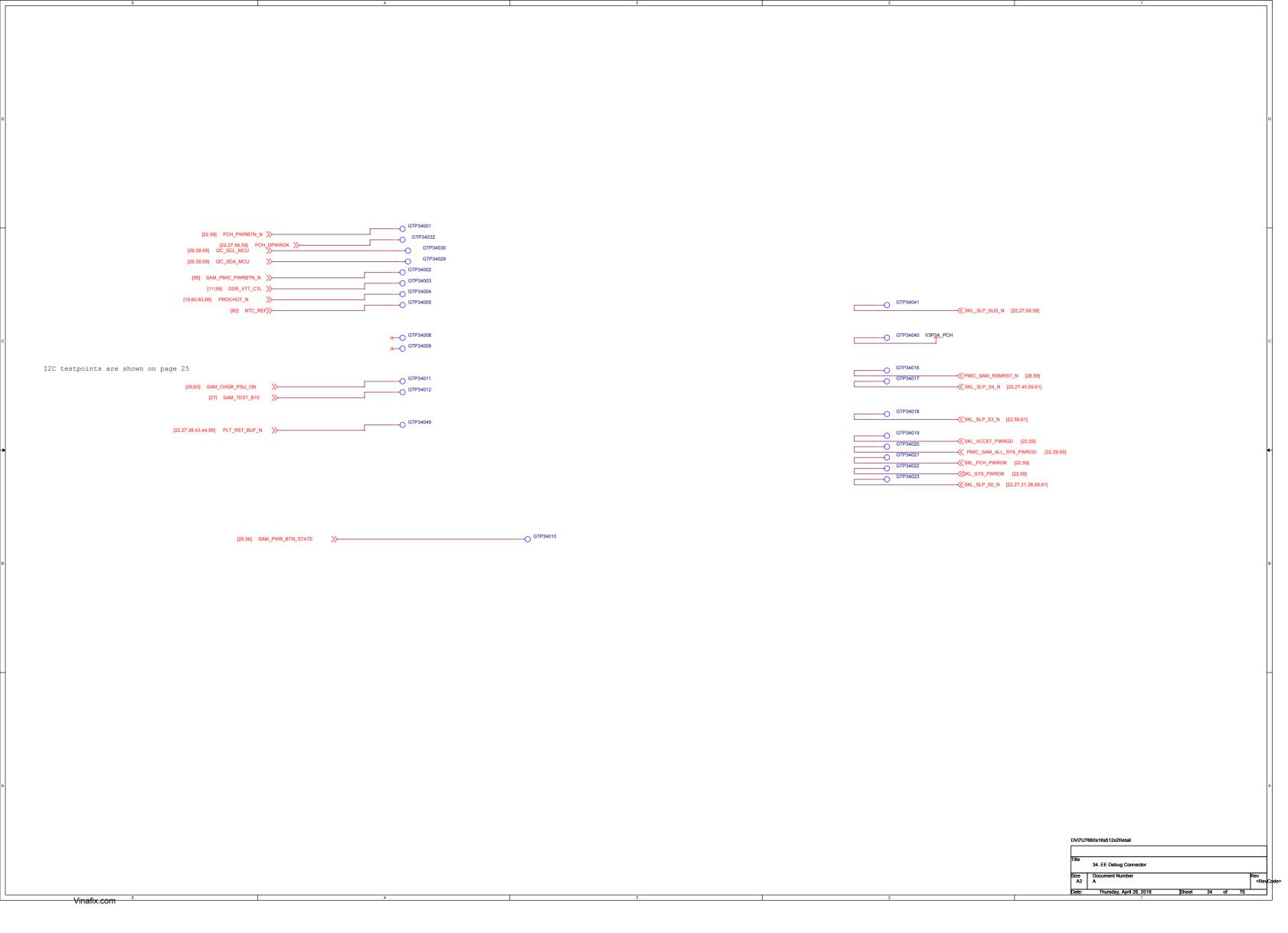


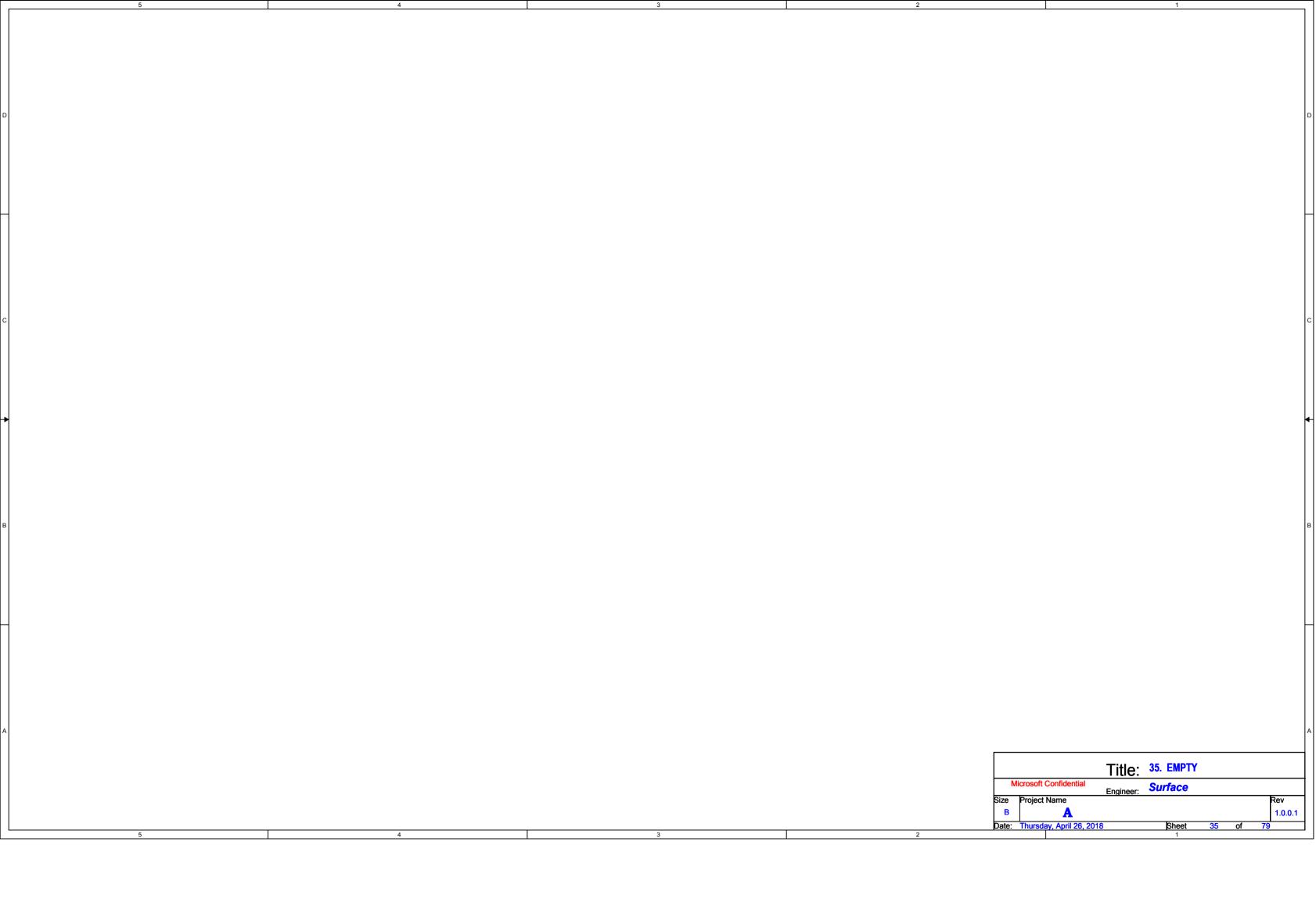












SMD RND 22.8mil

MTP36001

MTP36002

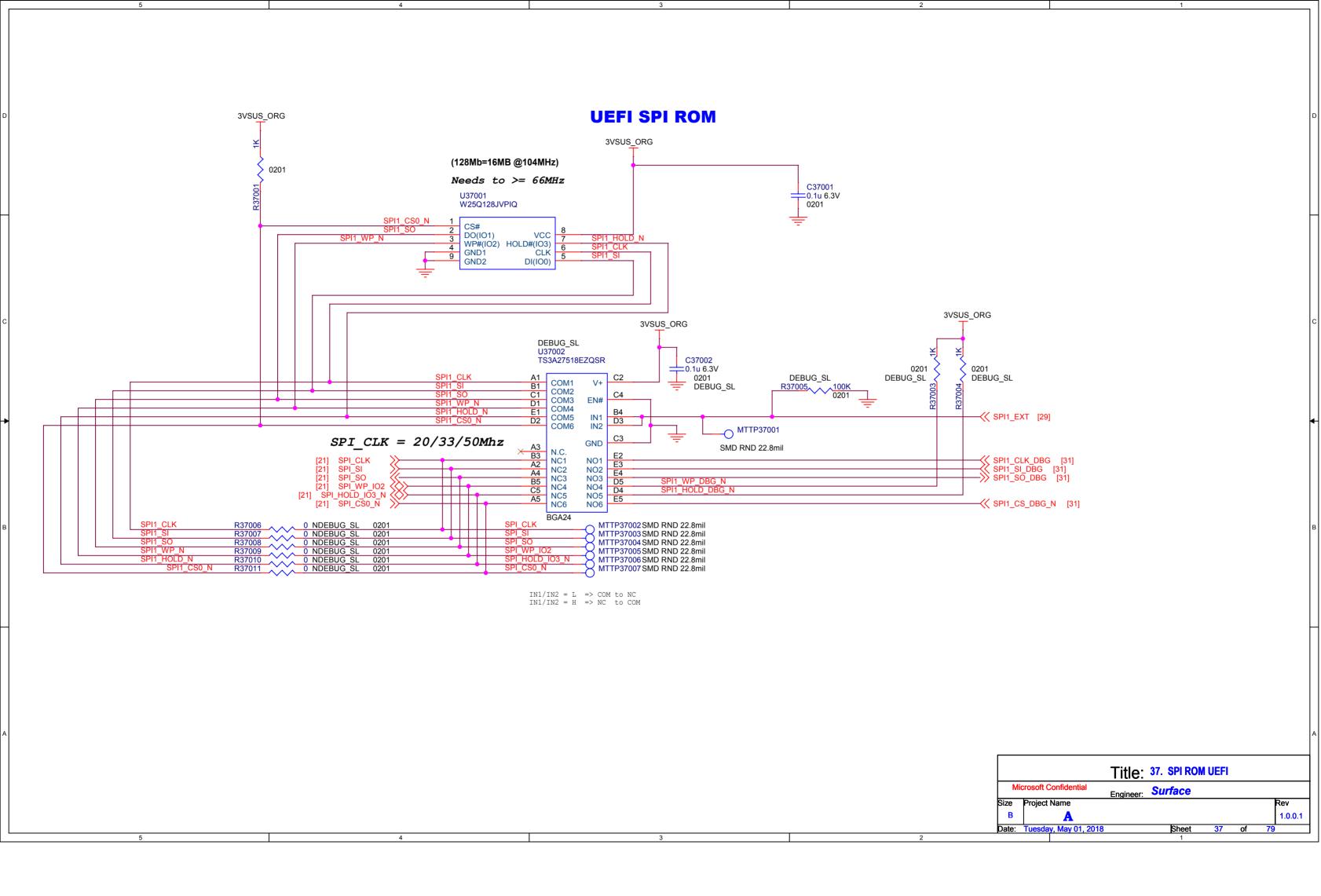
SMD RND 22.8mil

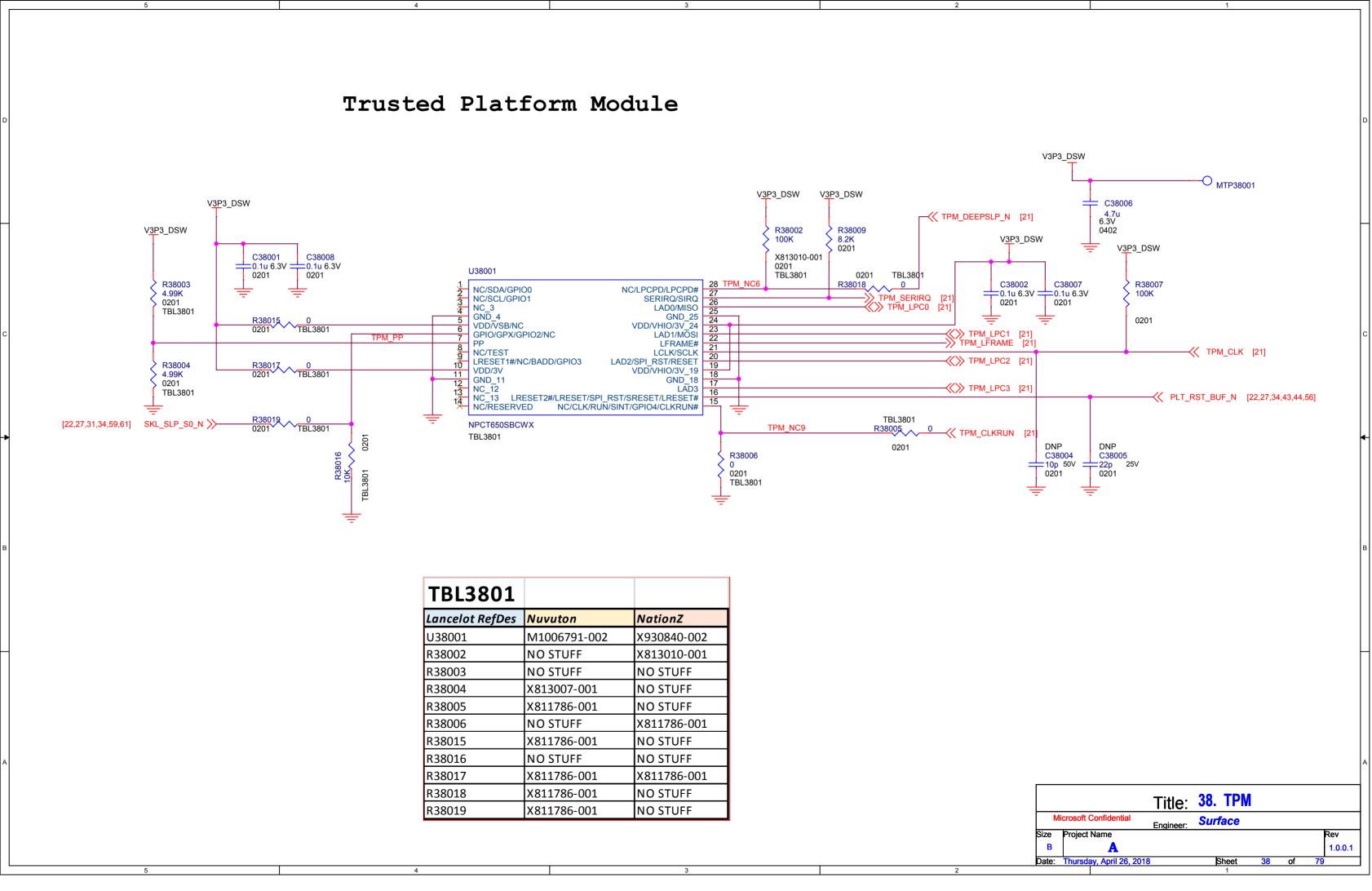
× MTP36003 SMD RND 22.8mil

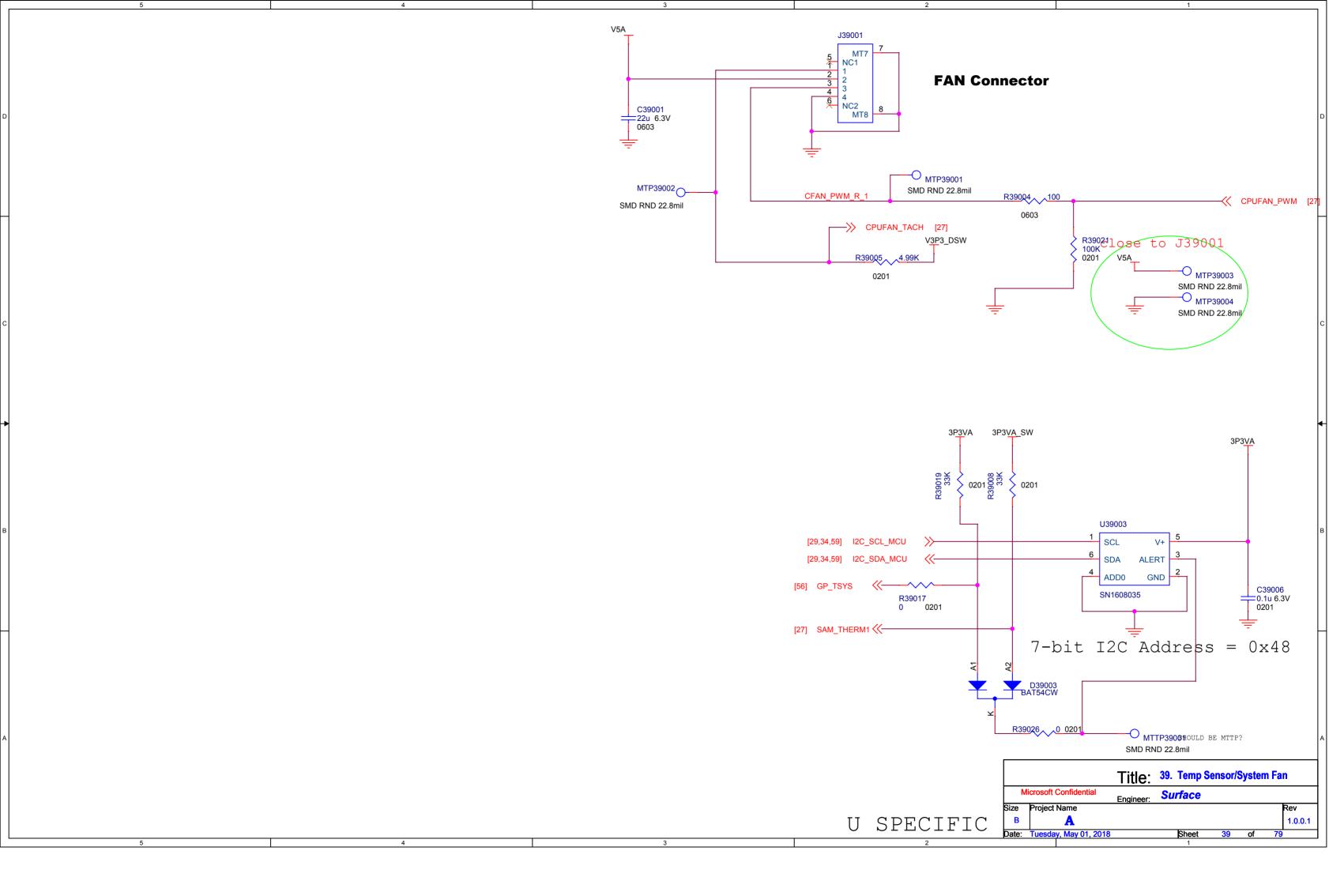
No Power Monitors in this SKU

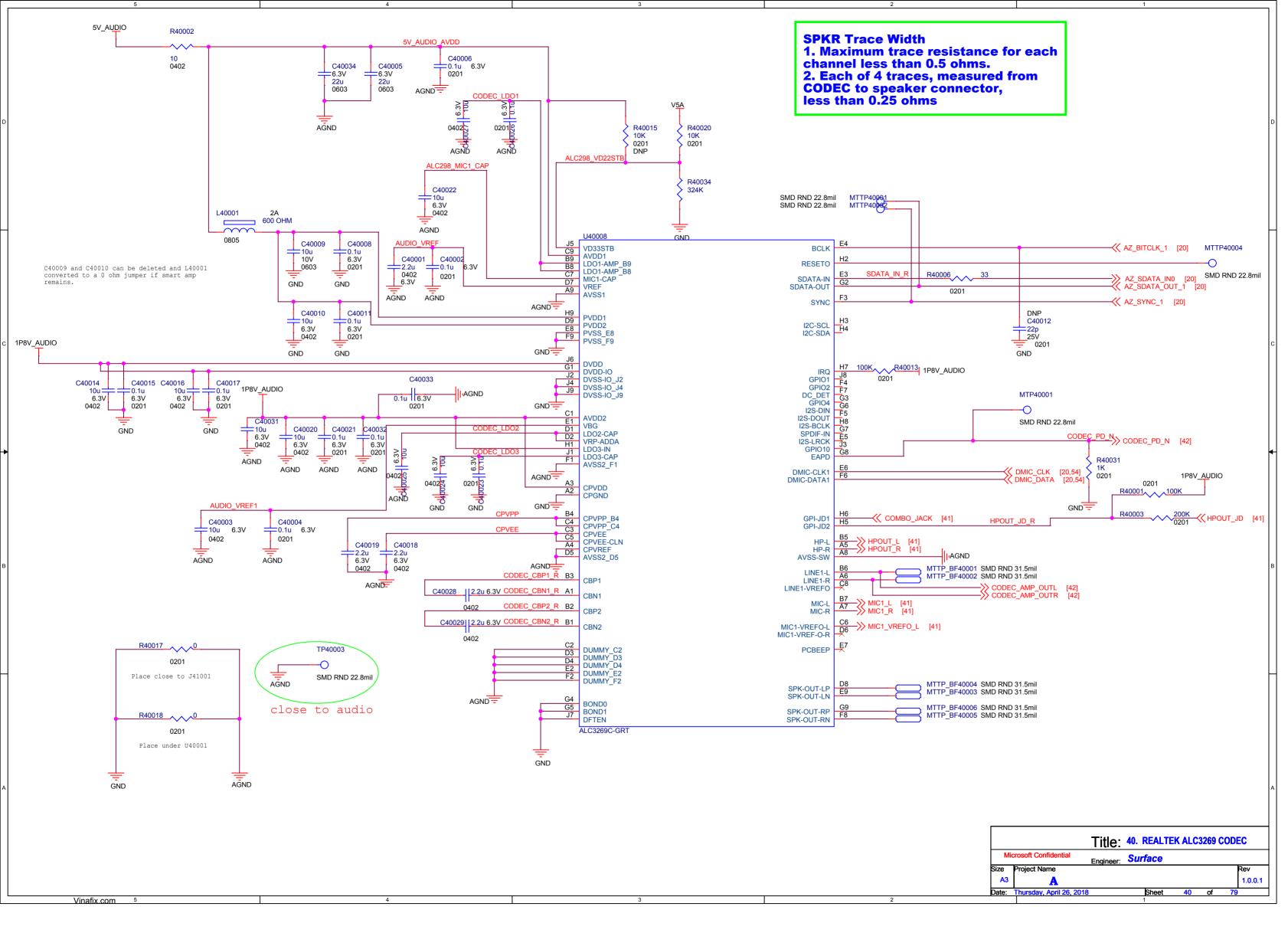
Resistor Address for MAX3440
20.5K => 0x3C/0x3D
11.0K => 0x38/0x39
5.90K => 0x34/0x35
3.16K => 0x30/0x31
1.74K => 0x2C/0x2D
931K => 2x28/2x29
499 => 2x24/2x25
GND => 2x20/2x21

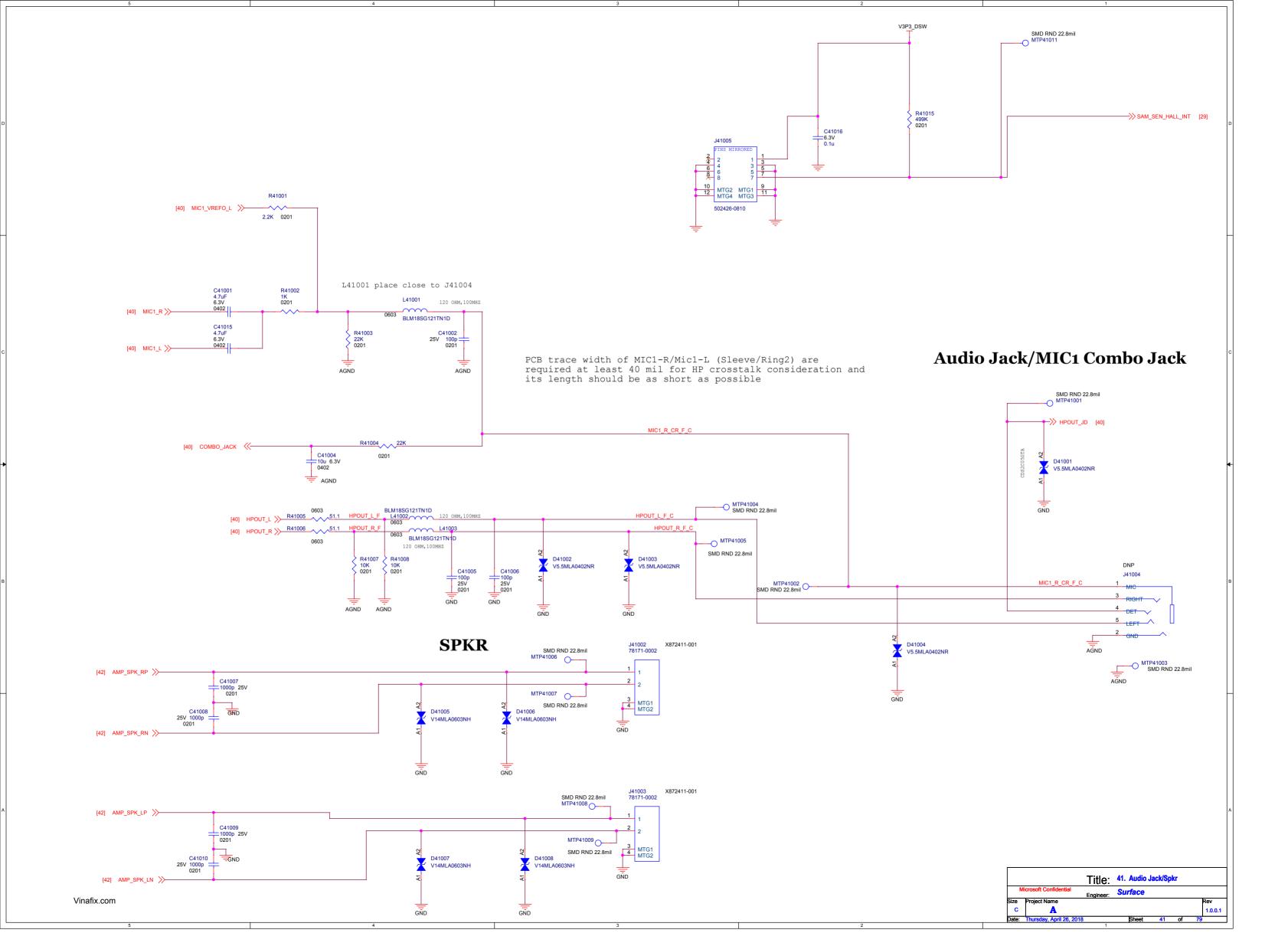


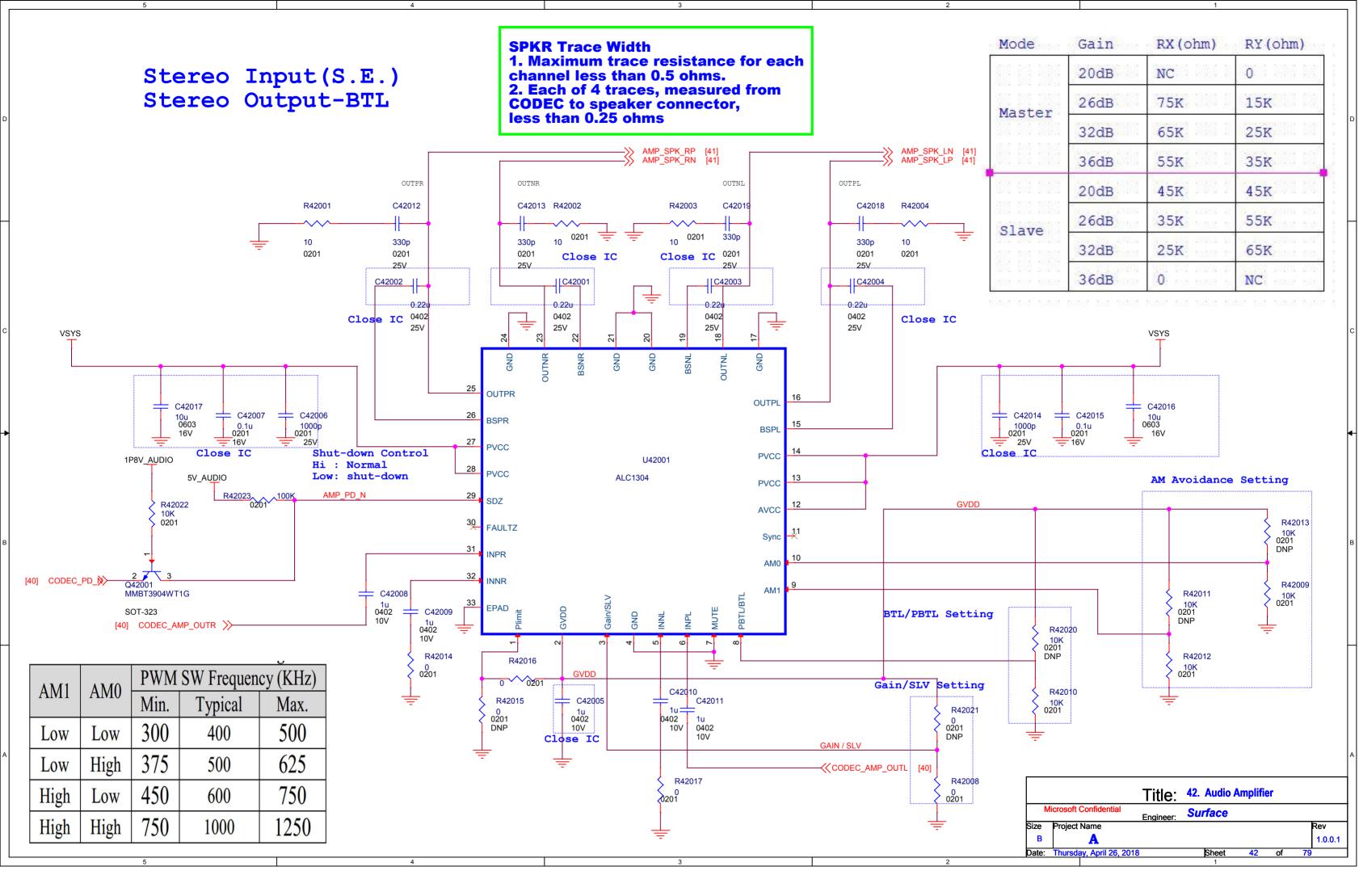


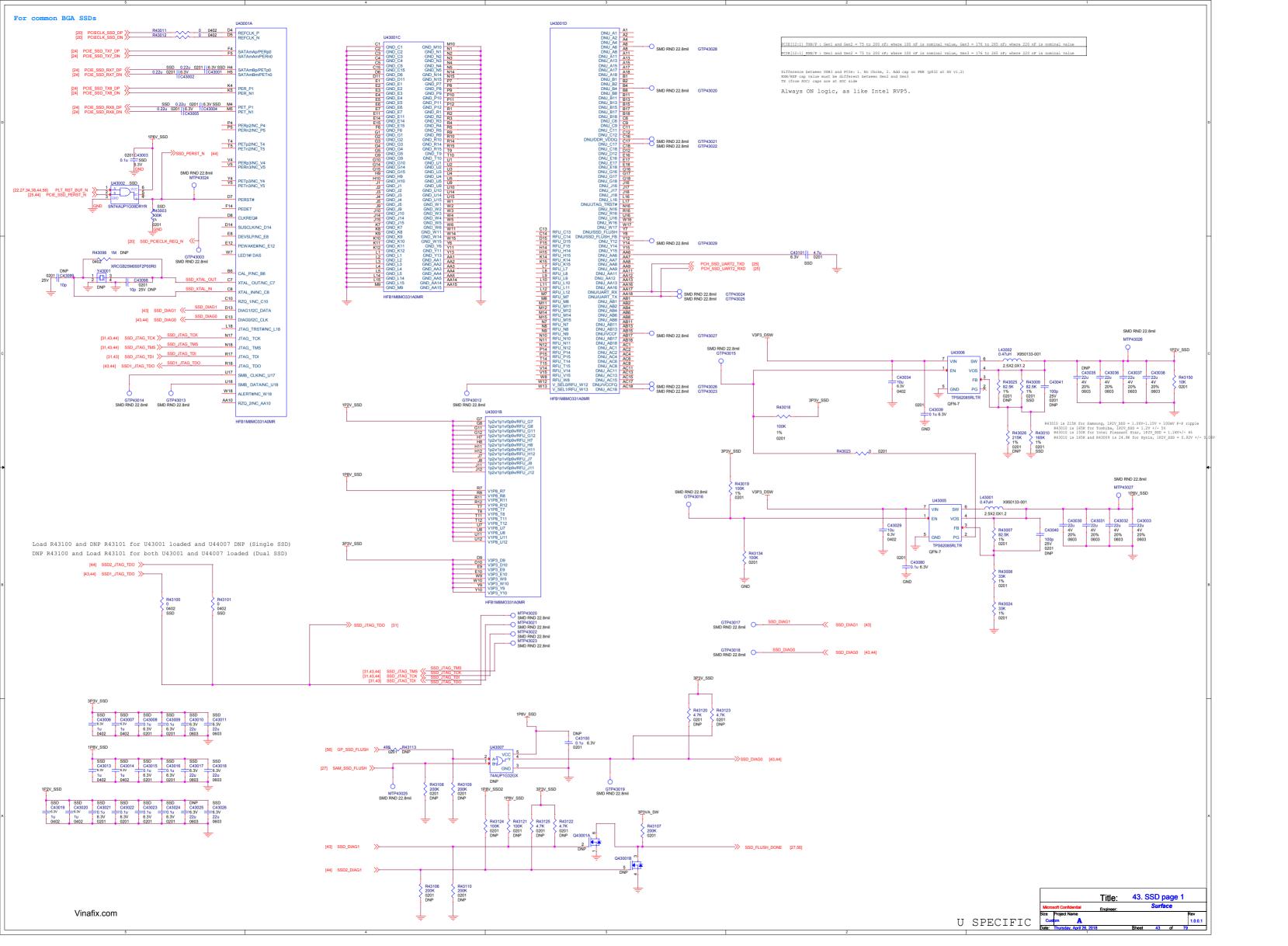


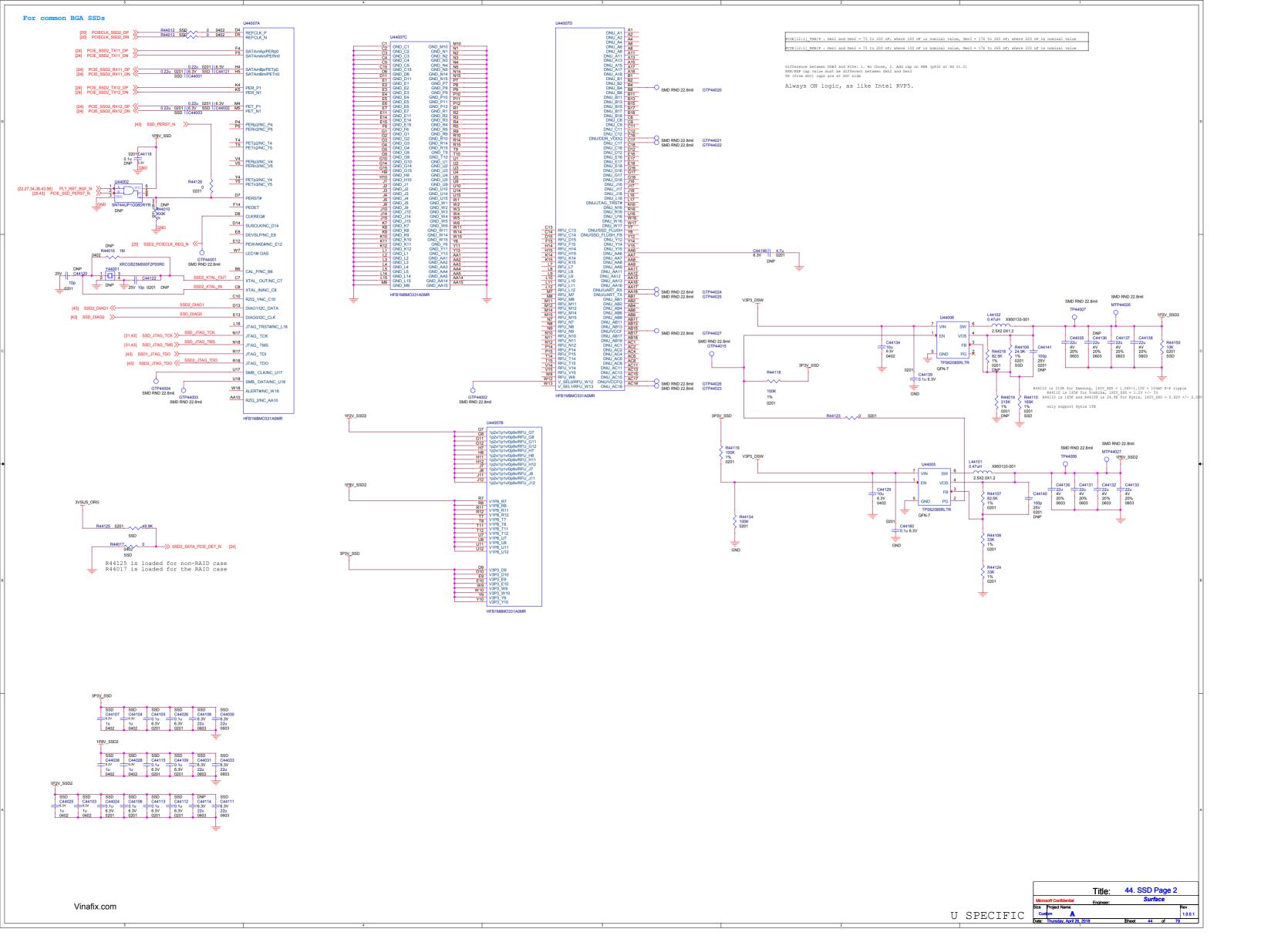


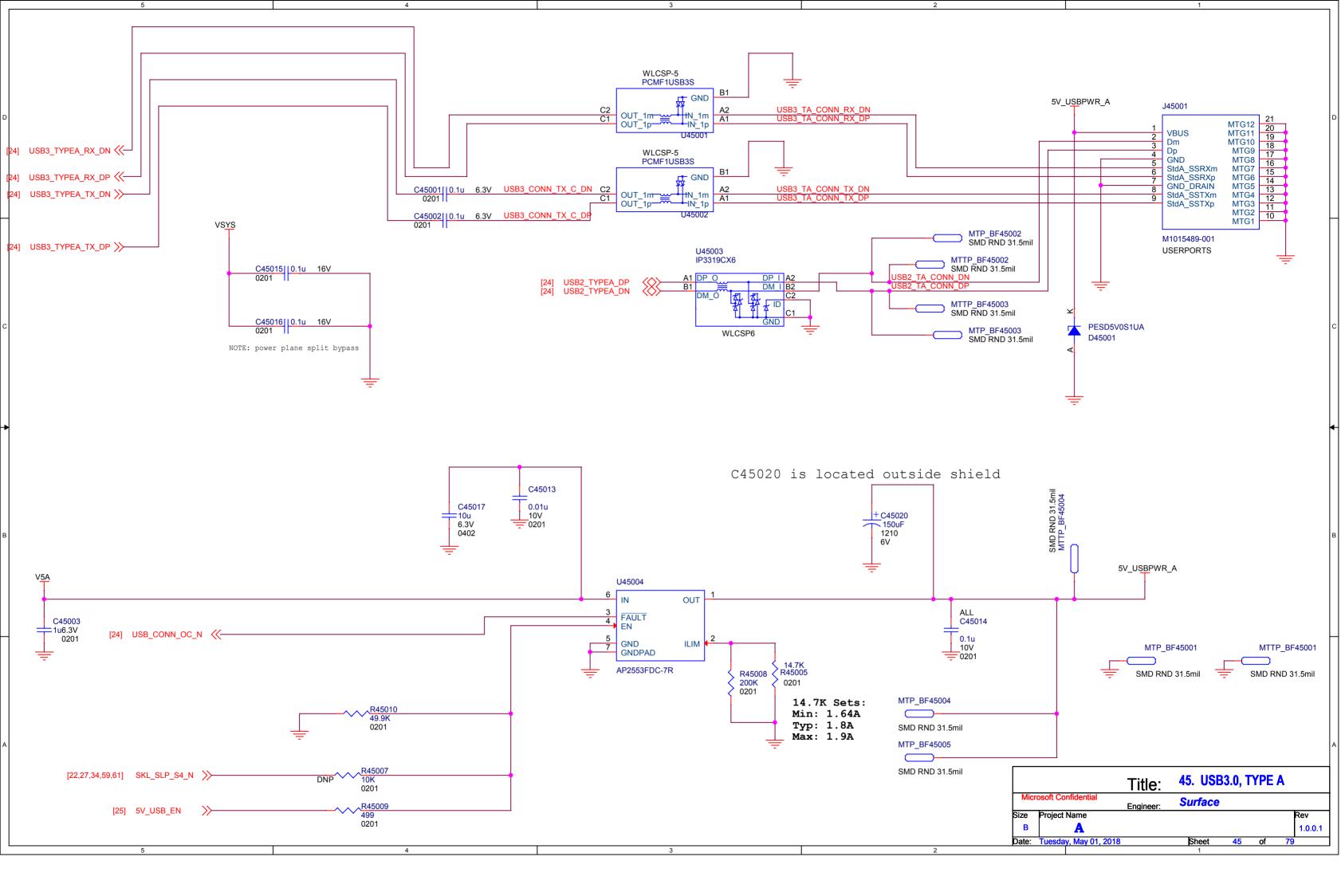


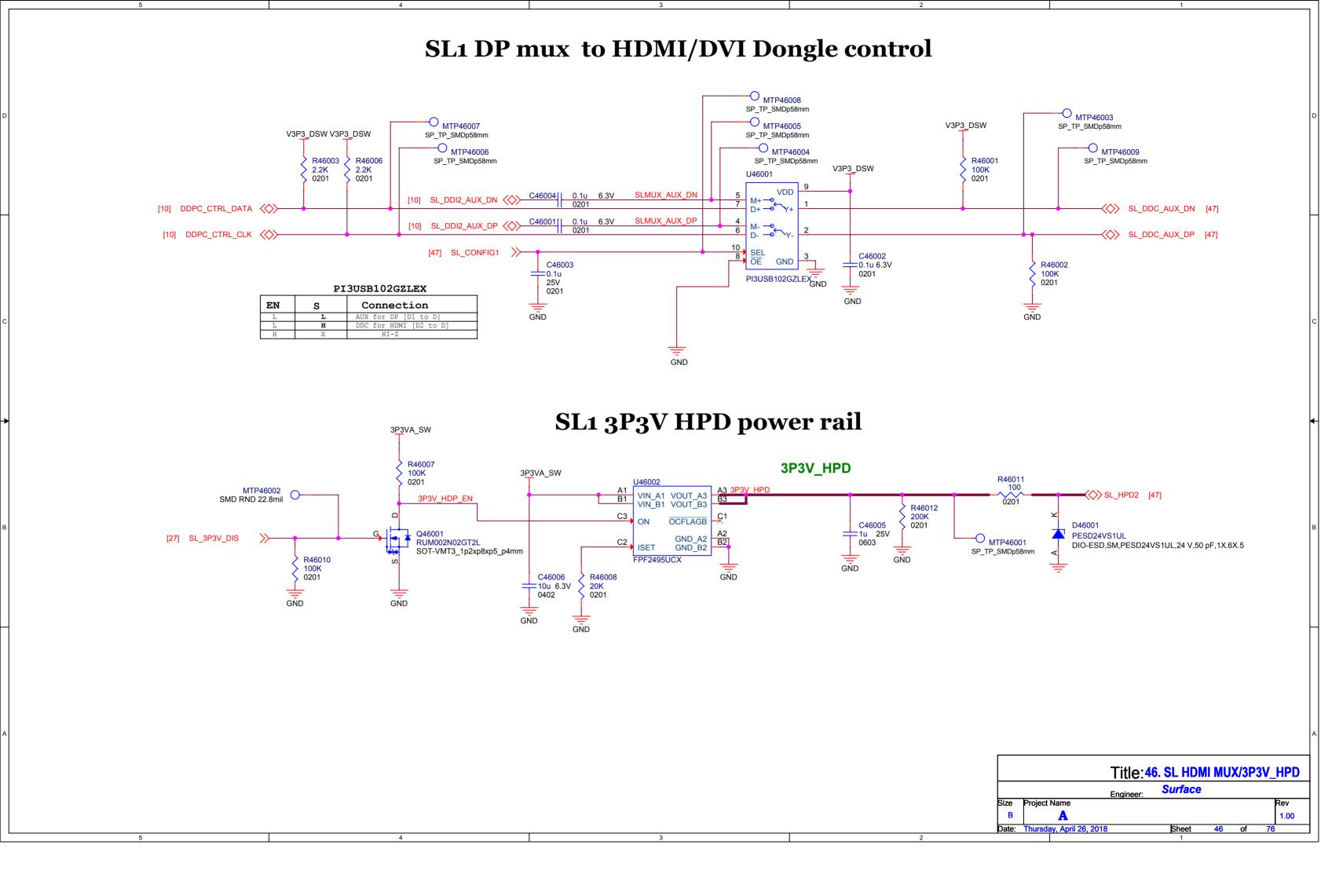


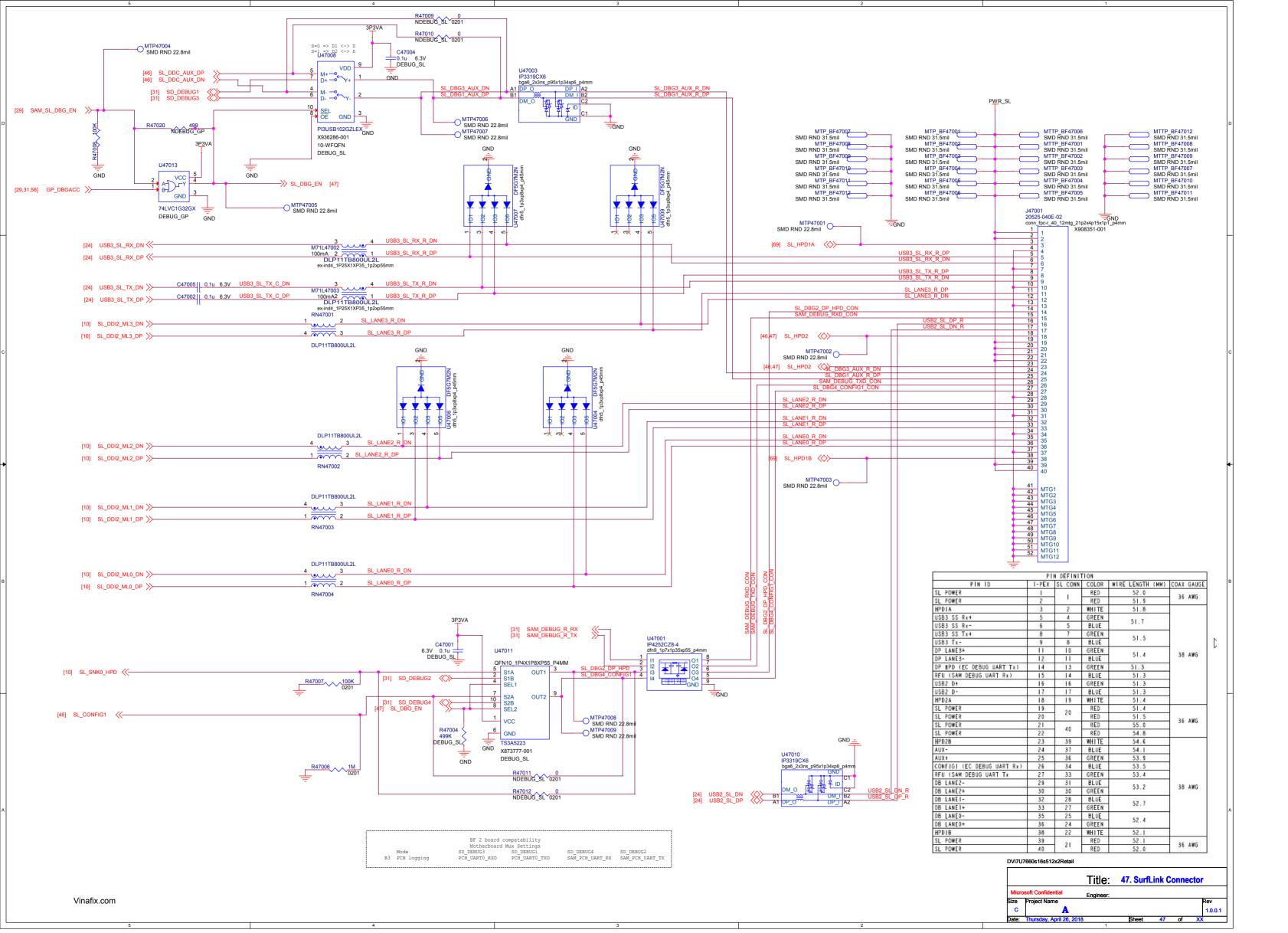


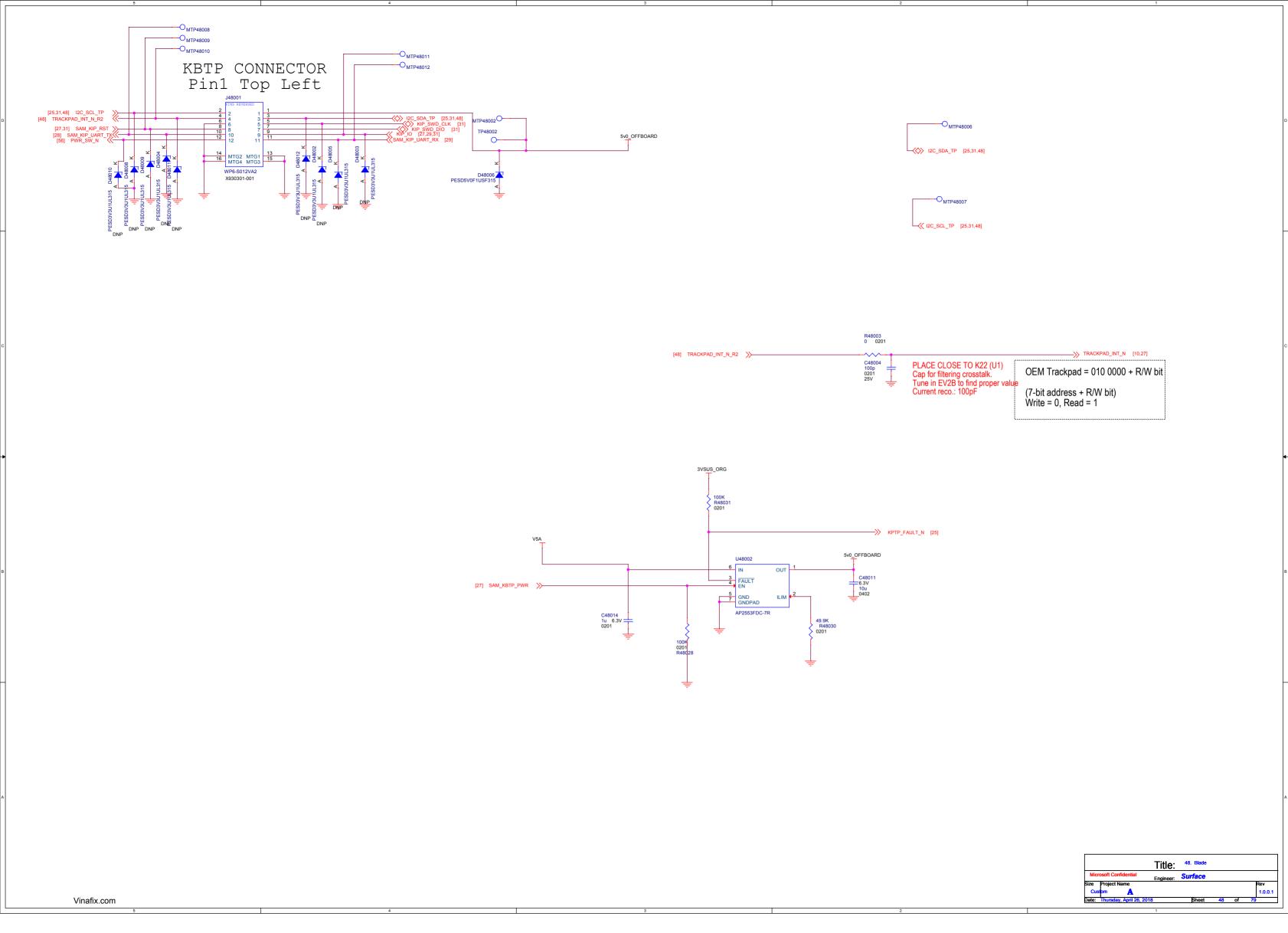


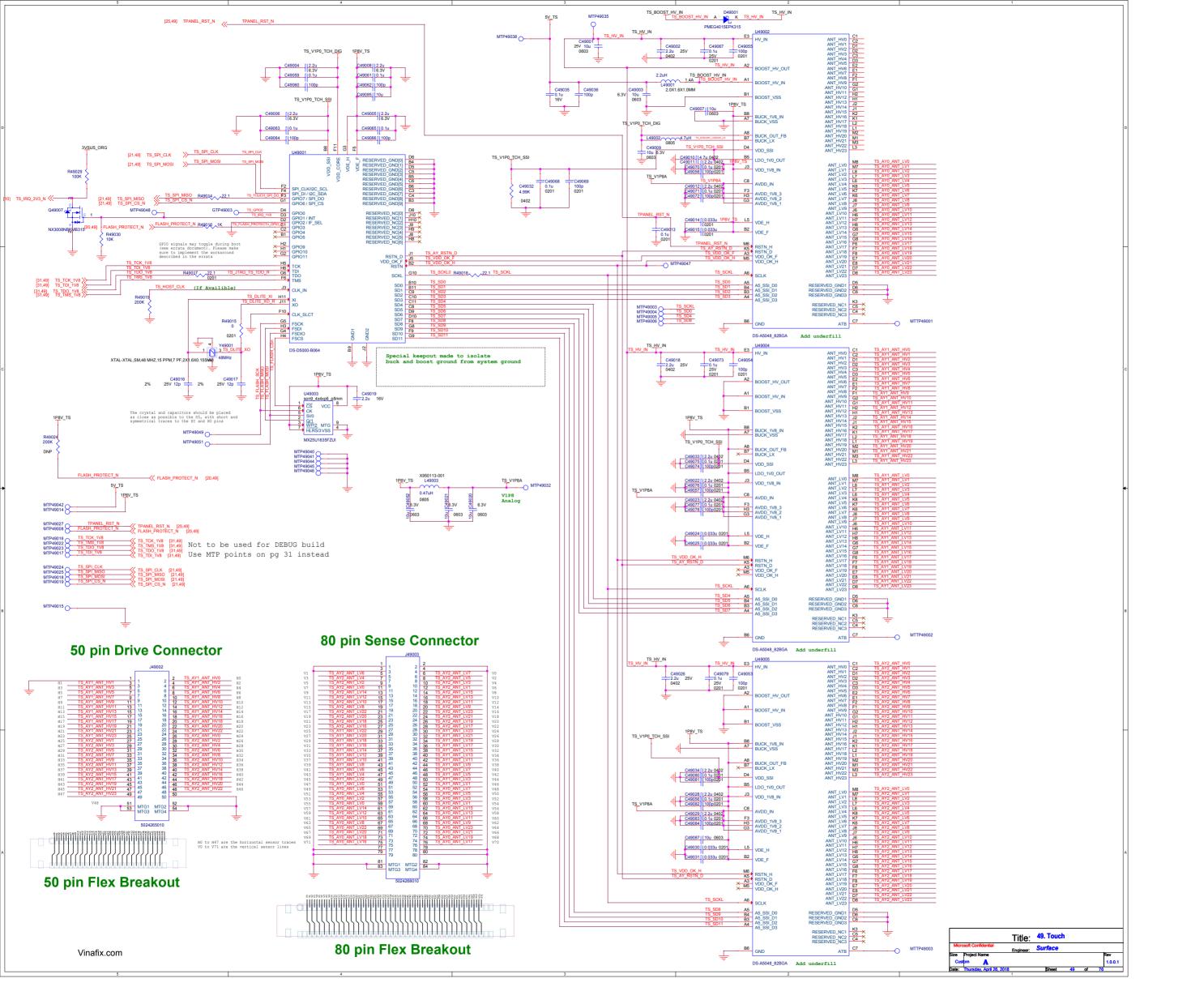


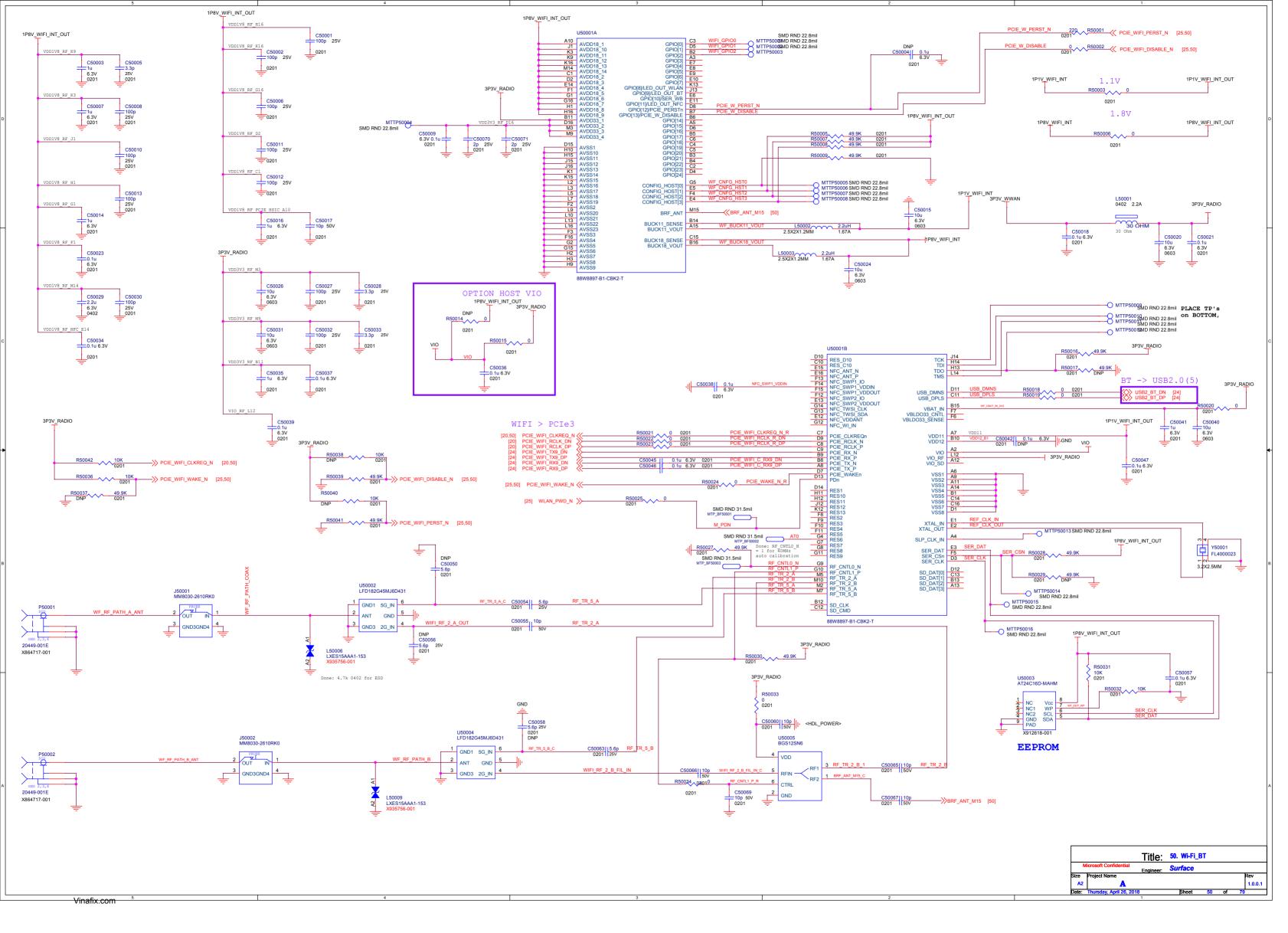




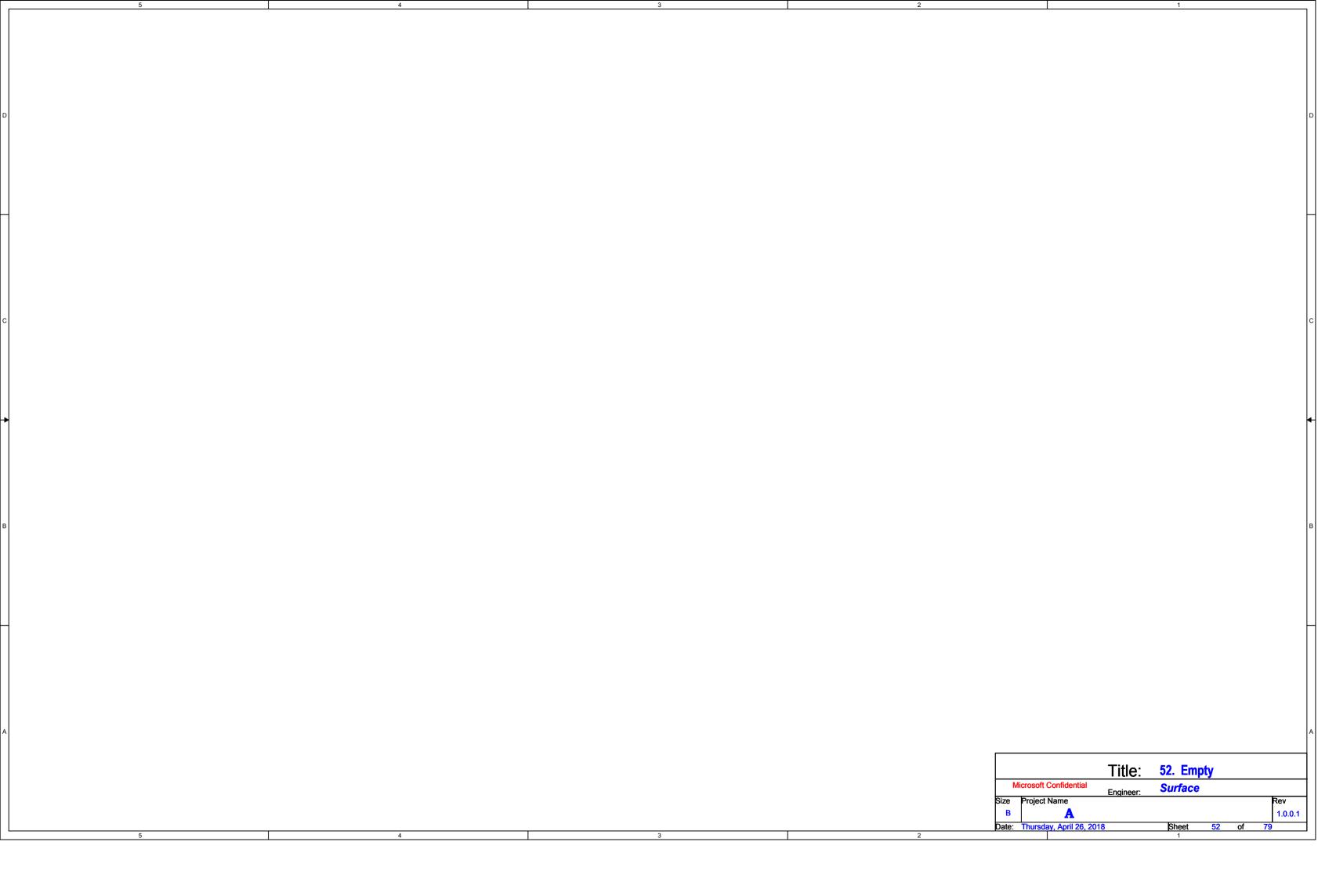


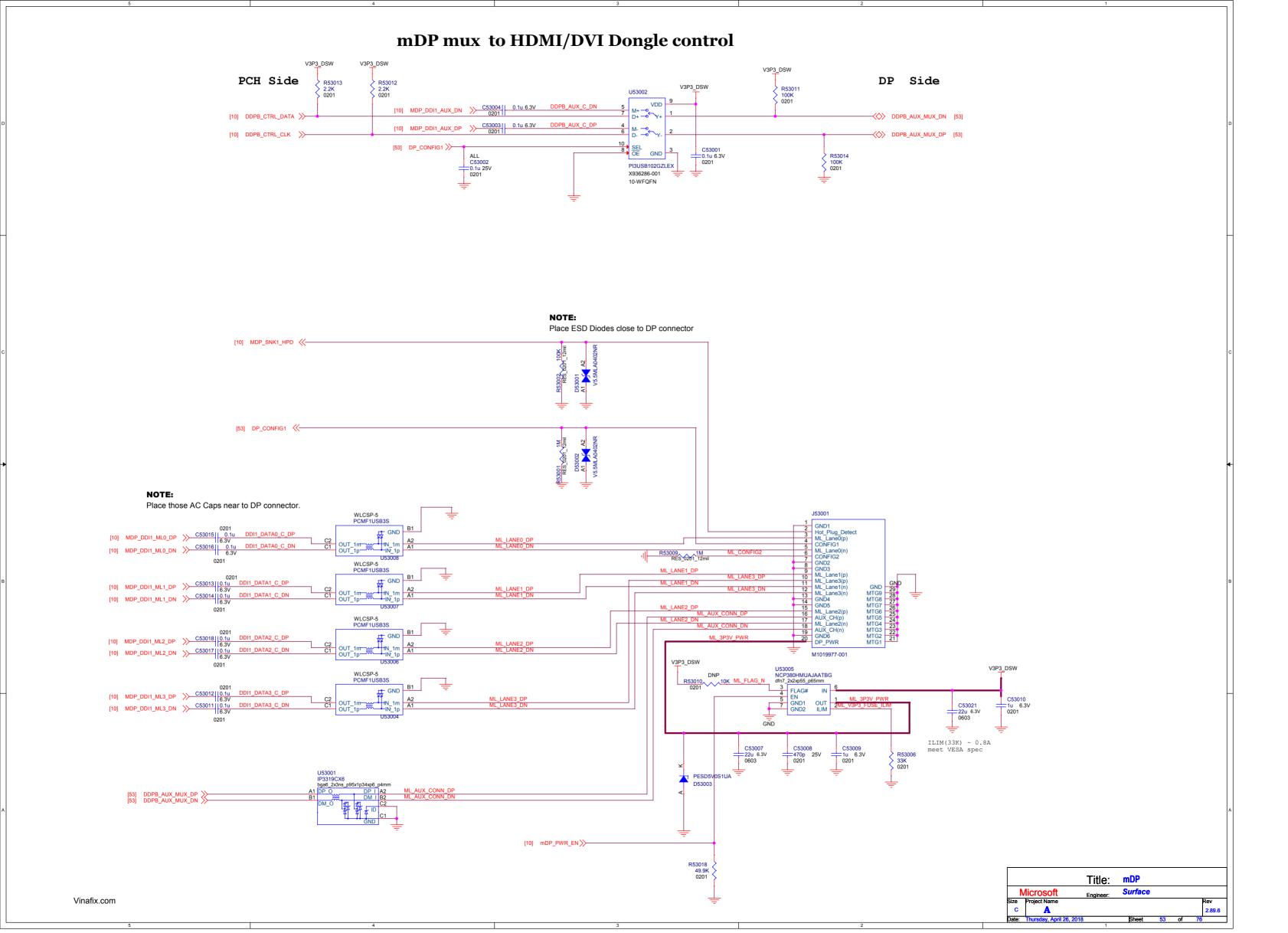


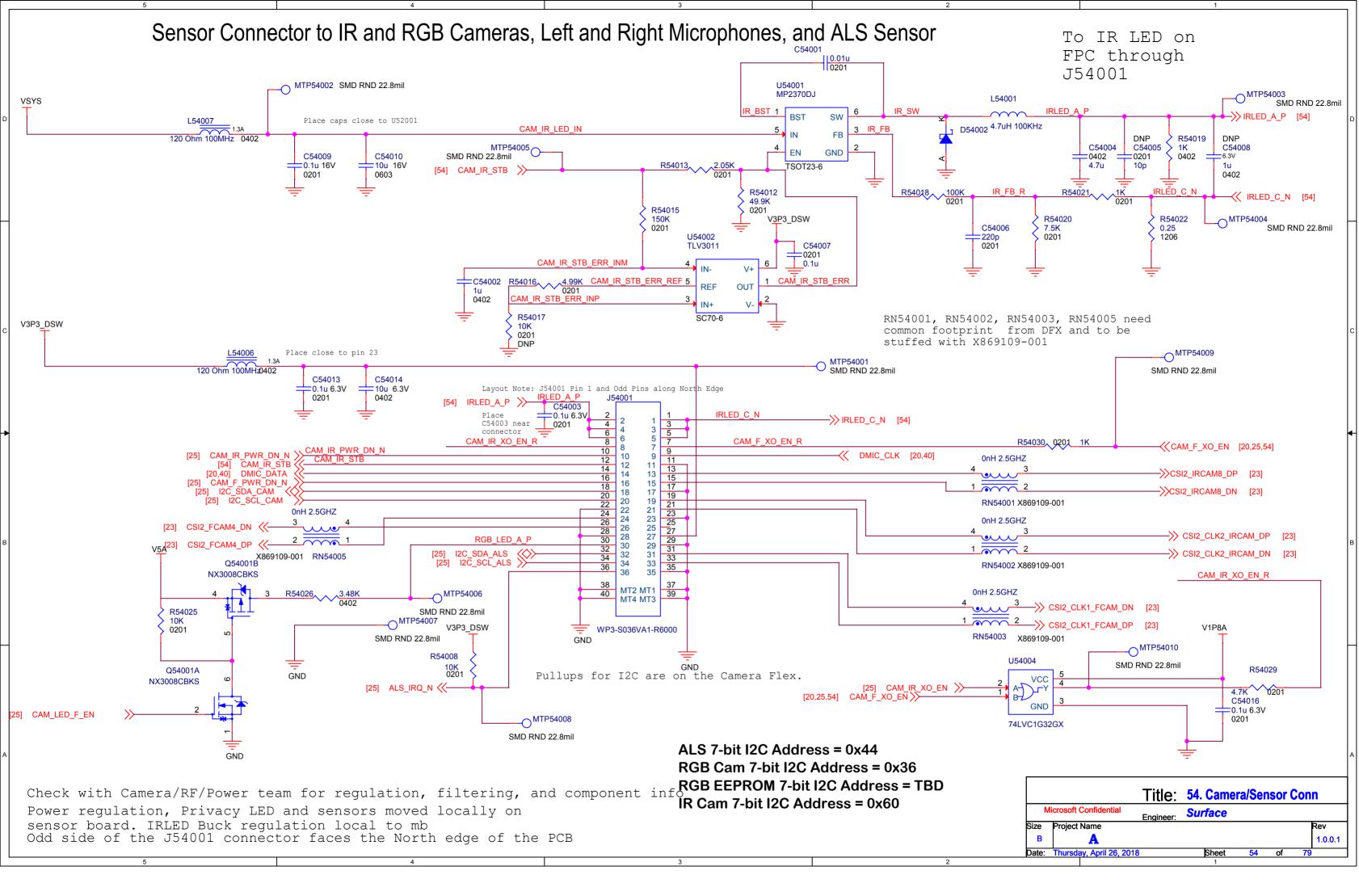


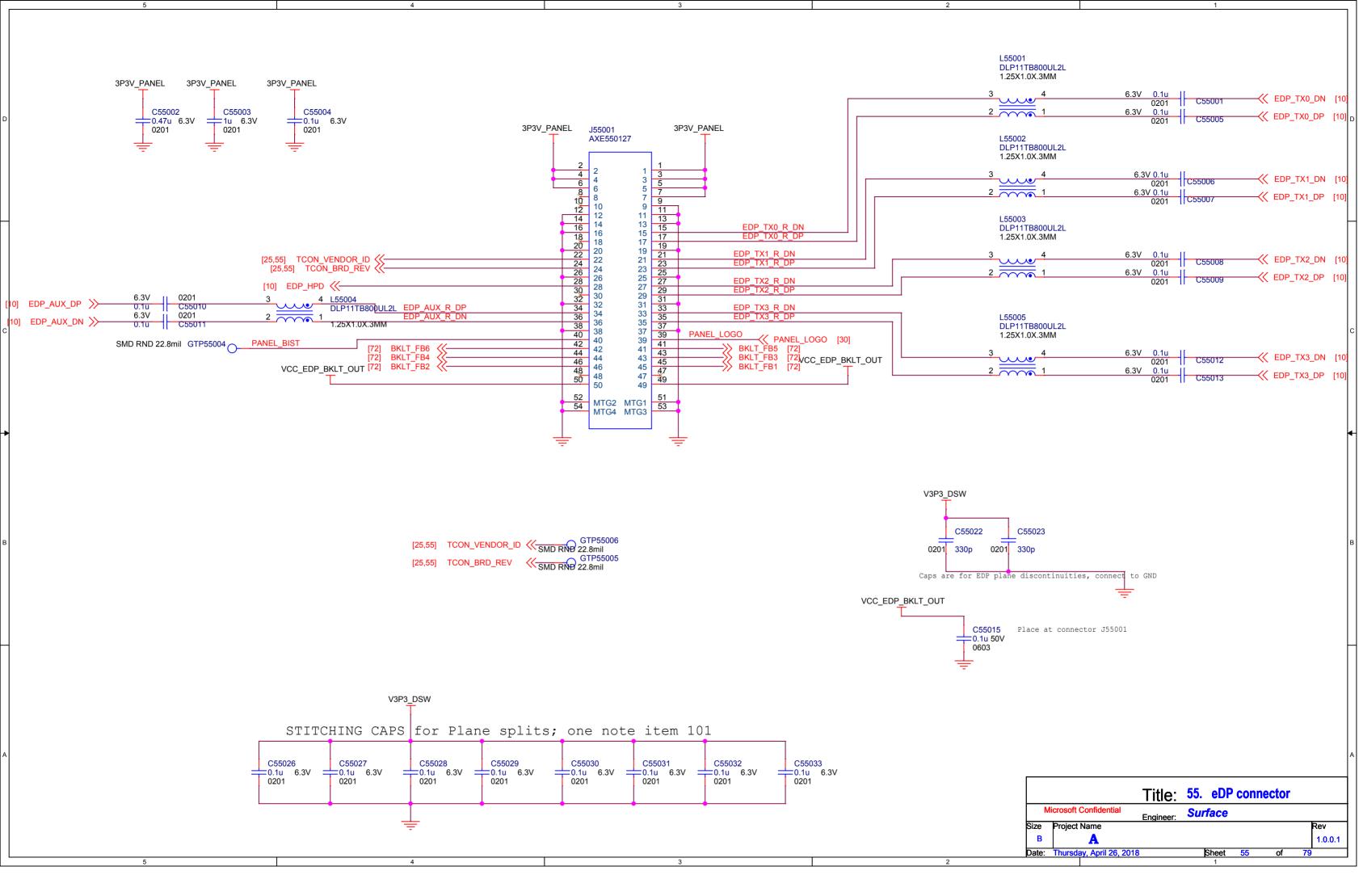


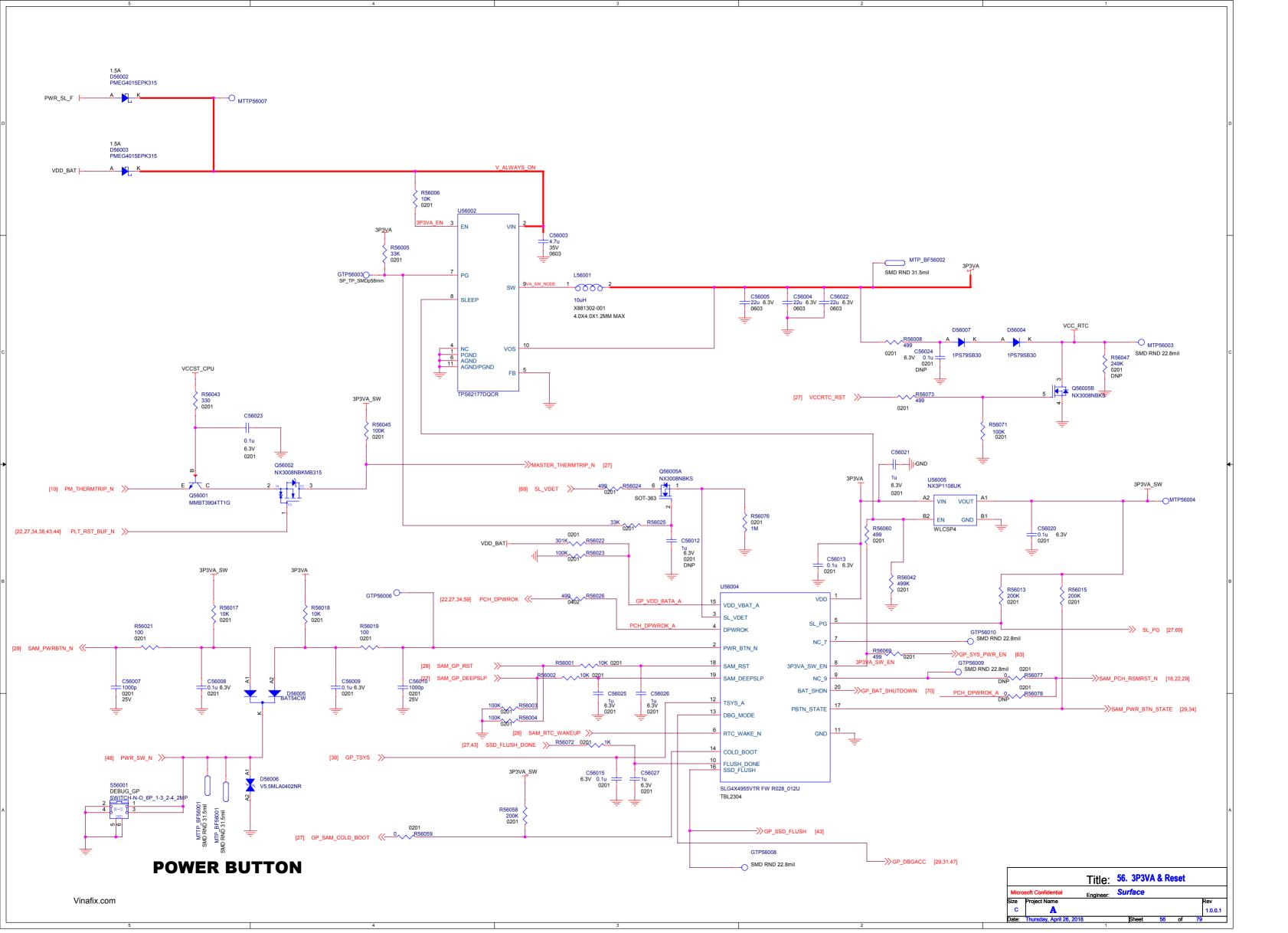


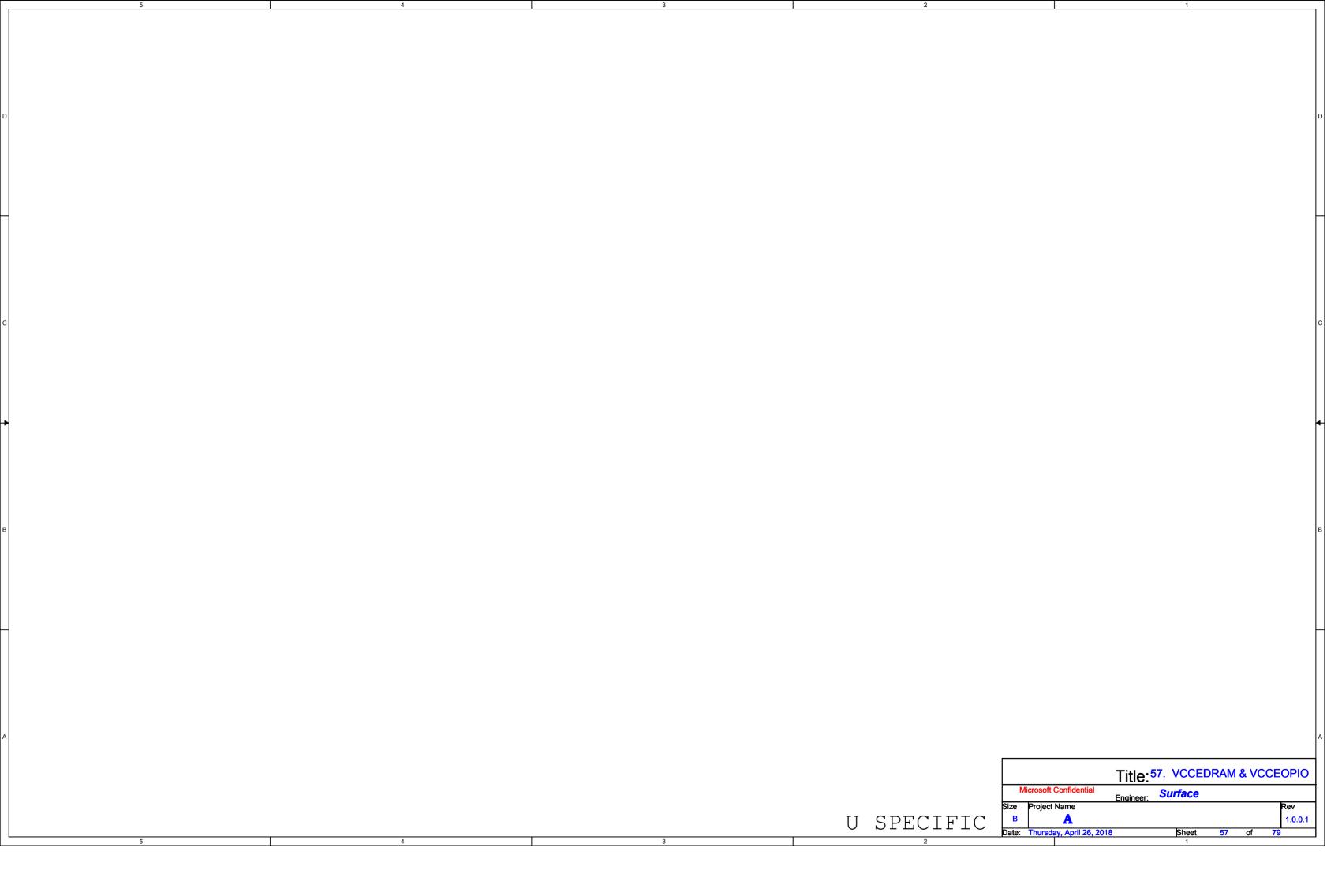


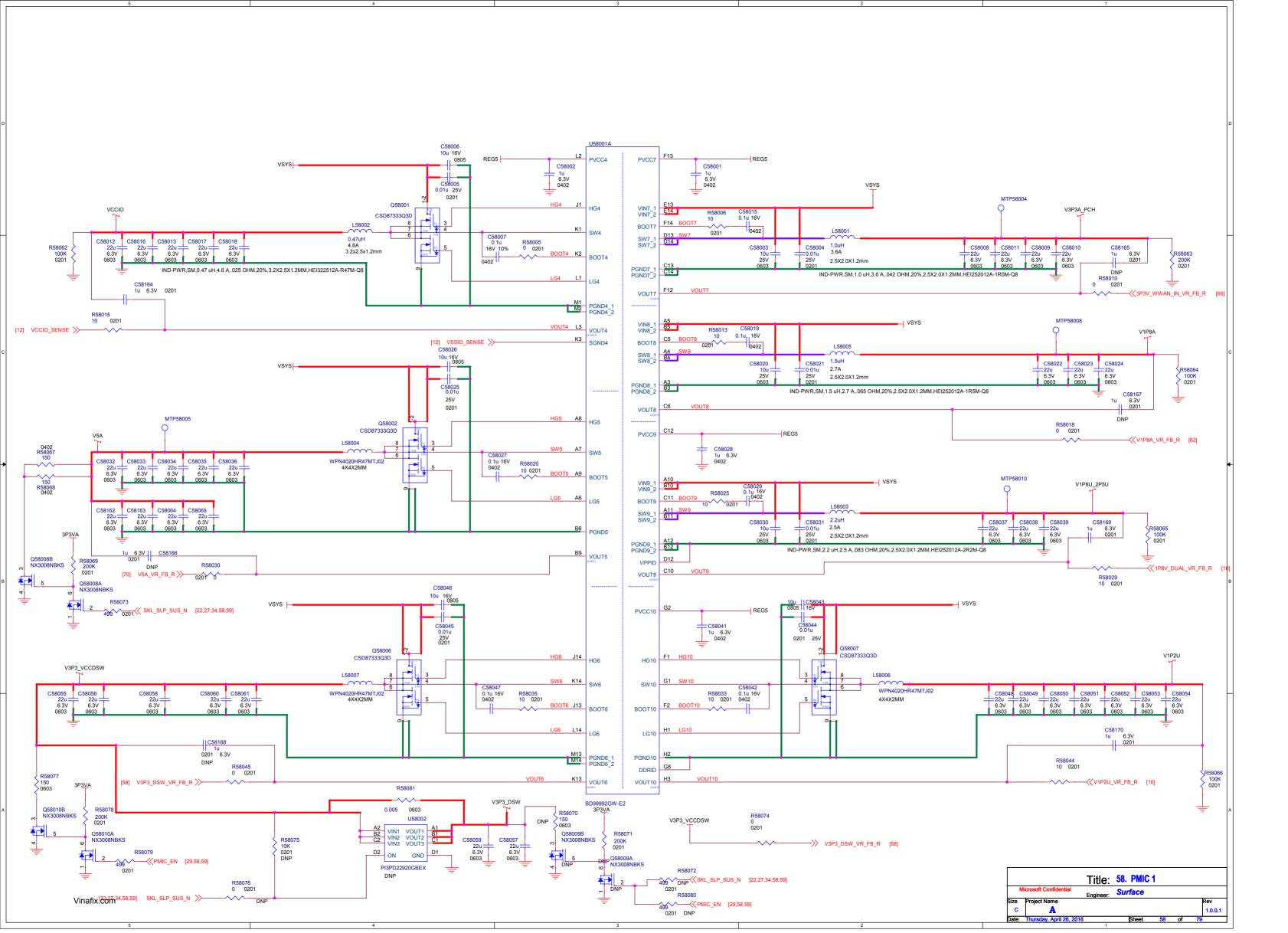


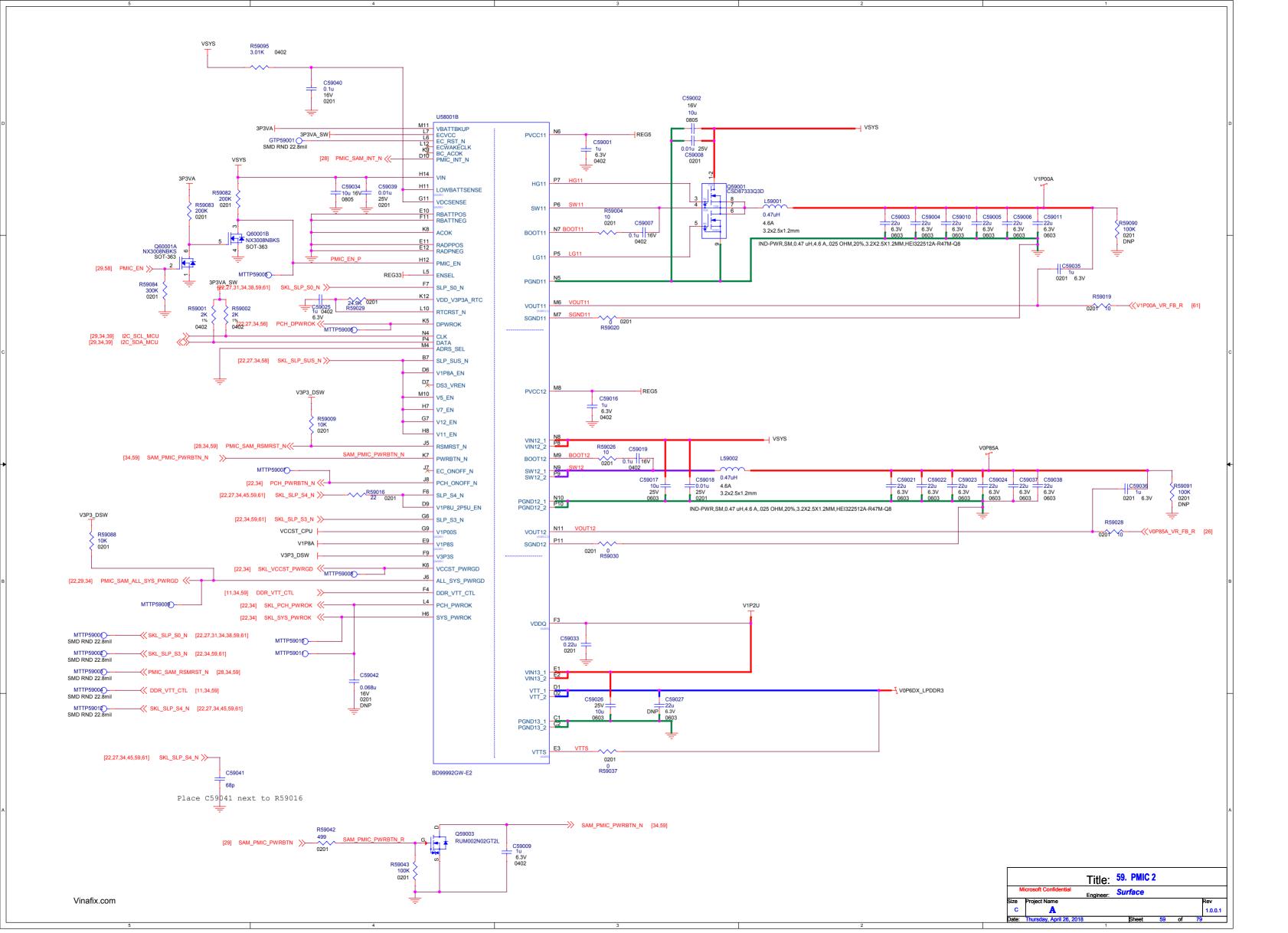


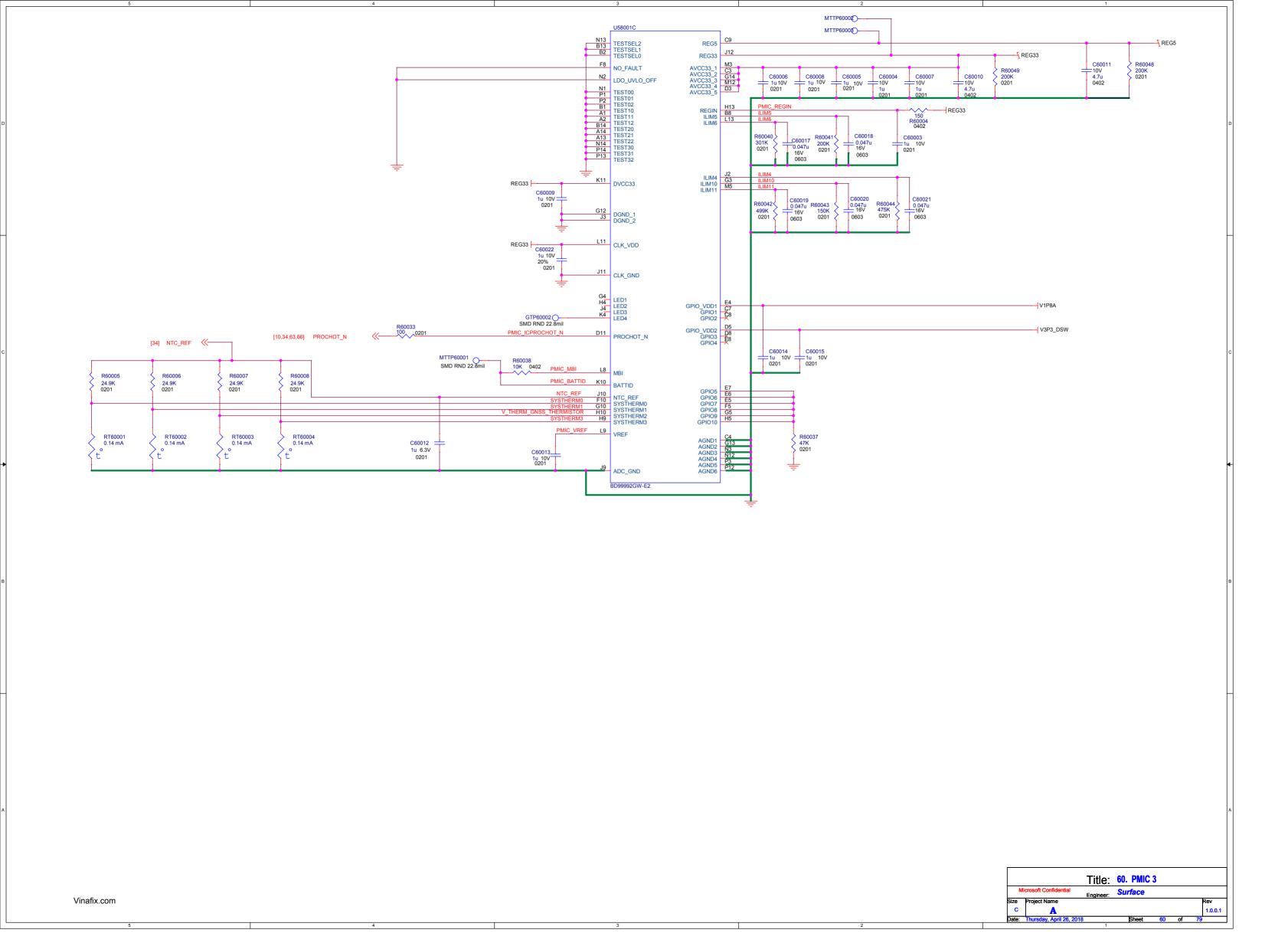


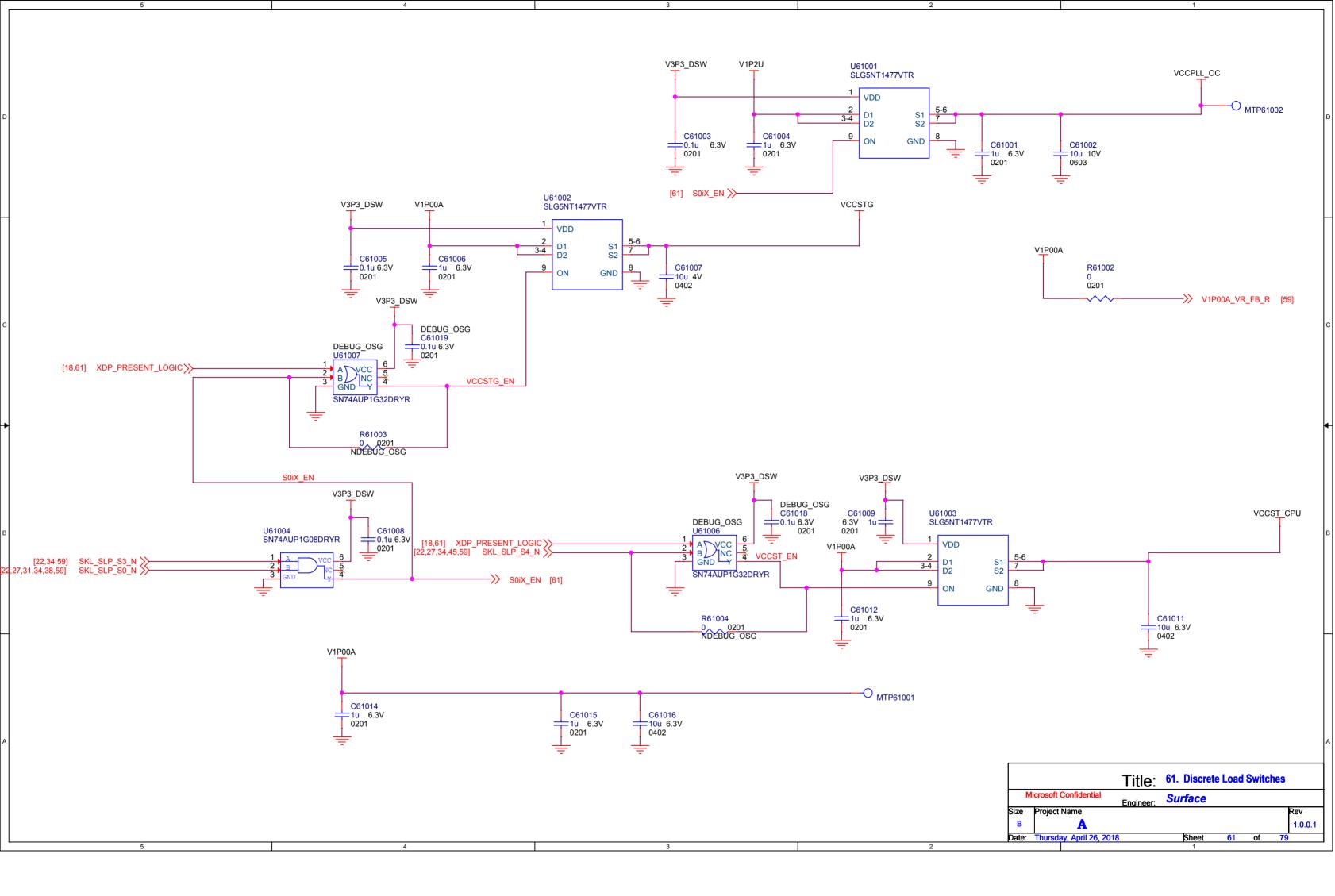


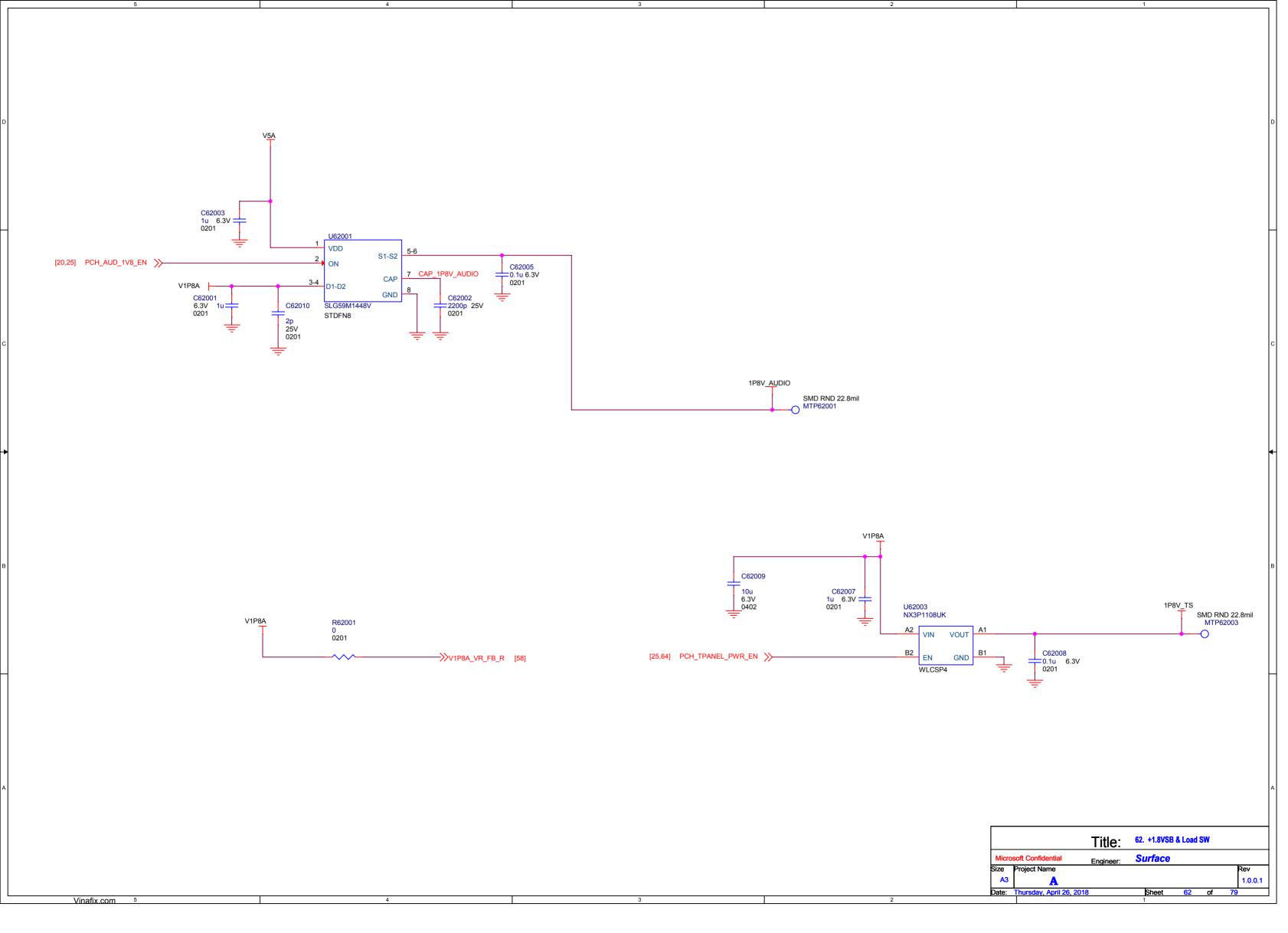


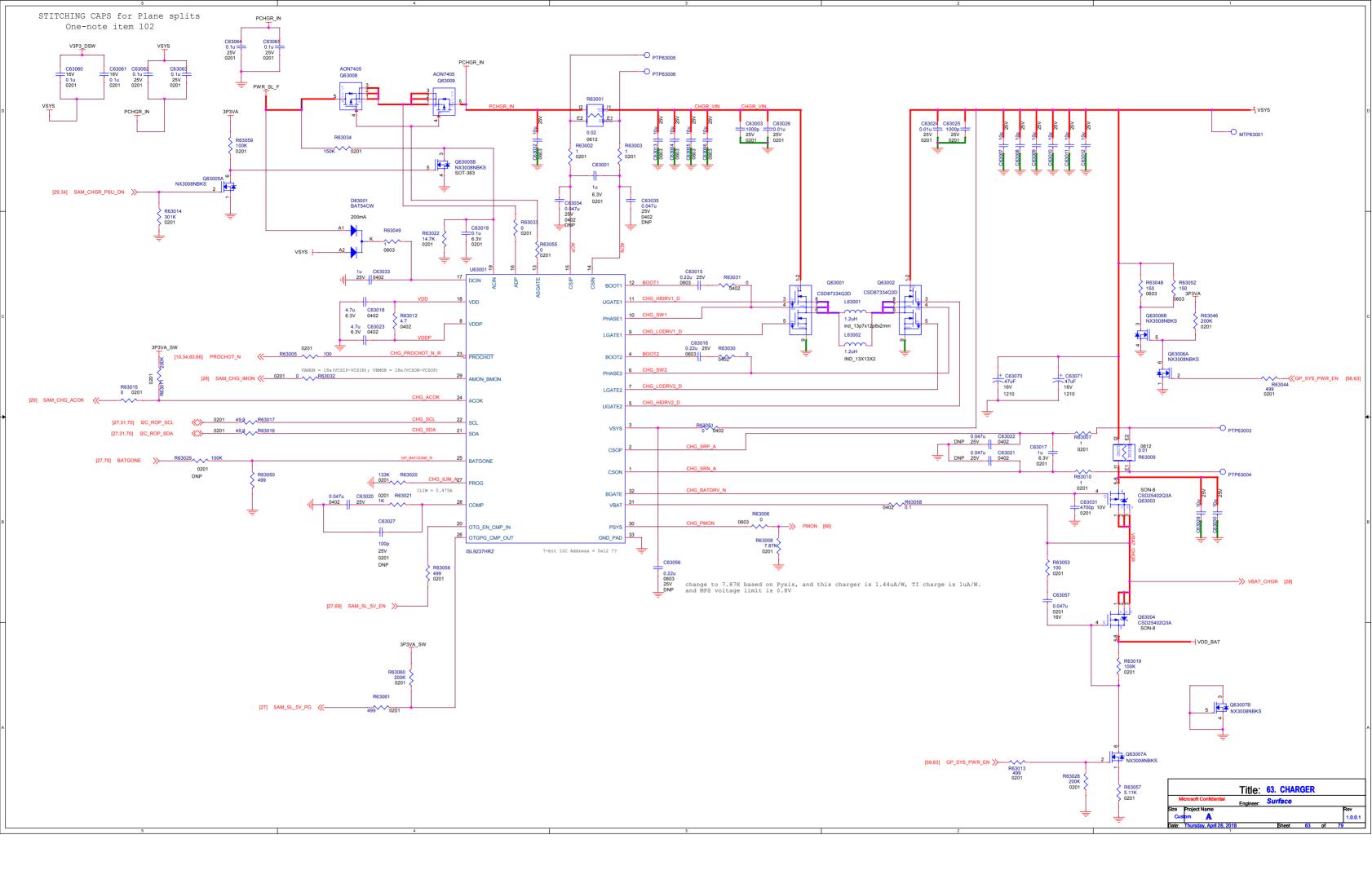


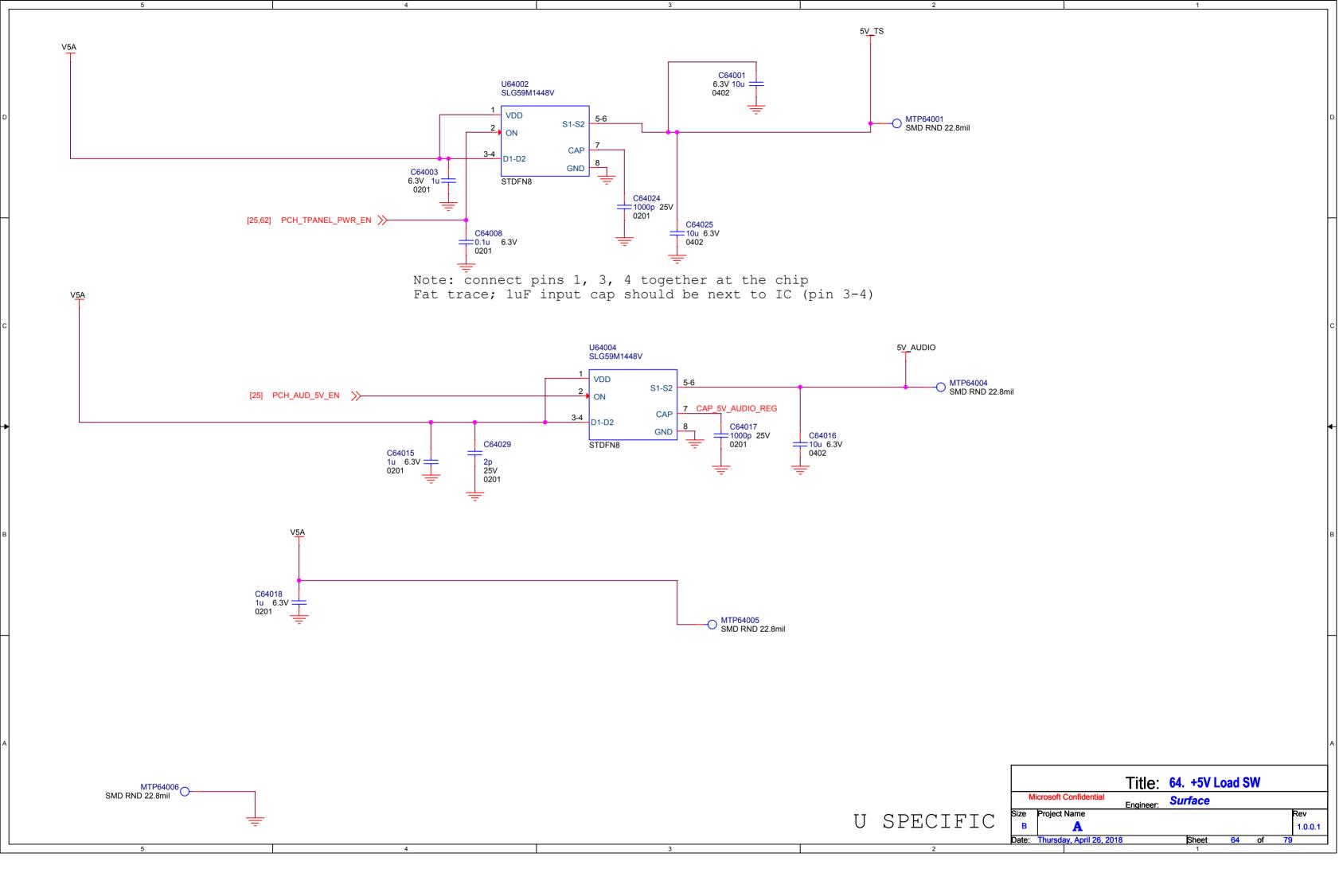


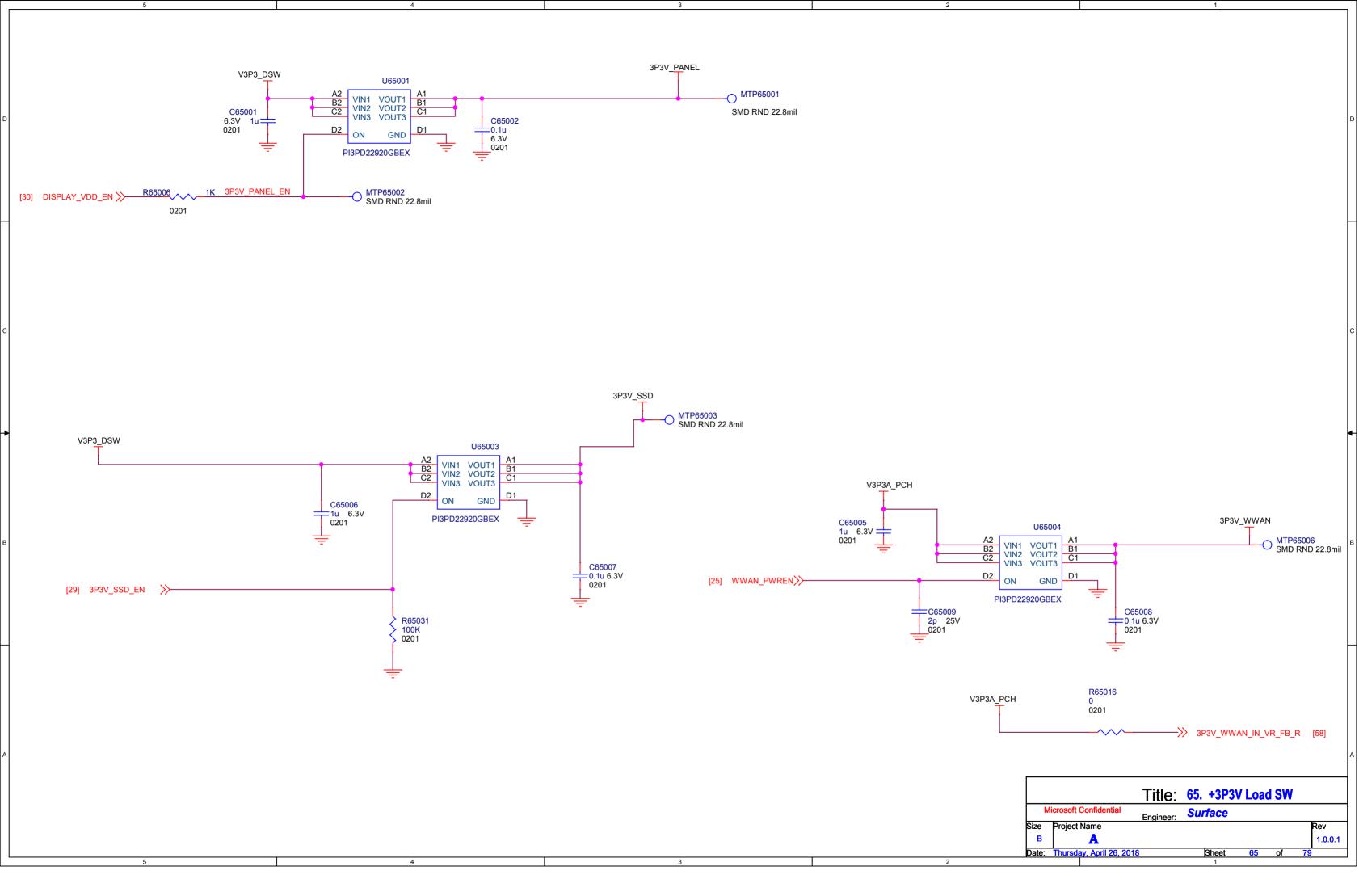


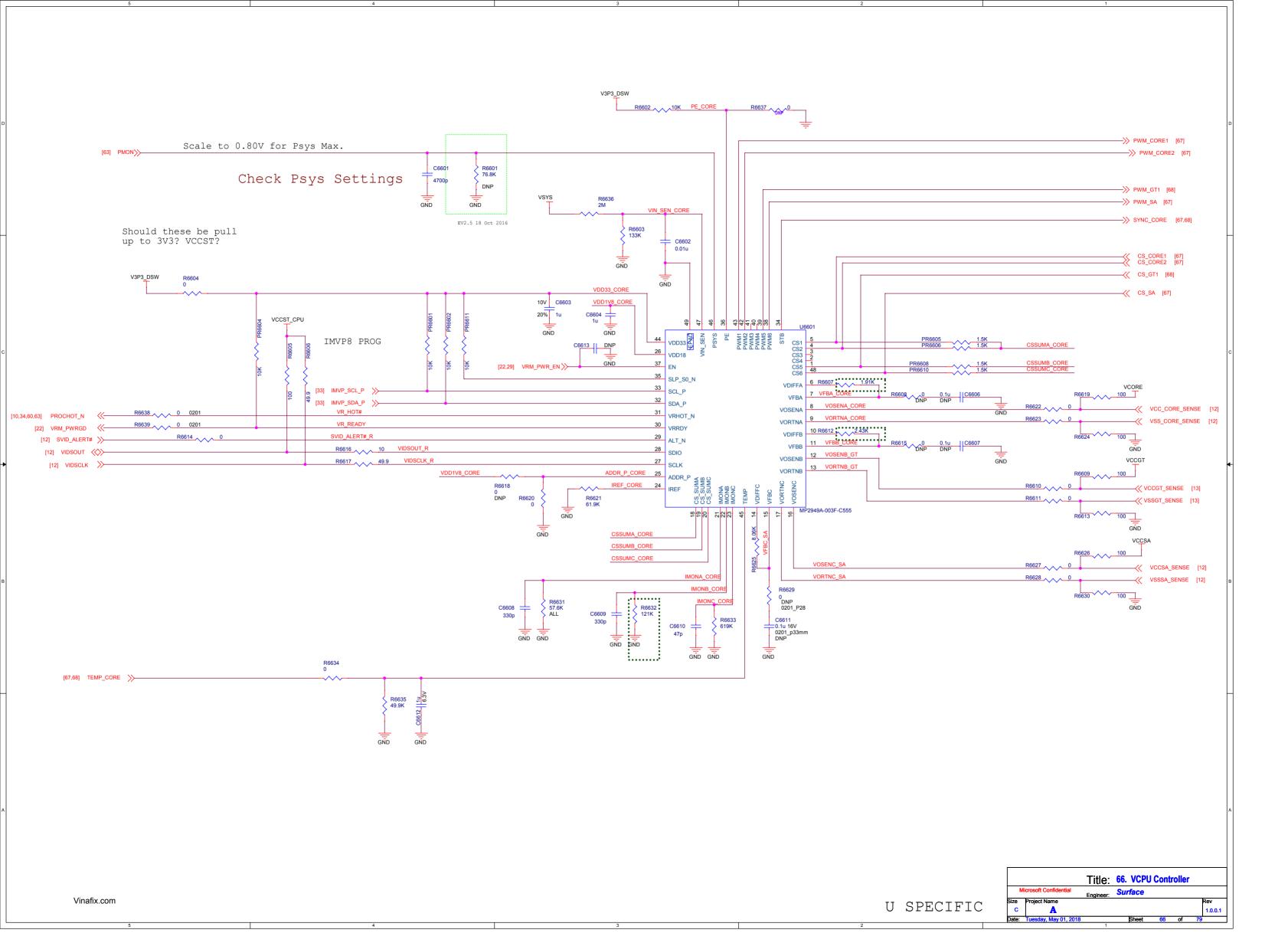


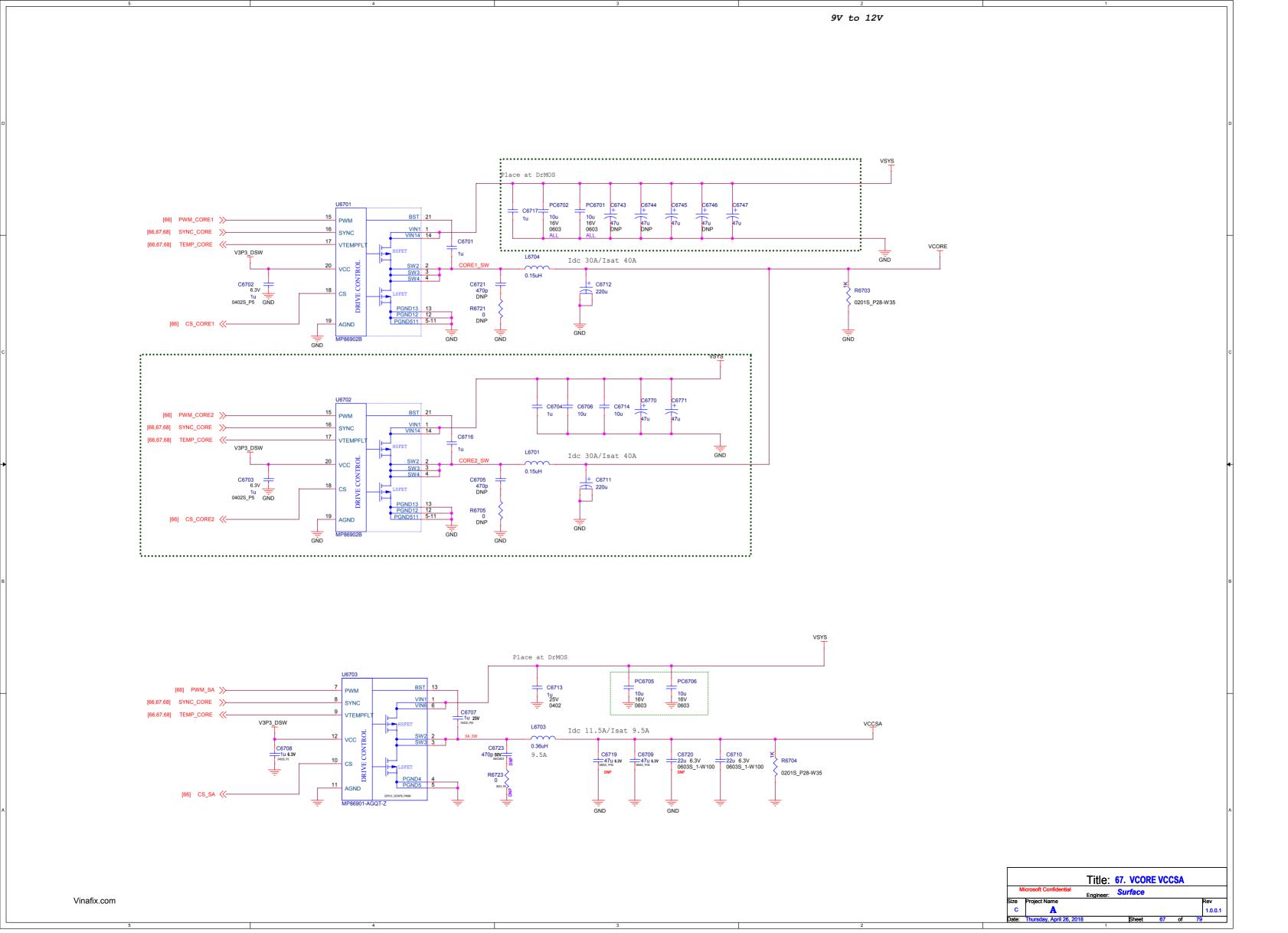


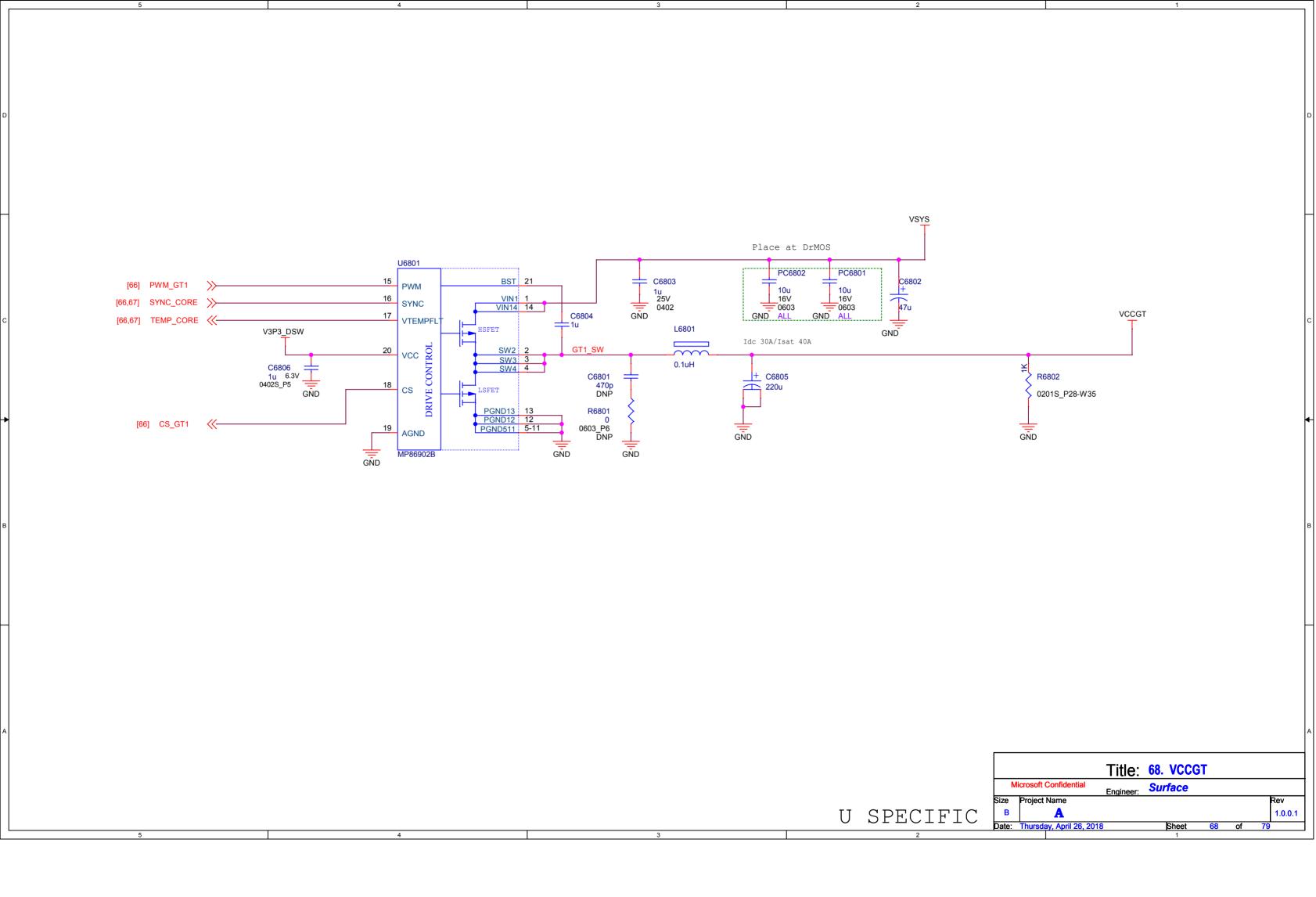


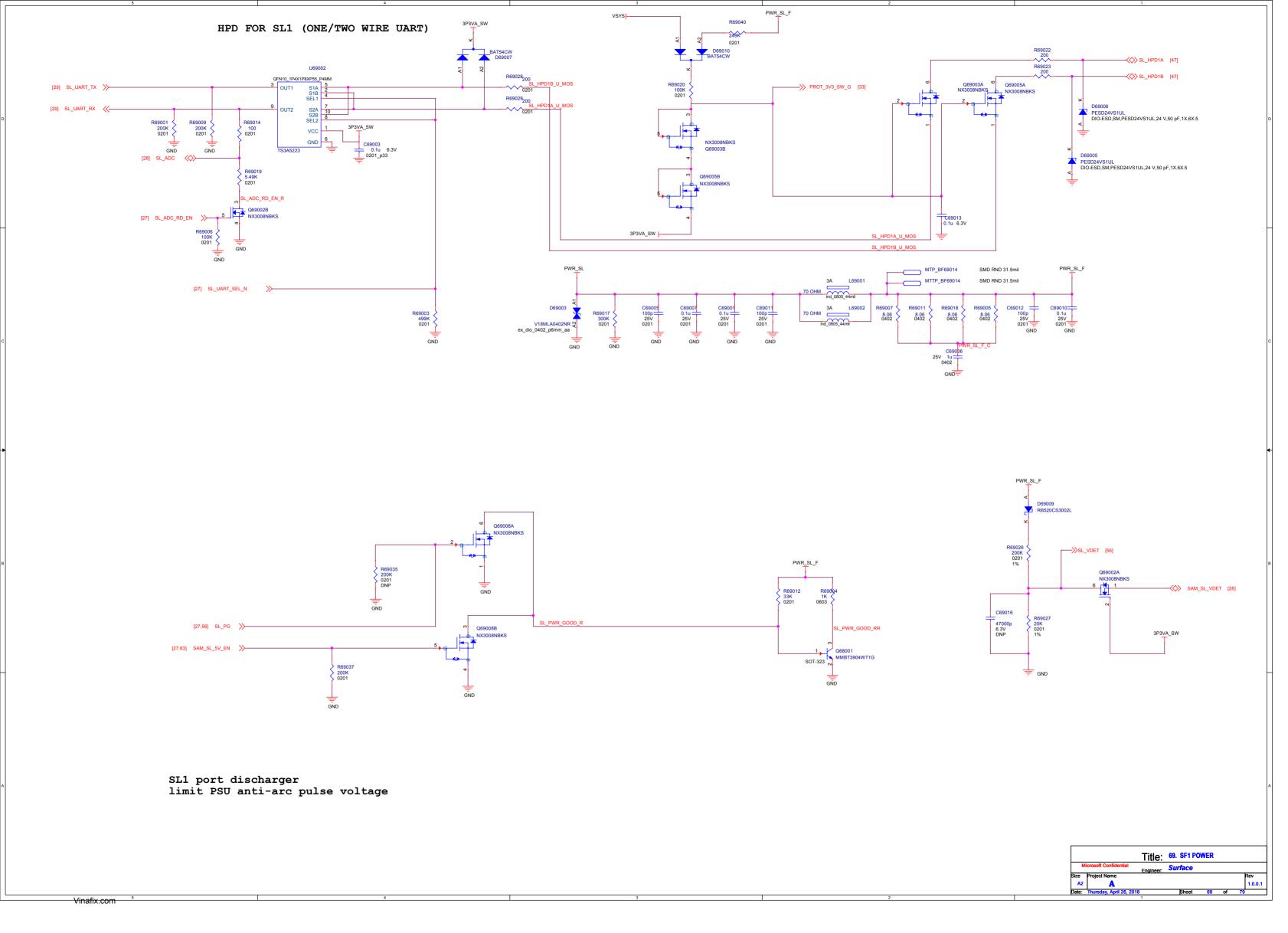


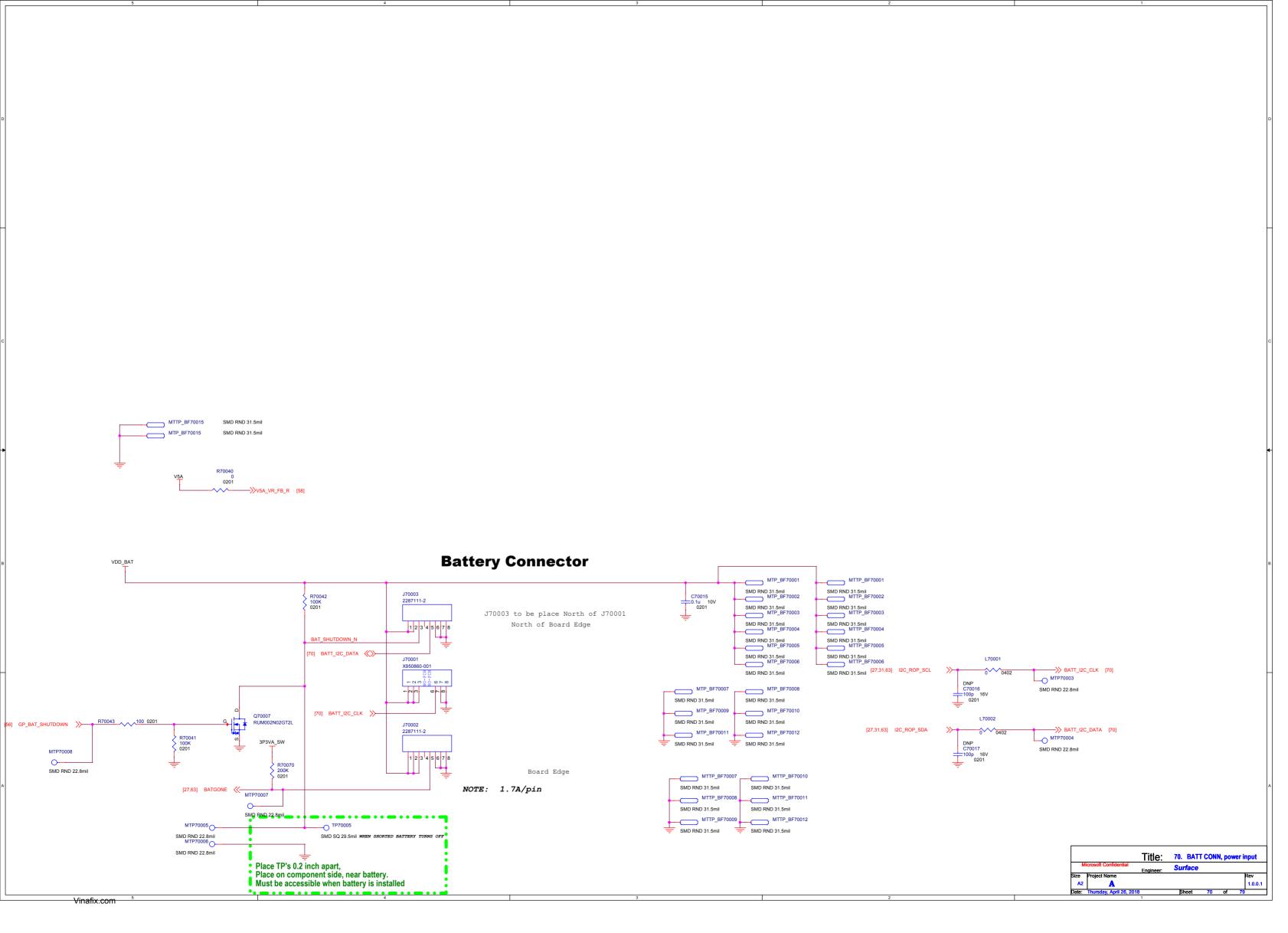


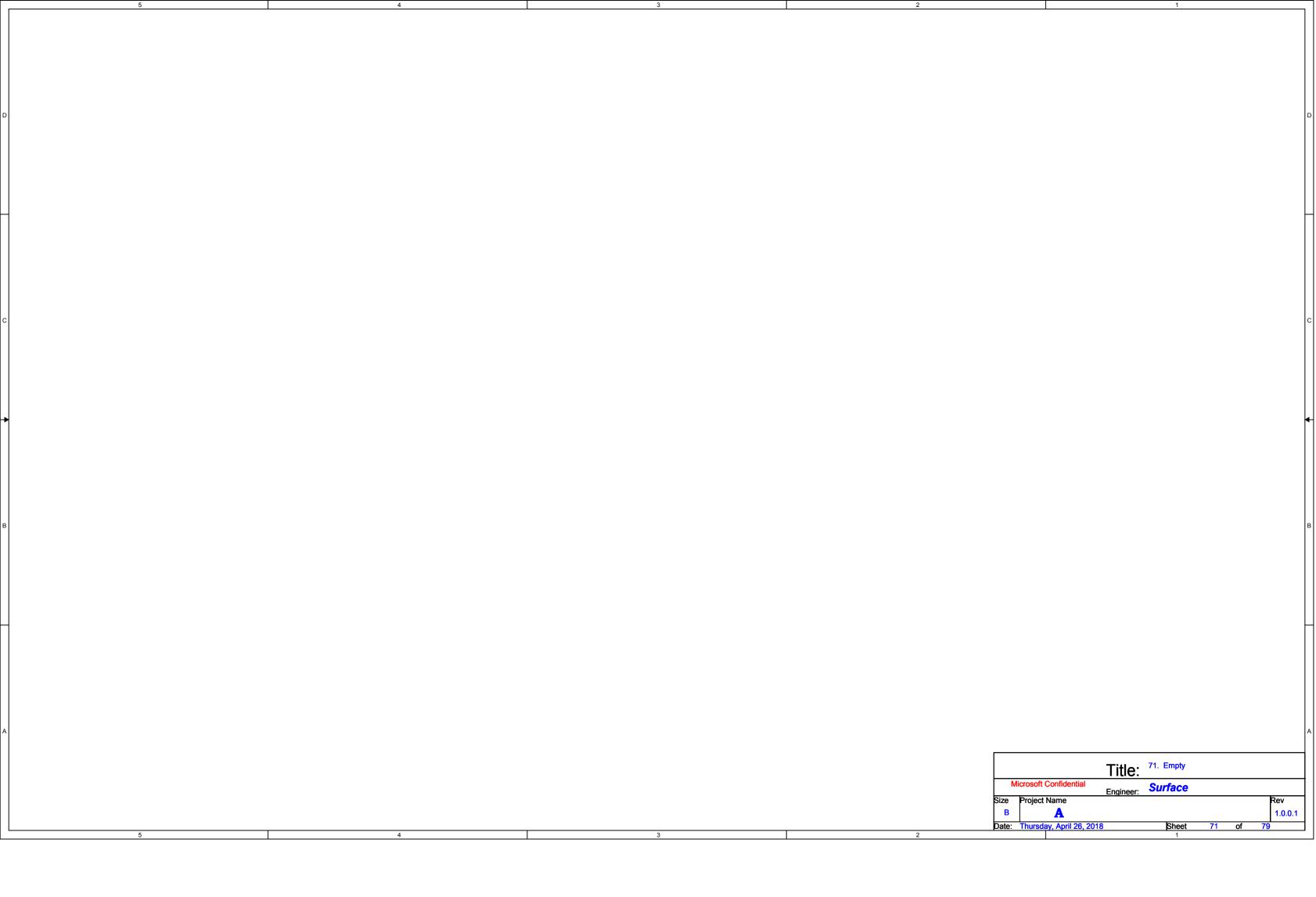


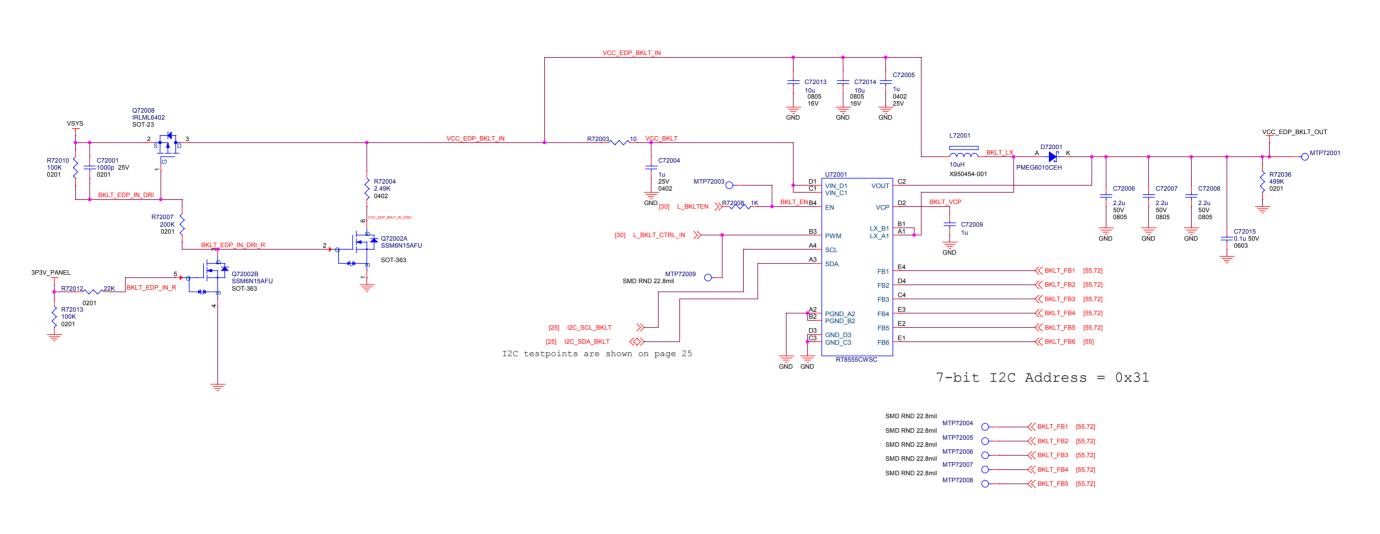












isolated ground on layer 2 to tie Cin GND, Cout GND, and controller PGND together. Then tie this isolated ground plane to main GND under the exposed pads.



